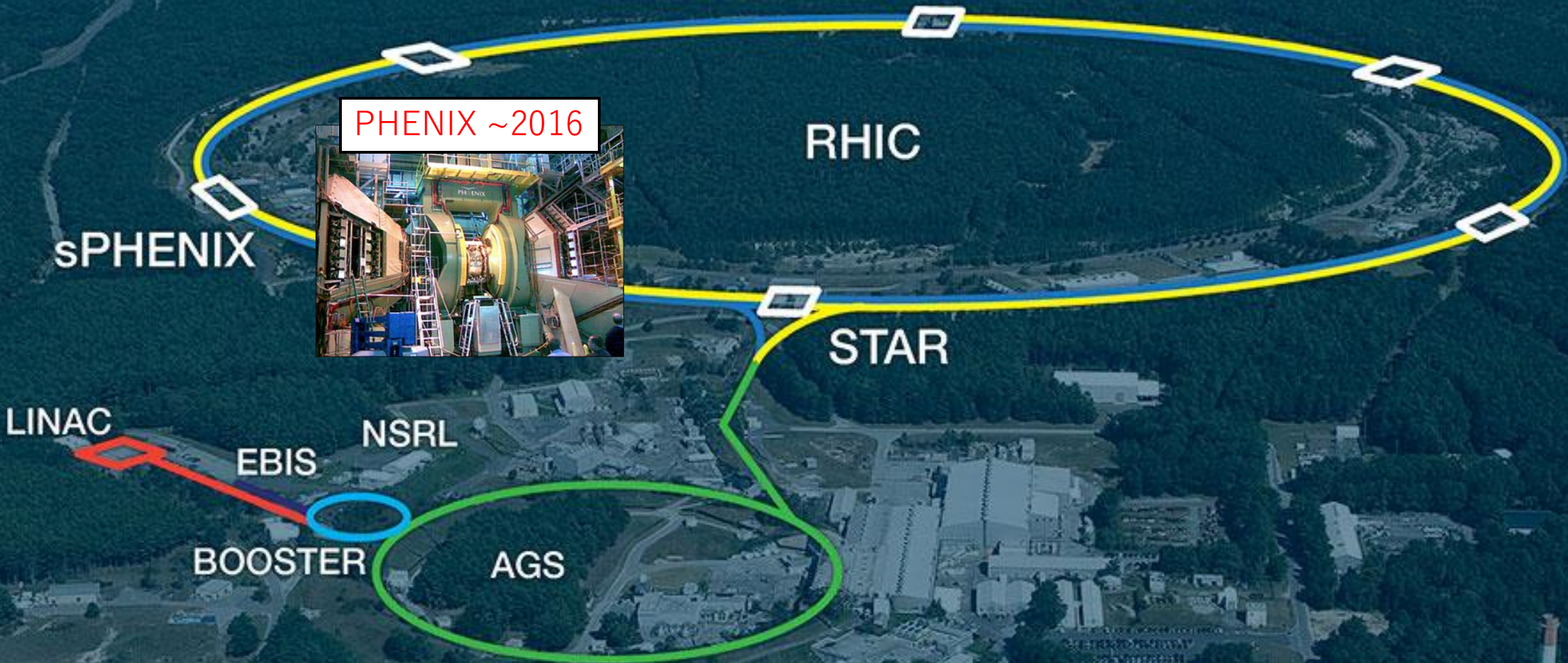




Introduction of sPHENIX & INTT

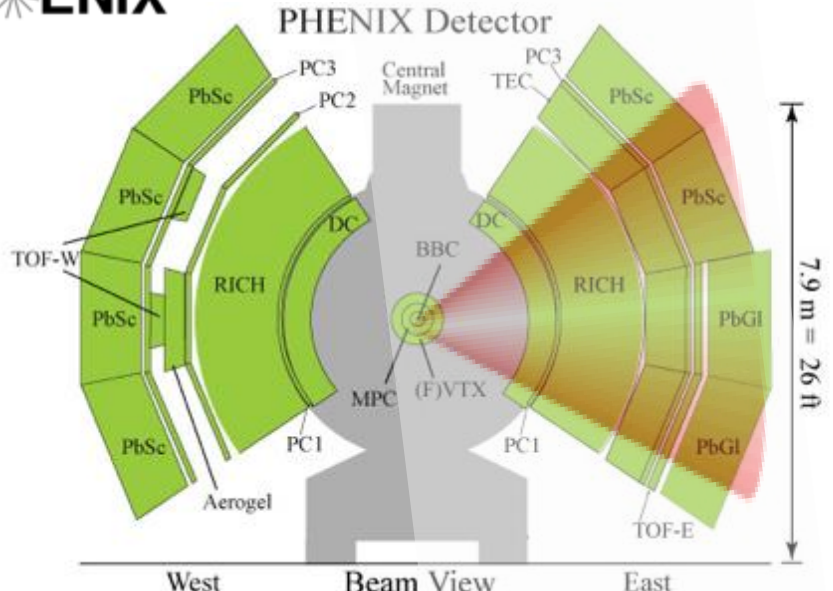
RIKEN/RBRC
Itaru Nakagawa

sPHENIX Detector



What's new about sPHENIX

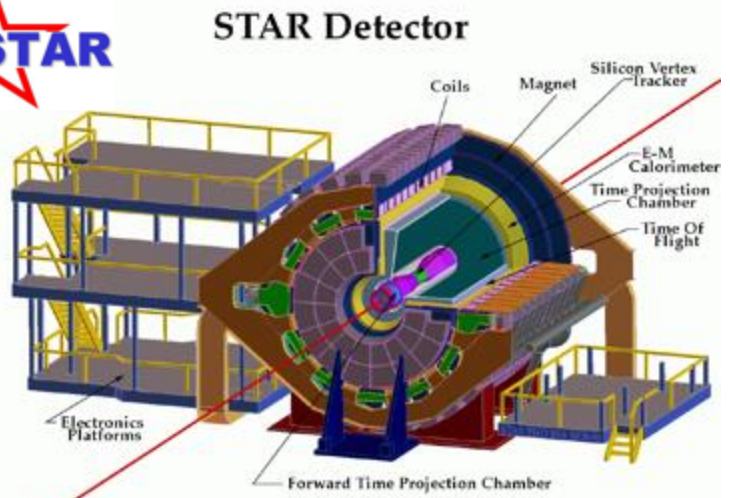
PHENIX



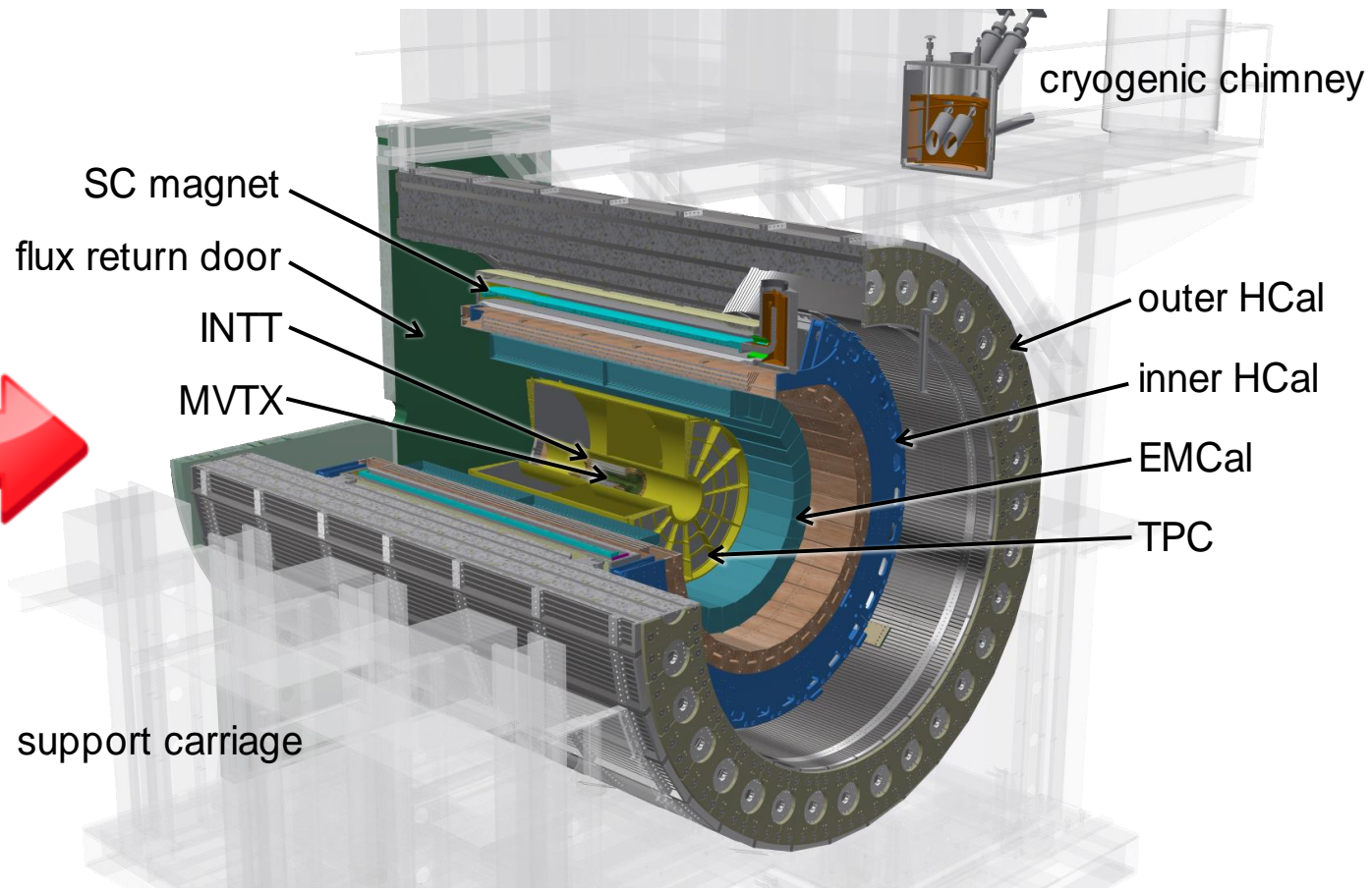
Limited acceptance to measure Jet.



STAR



4π , but incomplete for jet without HCAL



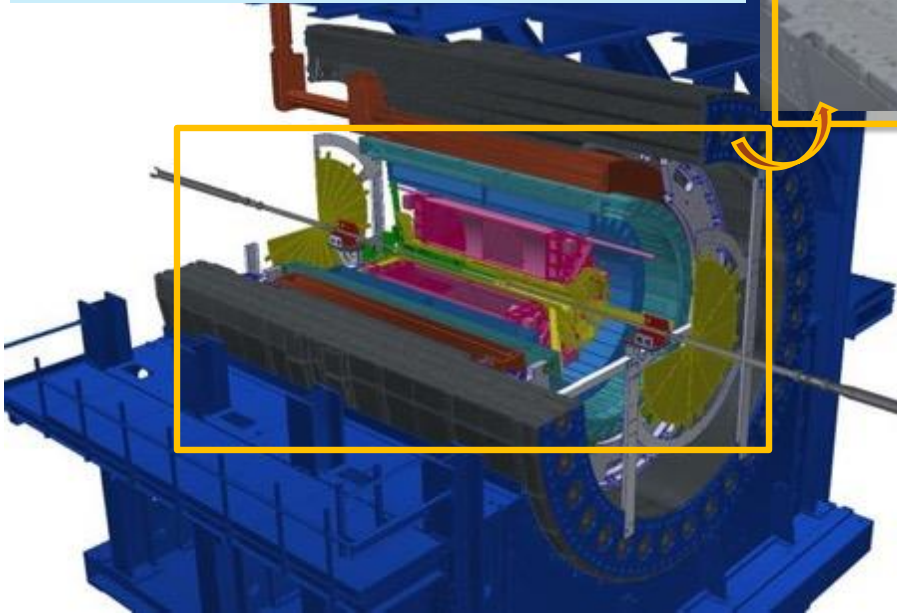
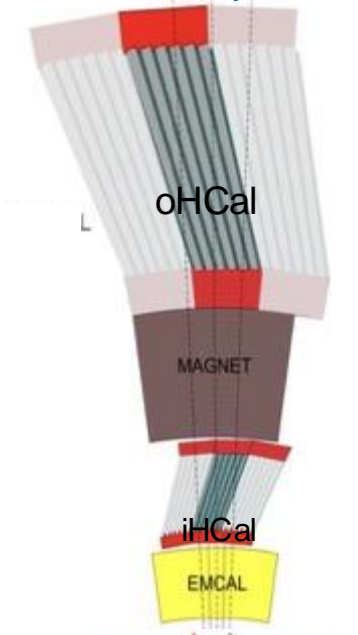
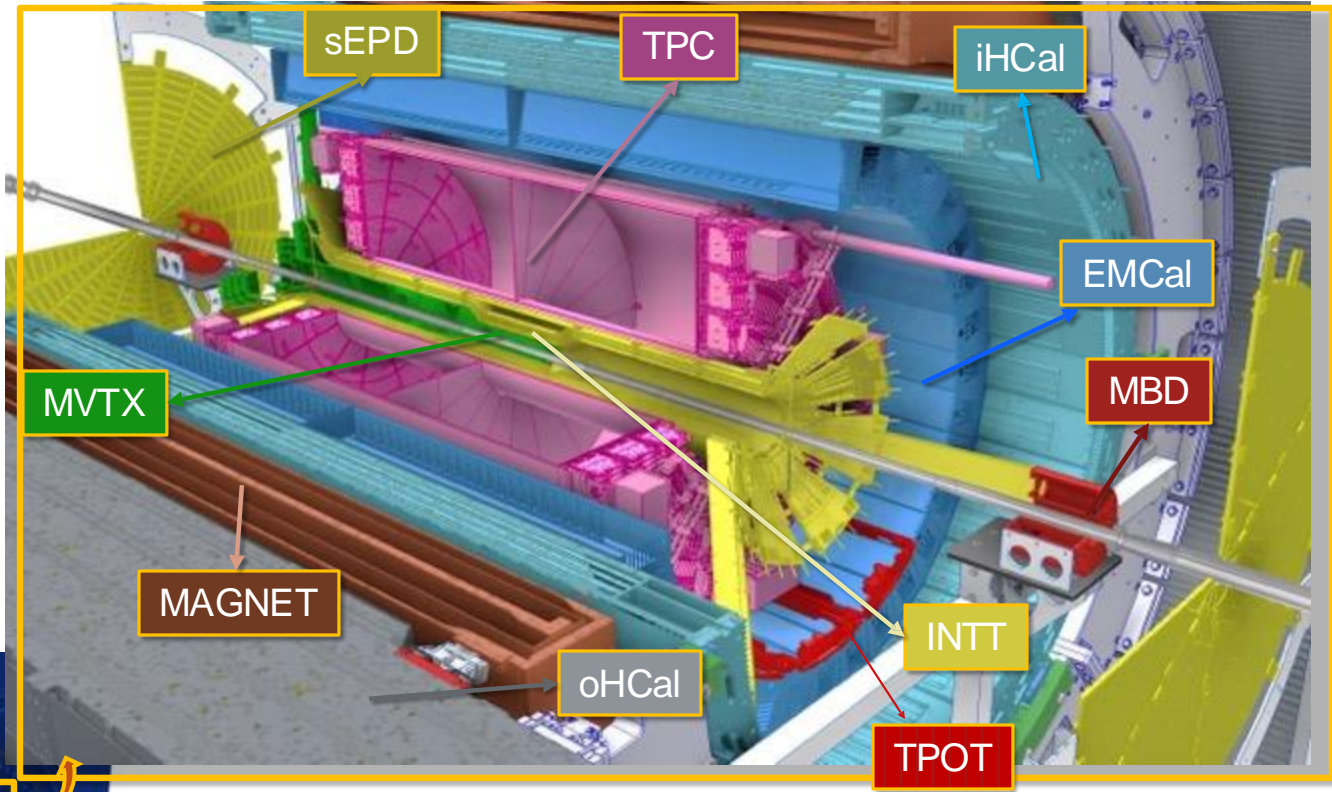
4π & $-1 < \eta < 1$ with HCAL
Designed to be ideal detector for Jet



sPHENIX Detector

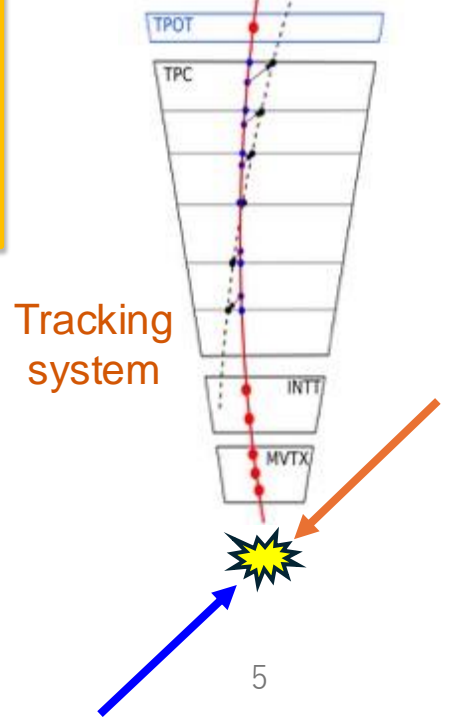
Calorimeter system

- 1.4T Solenoid from BaBar
- Hermetic coverage: $|\eta| < 1.1$, 2π in ϕ
- Large-acceptance EM+H calorimeters: brings first full jet reconstruction & b-jet tagging at RHIC!!
- High data rates: 15 kHz for all subdetectors
- Precise tracking with tracking system in stream readout

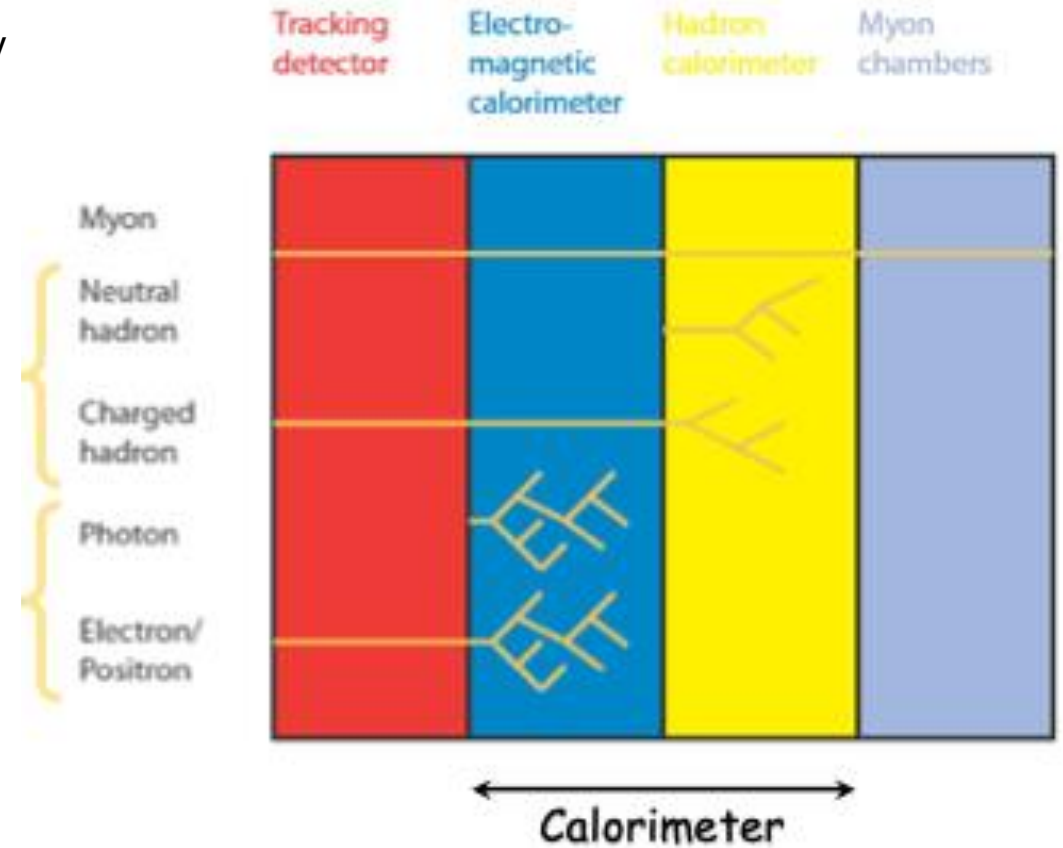
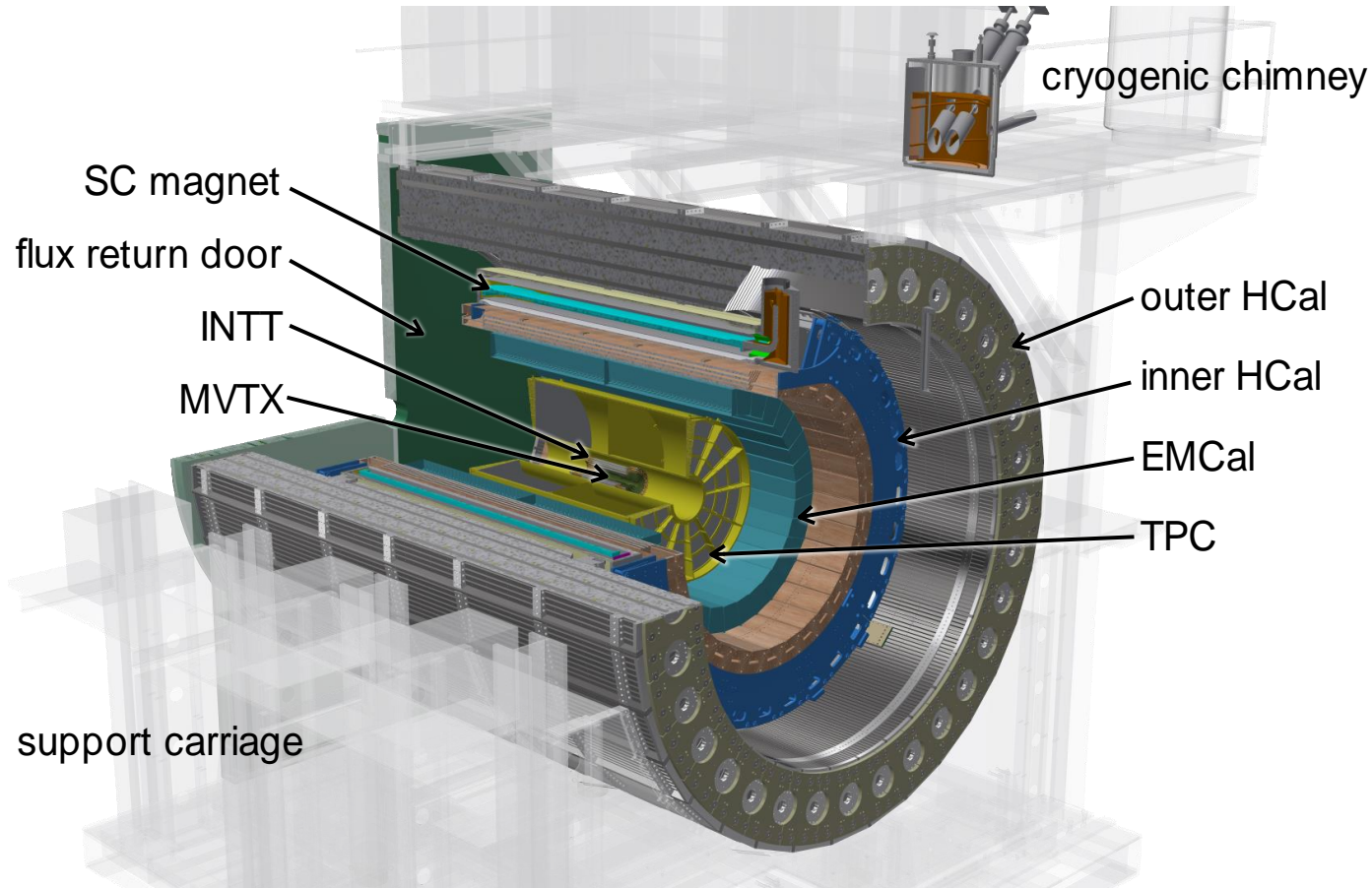


2023 : Commissioning Au+Au
 2024 : p+p, Au+Au
 2025 : Au+Au ... p+A?

} $\sqrt{s} = 200\text{GeV}$



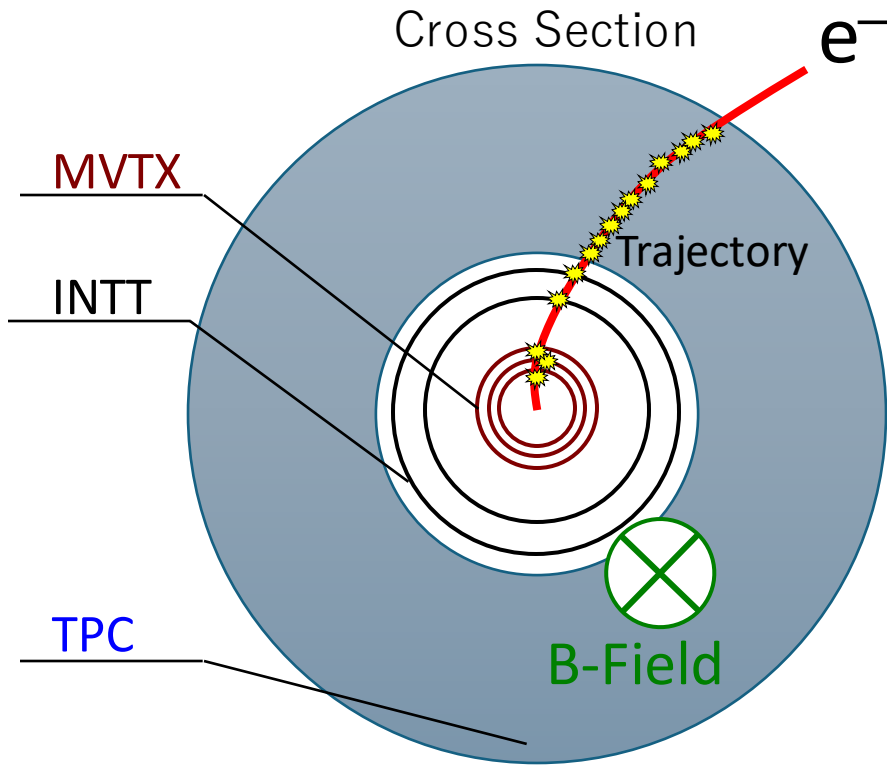
Modern Experimental Detector Layout



Tracking System

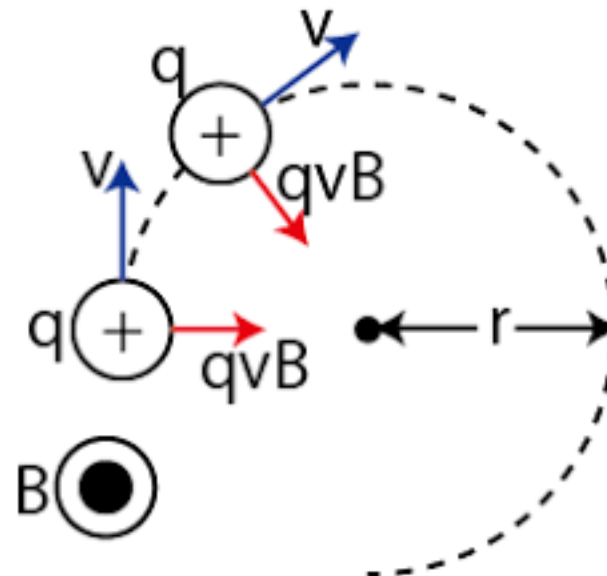
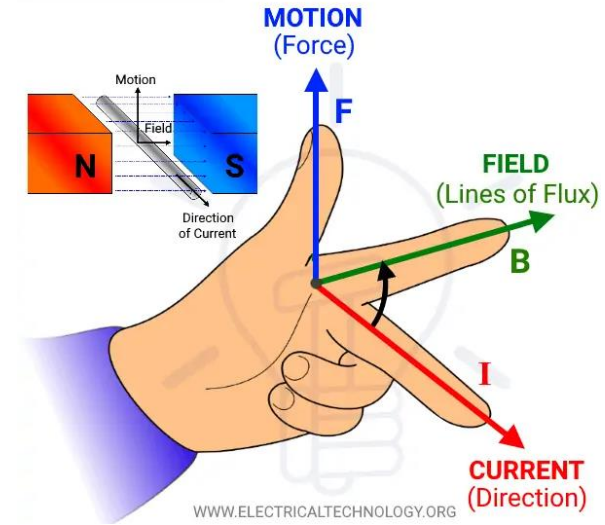


Tracking Particle Trajectory



Estimate Momentum of the particle trajectories by measure radius.

FLEMING'S LEFT HAND RULE



sPHENIX Tracking Detectors

MVTX ($2.3 < r < 3.9$ cm): precision vertexing

- 3 layers of Monolithic Active Pixel Sensors (MAPS) closely based on ALICE's ITS2
- $5 \mu\text{m}$ position resolution for tracks with $p_T > 1$ GeV

INTT ($7 < r < 12$ cm): pileup separation

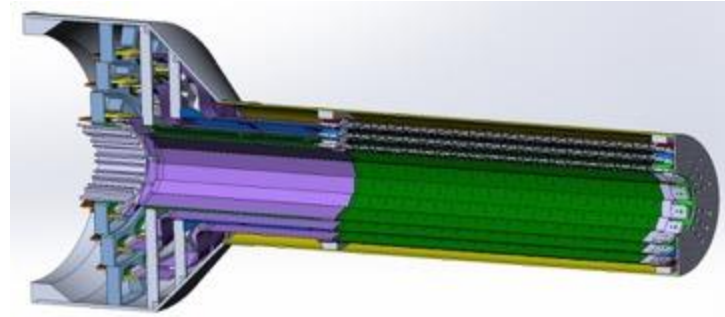
- 2 layers of silicon strips ($78 \mu\text{m}$ pitch)
- single-beam-crossing timing resolution

TPC ($30 < r < 78$ cm): momentum measurement

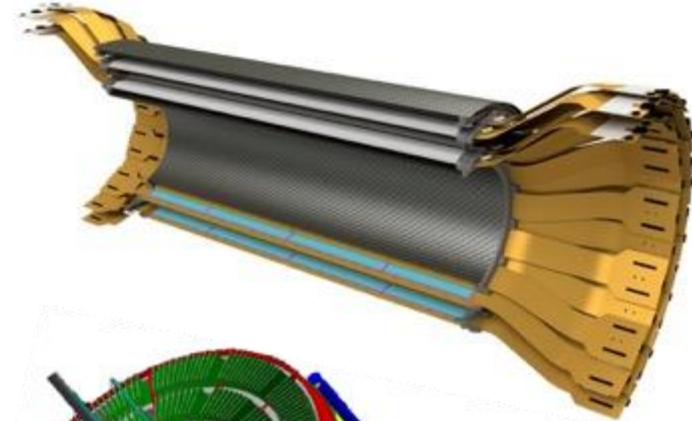
- Very compact GEM-based TPC: 48 layers with gateless and continuous readout.

TPC Outer Tracker (TPOT): calibration of beam-induced space charge distortions

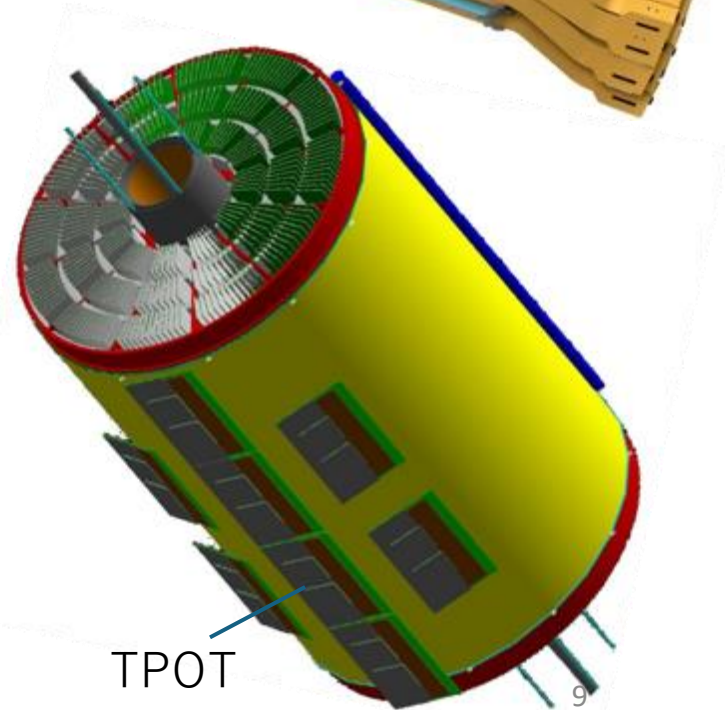
- 8 modules of Micromegas inserted between TPC and EMCal



MVTX

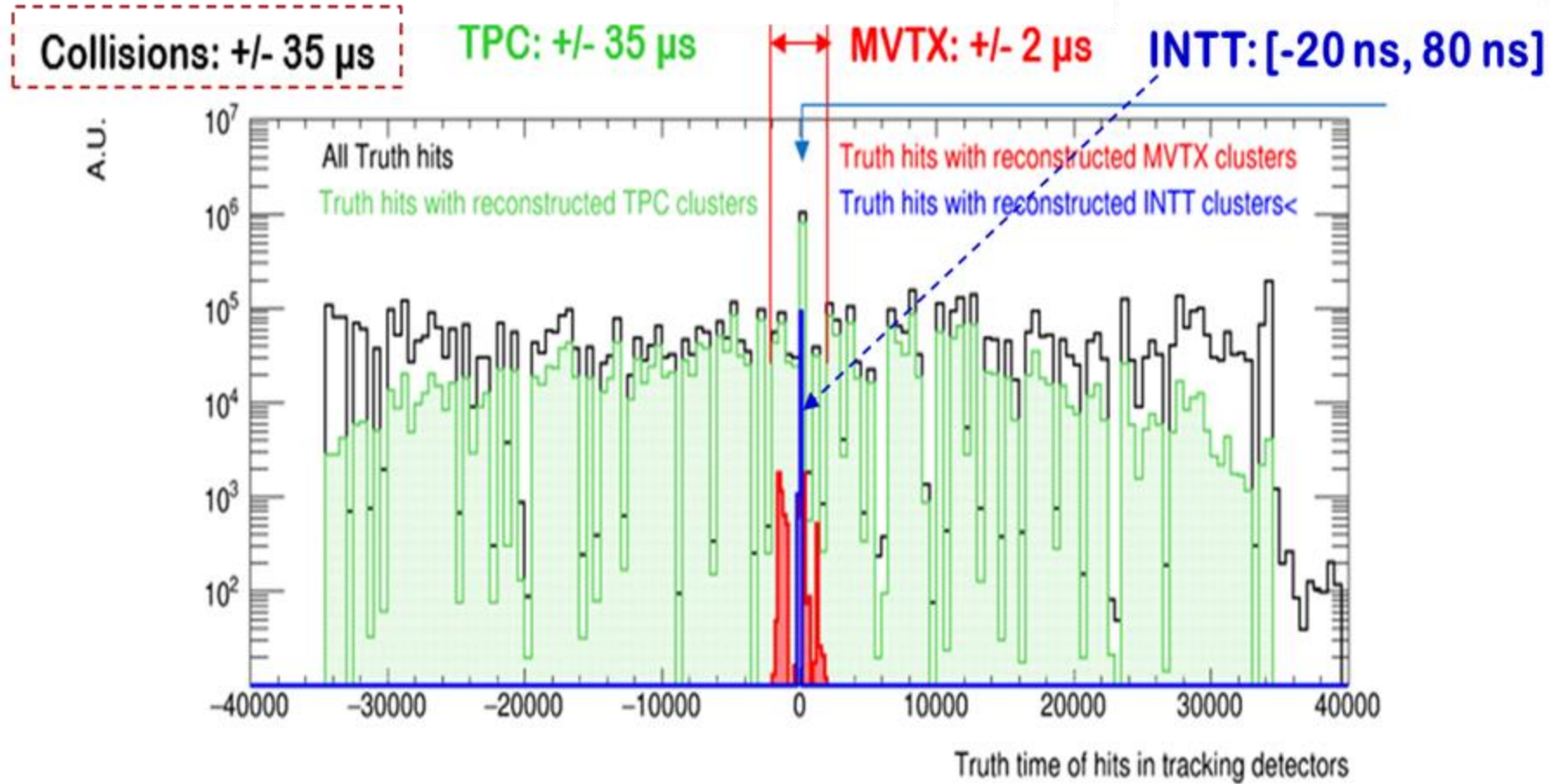
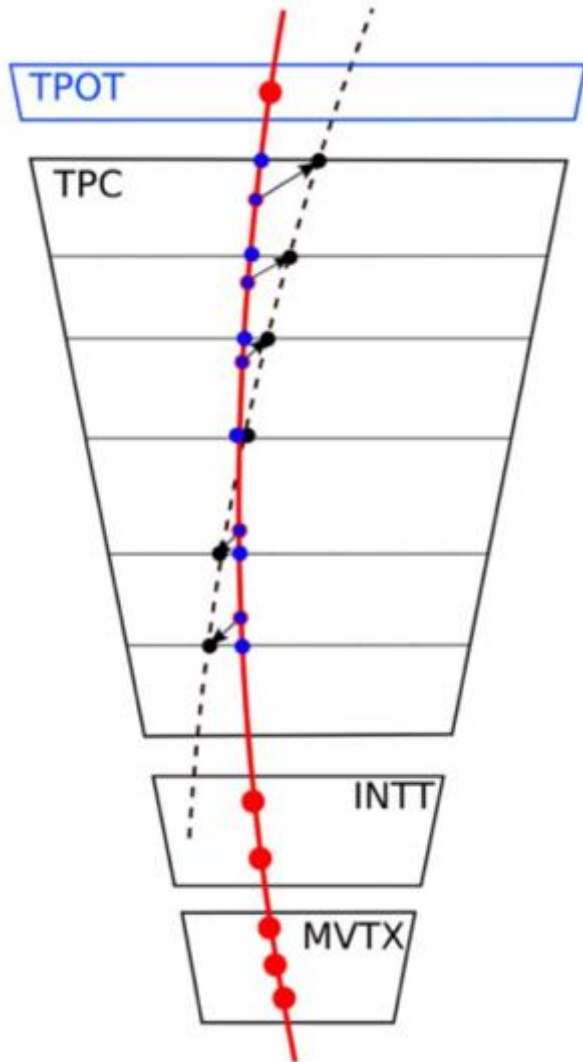


INTT



TPC

Tracking Points and Timing



Silicon Sensors

Design: Silicon and the Bethe-Bloch equation

- Doped silicon is our typical semiconductor
- A charged particle passing through a material releases energy and is measured by the Bethe-Bloch equation [[PDG](#)]:

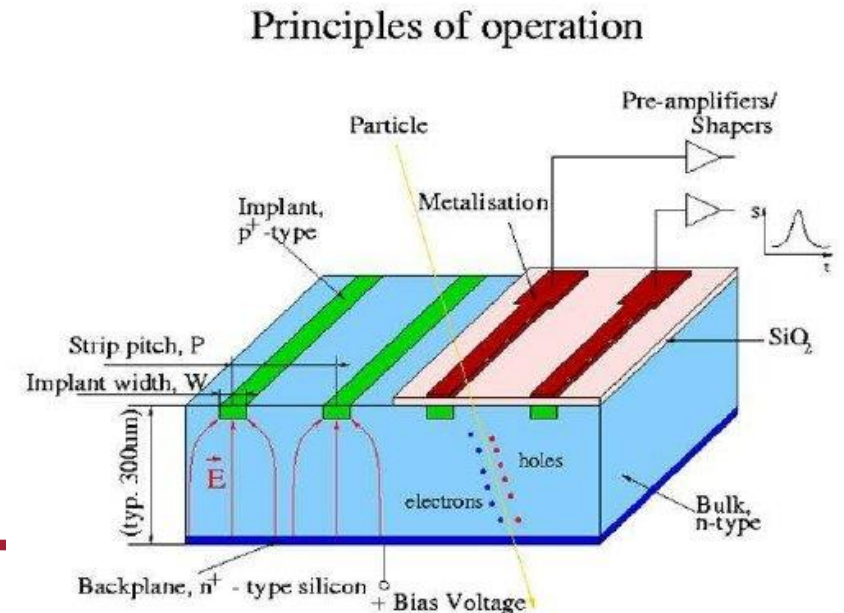
$$-\left\langle \frac{dE}{dx} \right\rangle \propto z^2 \frac{Z}{A} \frac{1}{\beta^2} \left[\frac{1}{2} \ln \left(\frac{2\gamma m_e c^2 \beta^2 K}{I^2} \right) - \beta^2 - \frac{\delta}{2} \right]$$

where K is the energy of the particle and I is the excitation energy

- It takes 3.6 eV to make an electron-hole pair
- A 1 GeV pion passing through silicon releases ~ 400 eV/ μm
- You get about 100 electrons produced for every micrometer of silicon in your detector

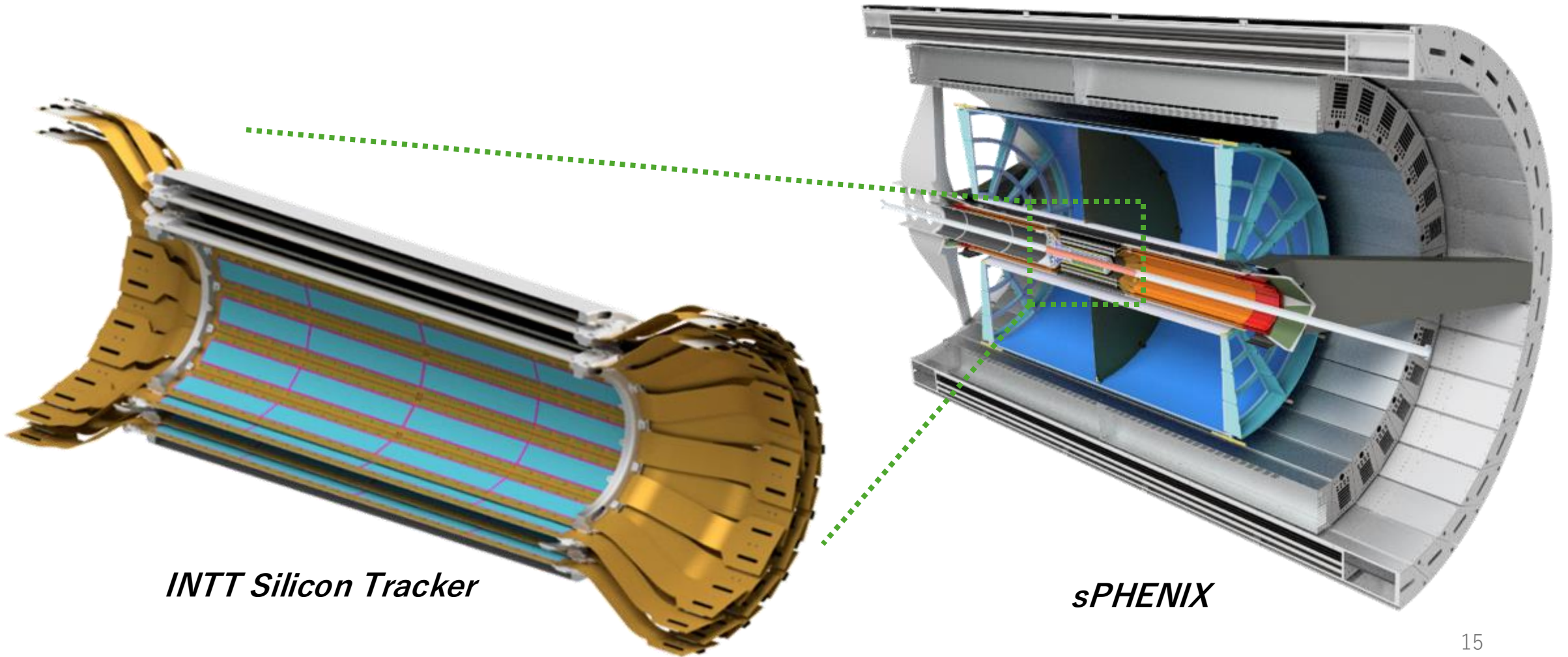
Design: The pn junction

- Silicon has 4 valence electrons
- Dope with a 5 valence element and you make an n-type material (donors)
- Dope with a 3 valence element and you make a p-type material (acceptors)
- Combine a p and n material and you create a depletion zone at the boundary and a pn junction where there's an electric field
- Apply a positive voltage to the n material and a negative voltage to the p material and we have a reverse-biased diode
- If we fully deplete the region, no charge can flow without external influence (our particles)
- Particles release energy in the silicon, create electron-hole pairs which we can pick up in our strips or pixels
- Width (W) of the depletion region

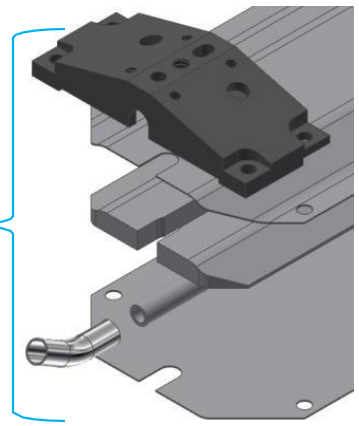
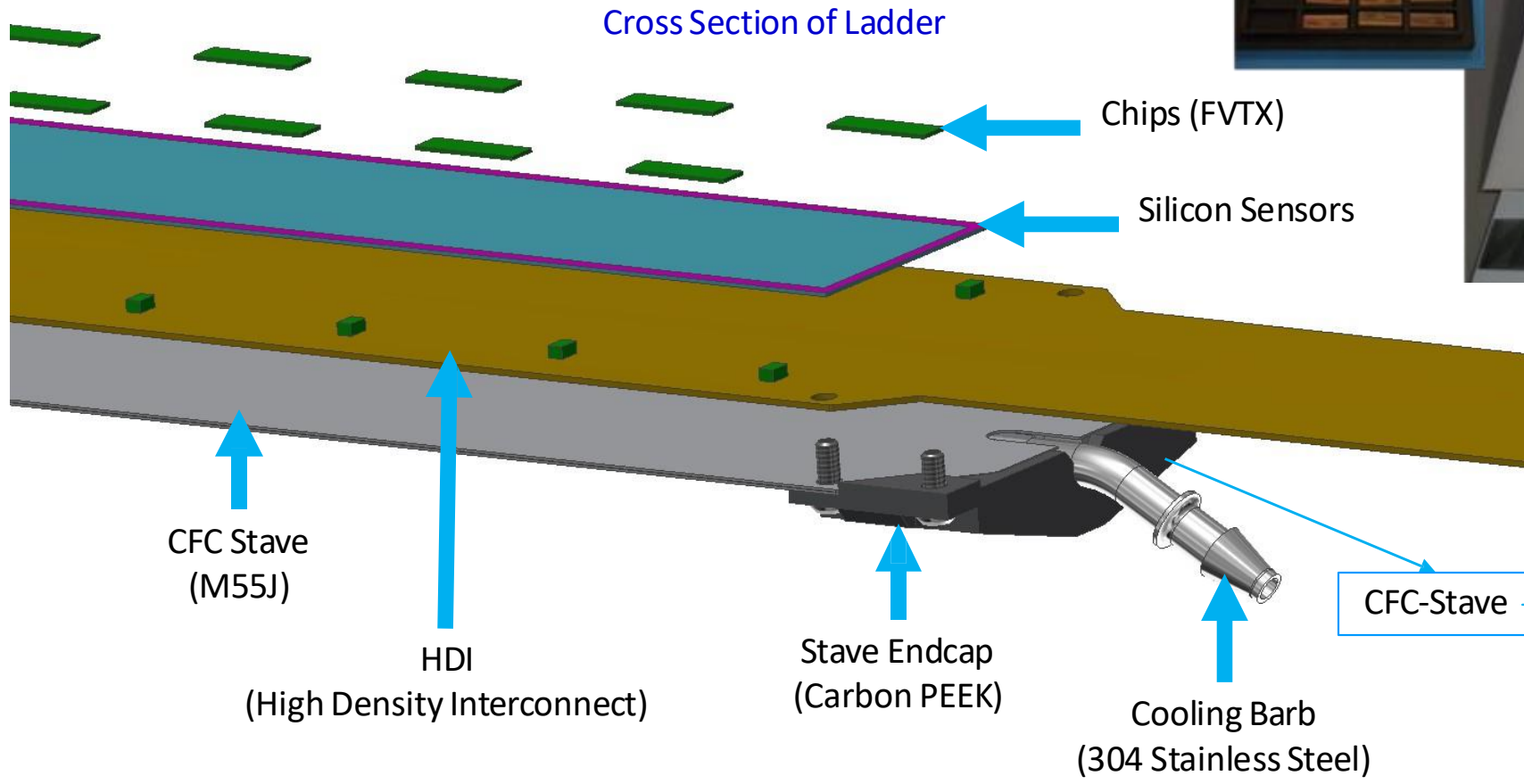


INTT

INTT Silicon Tracker

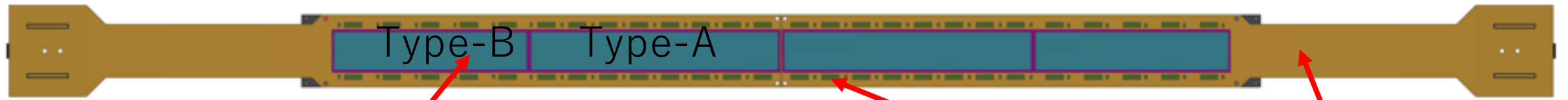


INTT Silicon Ladder



Assembled INTT Silicon Ladder

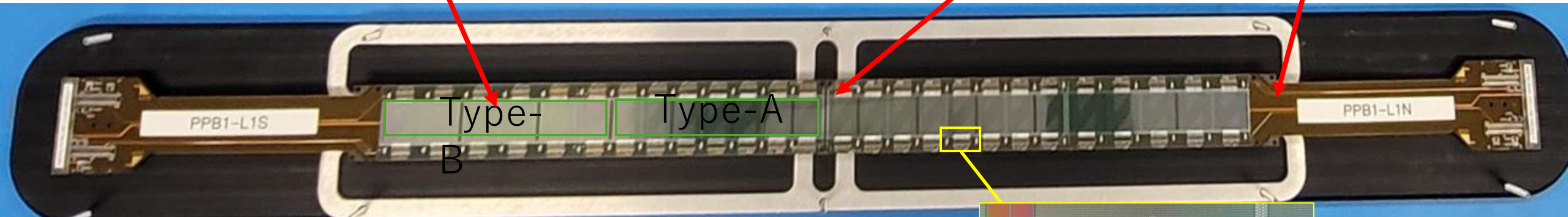
INTT Full Ladder



1. Silicon strip sensors

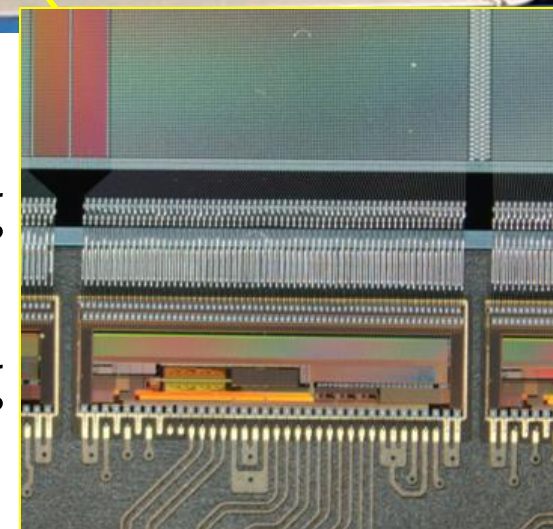
2. FPHX Chips

3. HDI Readout Cable



Wirebonding
(silicon-FPHX)

Wirebonding
(FPHX-HDI)

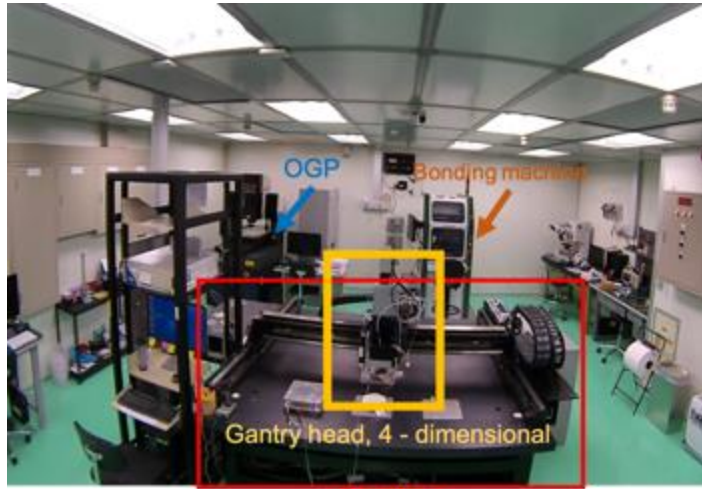


Silicon

FPHX Chip

HDI

INTT assembly in Taiwan



Taiwan Silicon Detector Facility (TSiDF)

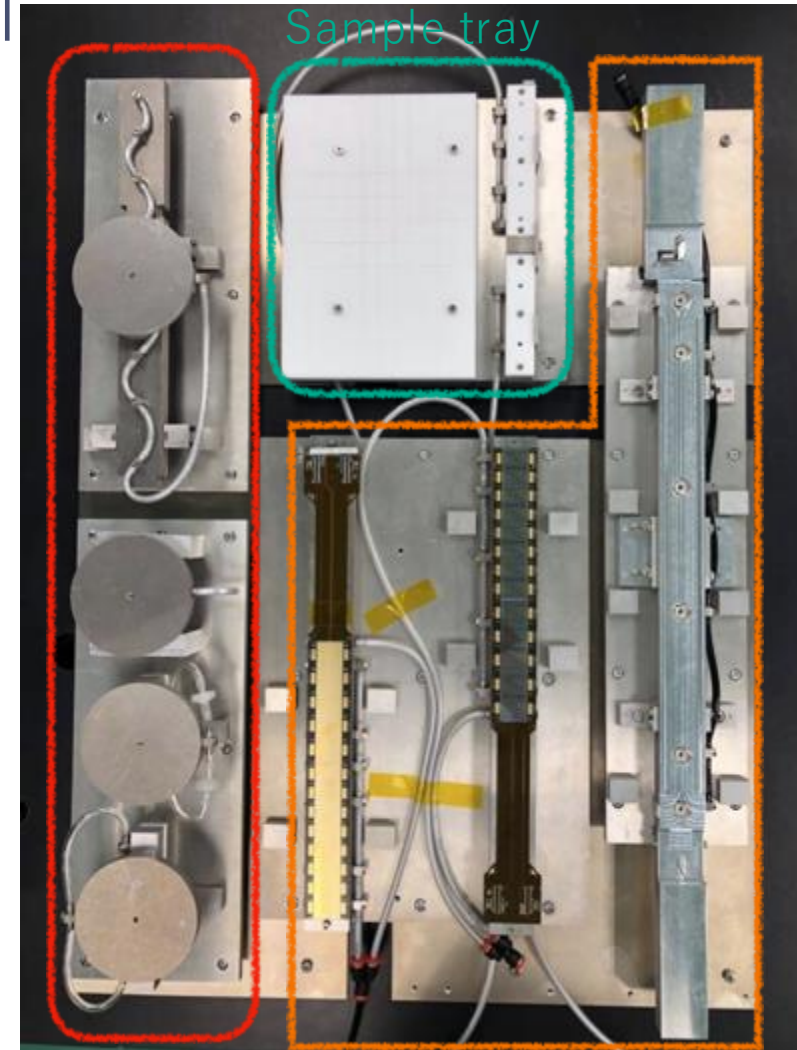
Assembly Unit : Half-ladder

Assembly procedures :

1. Chips glued on HDI then wire-bonded
2. Sensors glued on HDI then wire-bonded
3. Encapsulate all wire-bonds
4. Thermal cycles modules

Ladder assembly procedures :

- 2 half-ladder glued on stave



Pick up tools

Assembly tray

INTT assembly family on Gantry



Rong-Shyang Lu



Lian-Sheng Tsai



Wei-Che Tang



Jenny Huang



Kai-Yu Cheng



Cheng-Wei Shih



Ou-Wei Cheng

FPHX Chip/Produced by FNAL

Developed for Forward Vertex Detector for PHENIX at Fermi Lab.

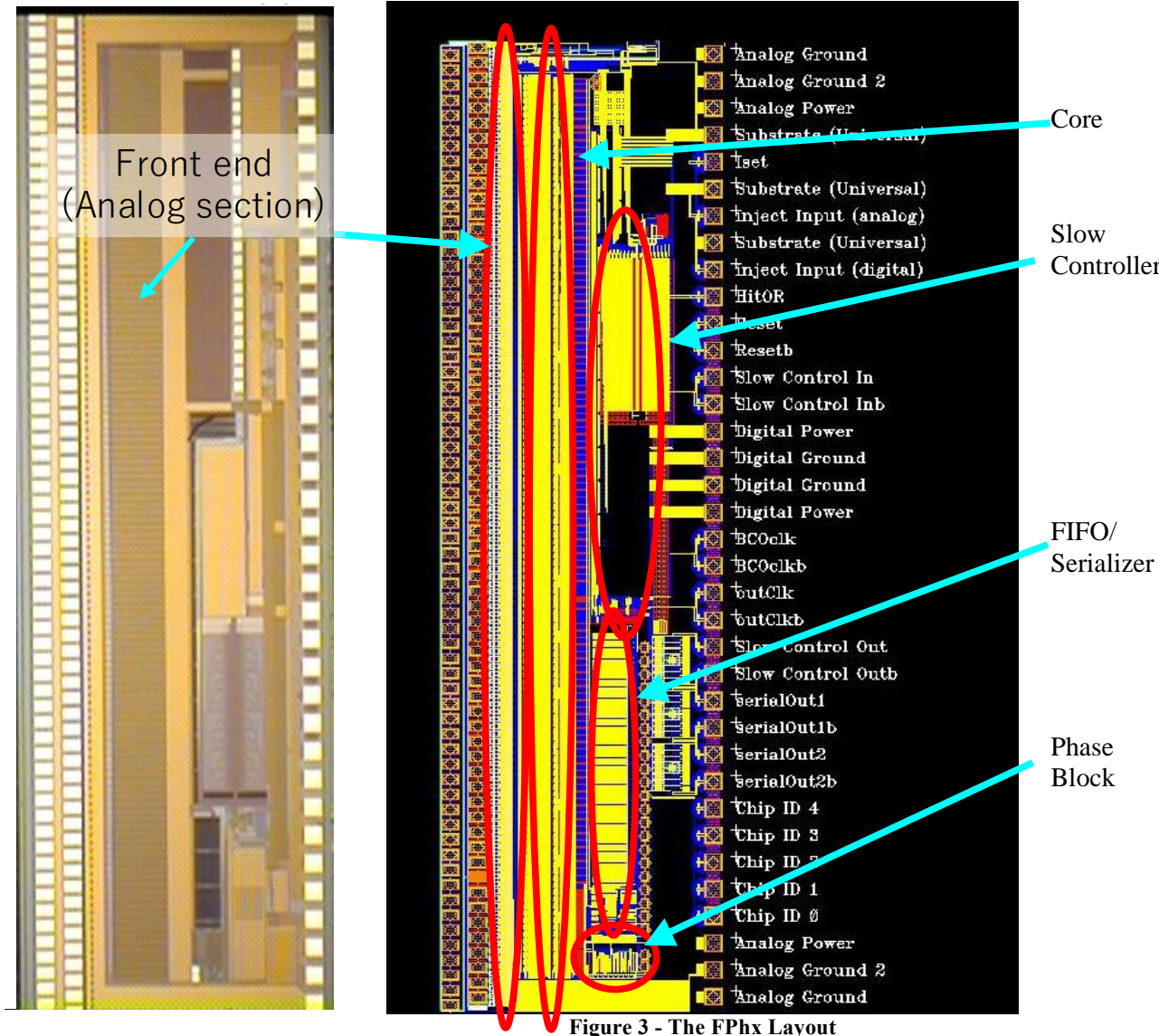
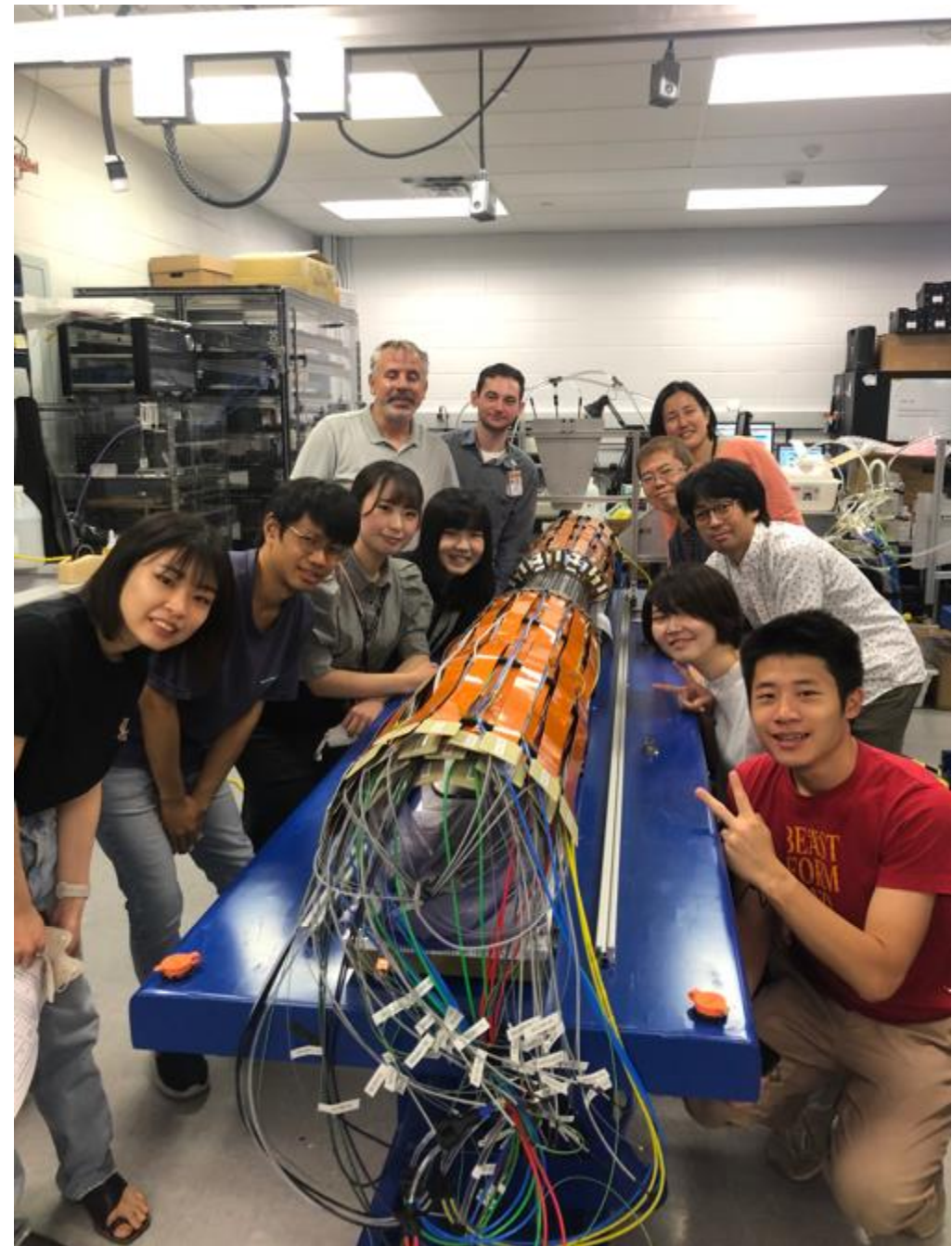
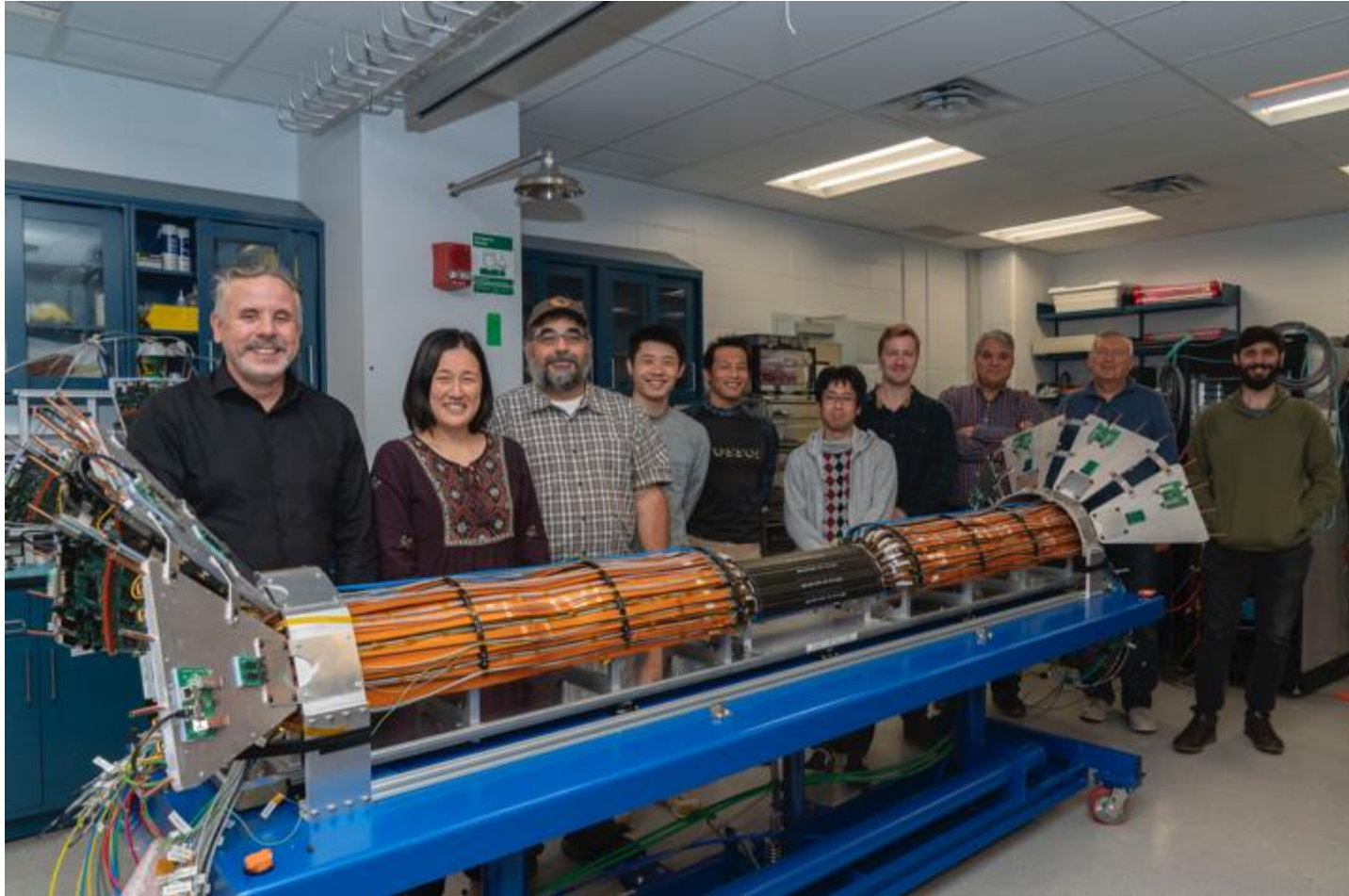


Figure 3 - The FPHX Layout

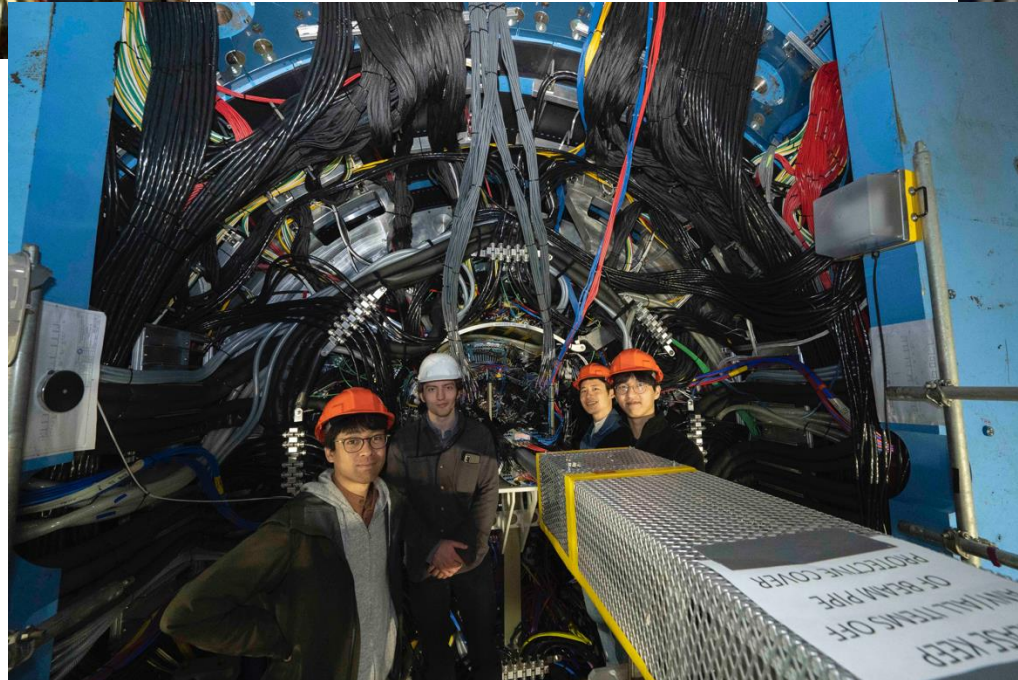
Specification	FPHX
ADC/channel	3 bits
Operation Voltage	2.5V
Power Consumption	64 mW
Number of channels	128
Data Transmission	200Mbps

Each FPHX chip integrates and shapes (CR-RC) signals, digitizes and sparsifies the hit channels each beam crossing (106ns beam clock), and serially pushes out the digitized data.

Barrel Assembly Completion

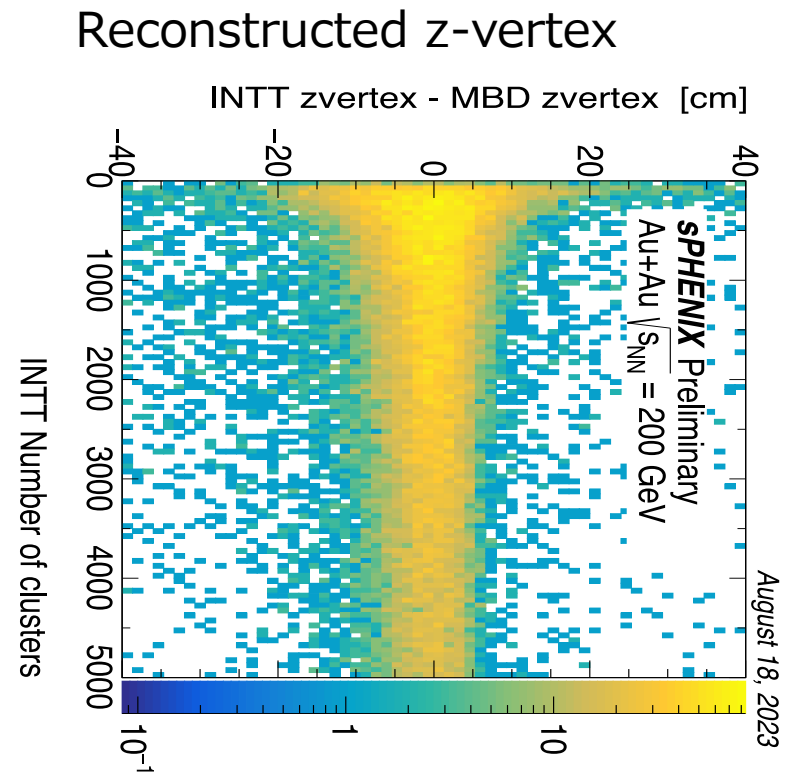
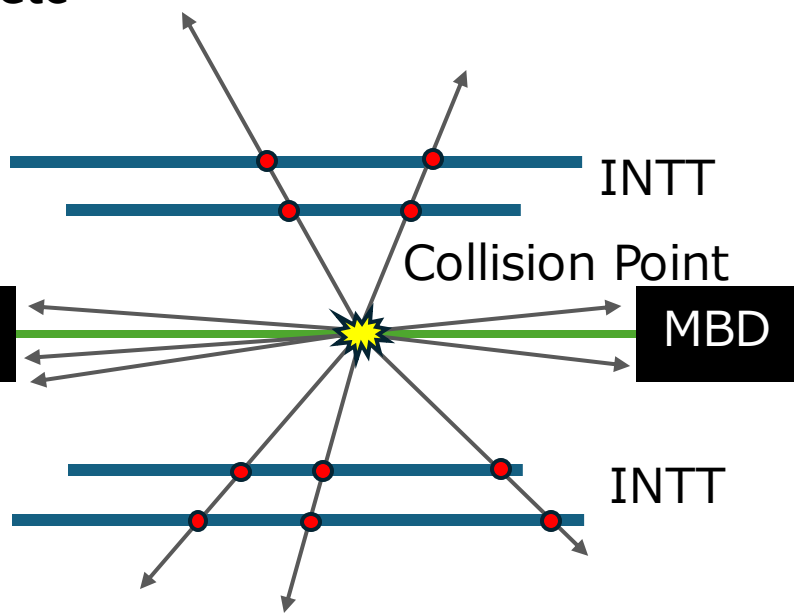
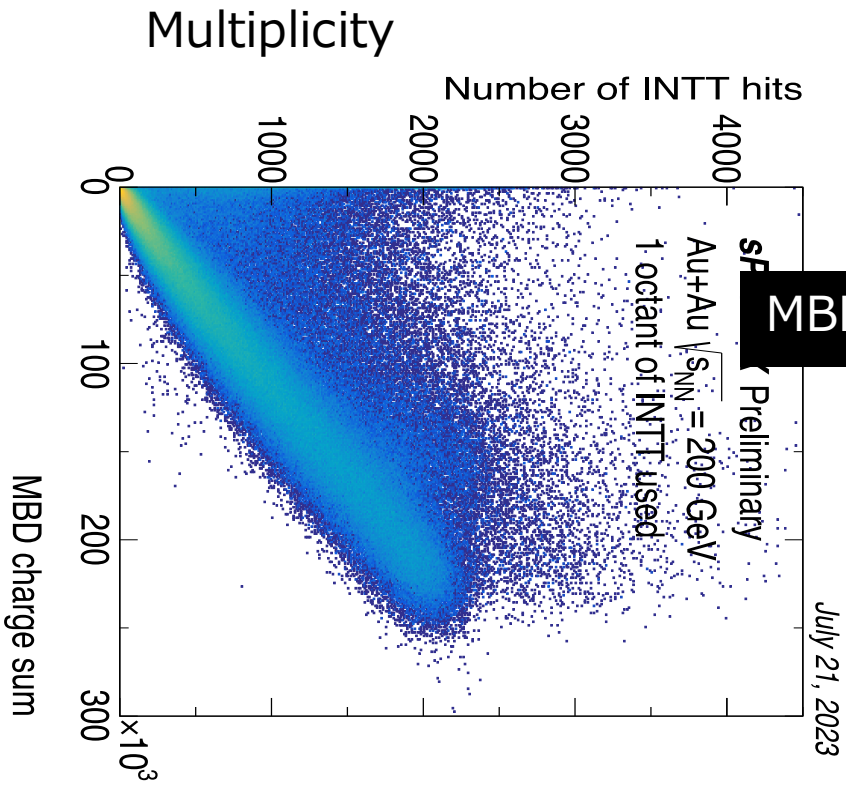


Installation to sPHENIX



Performance of INTT Silicon Sensors

- Active Strips ~ 99%
- Moderate dark currents
- etc



Reconstructed z-vertex proven to be consistent between MBD and INTT

MVTX

Cameron Dean

3rd sPHENIX in Asia Meeting

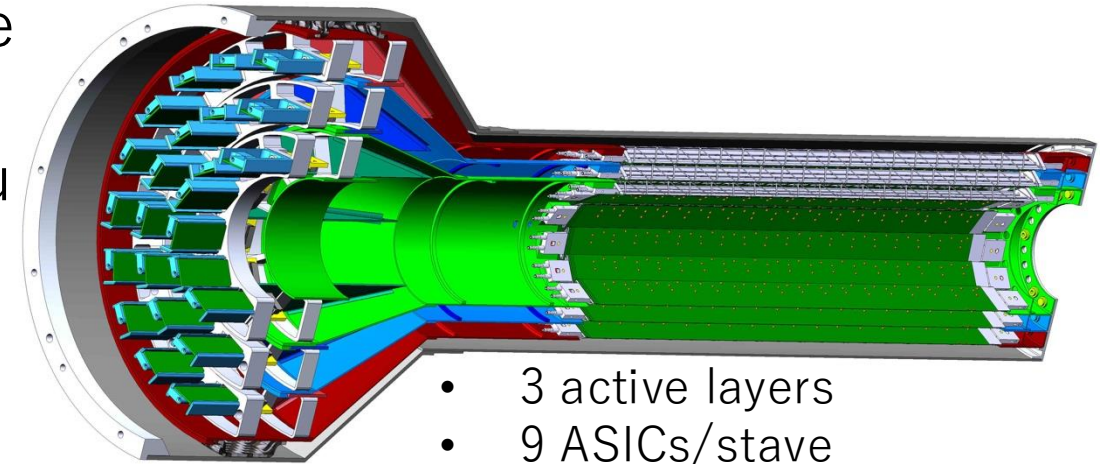
NCU, Taiwan

11/17/2022



The MAPS-based Vertex Detector

- Comprises of 3 layers of monolithic active pixel sensors using the ALICE ALPIDE
- The front-end readout uses the ALICE Readout
- The back-end uses the ATLAS FELIX
- Records from 2.5 cm to 4.5 cm, radially
- 226,492,416 pixels!



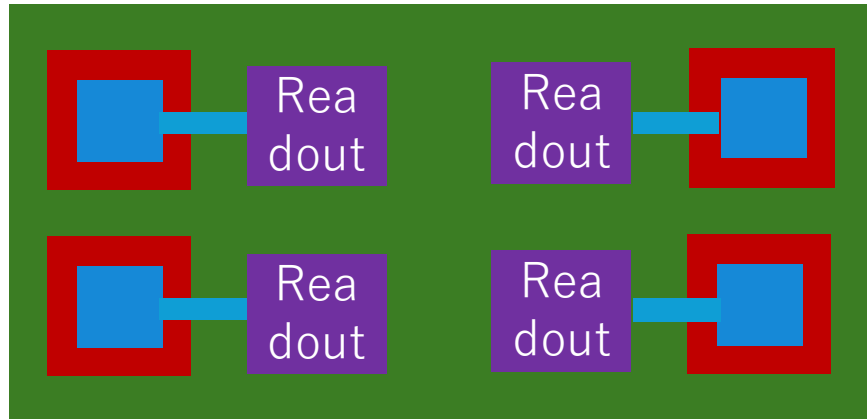
- 3 active layers
- 9 ASICs/stave
- 27 cm active length/stave

MVTX staves



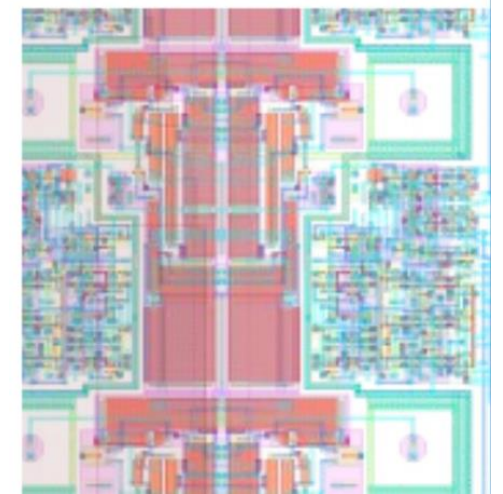
ALPIDE thickness [μm]	50
Pixel size [μm] / matrix	29 x 27 / 1024 x 512
Technology	180nm CMOS
Power Consumption [mW/cm^2]	40 (mean), 300 (peak)
Stave Material Budget	0.3% X_0
Timing resolution [μs]	$\sim 5 - 6$
XZ spatial resolution [μm]	< 6

Design: Monolithic active pixels sensors



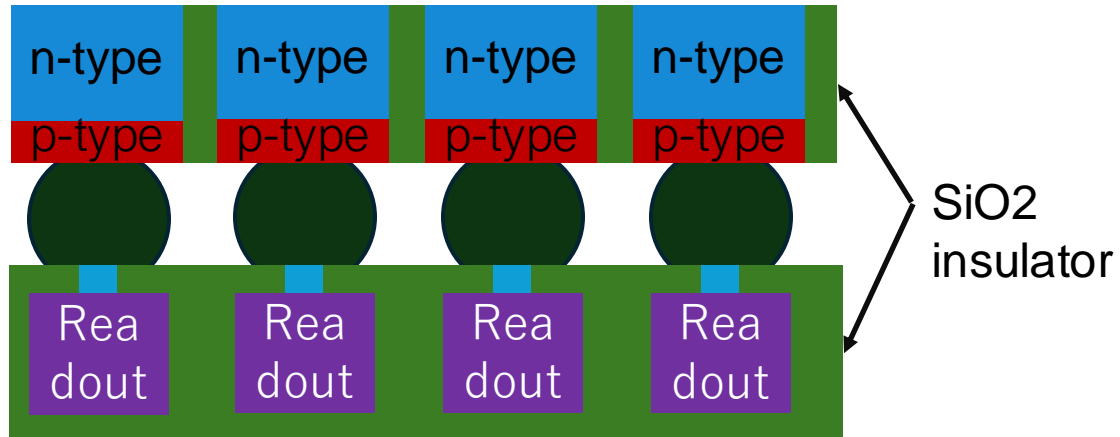
- Use Complementary Metal Oxide Semiconductor (CMOS) technology to build pixel directly on chip
- No bump bonding
- Small P-N width, no depletion voltage needed!
- Pixels can be small
 - Not driven by etching, bump size or placement precision
- Resolution is based on pixel size, p or pitch

$$\sigma_x = \sqrt{\langle \Delta x^2 \rangle} = \frac{\text{pitch}}{\sqrt{12}} \text{ where } \langle \Delta x^2 \rangle = \frac{1}{p} \int_{-p/2}^{p/2} x^2 dx$$



ALPIDE design for ITS-2 and sPHENIX MV

Design: Hybrid pixels



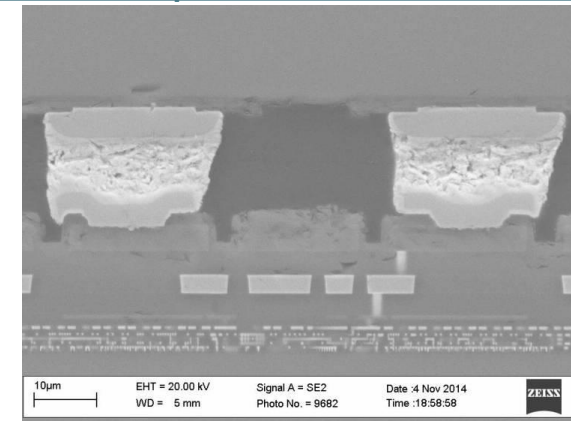
- Hybrid pixel detectors have 2 components
 1. A readout chip (typically ASIC for speed)
 2. A pixel matrix
- Each pixel must be bump-bonded to its chip readout
- Resolution is based on pixel size, p or pitch

$$\sigma_x = \sqrt{\langle \Delta x^2 \rangle} = \frac{\text{pitch}}{\sqrt{12}} \text{ where } \langle \Delta x^2 \rangle = \frac{1}{p} \int_{-p/2}^{p/2} x^2 dx$$

- Pitch is typically 50 – 100 μm

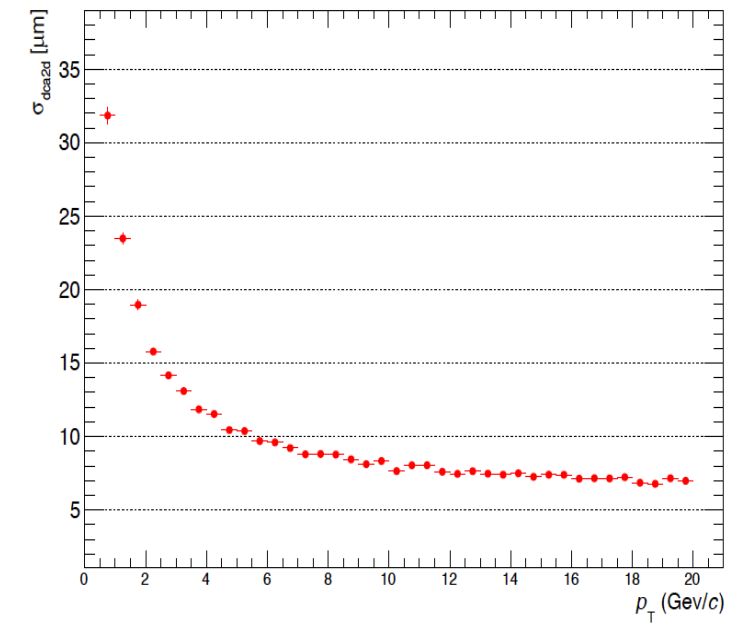
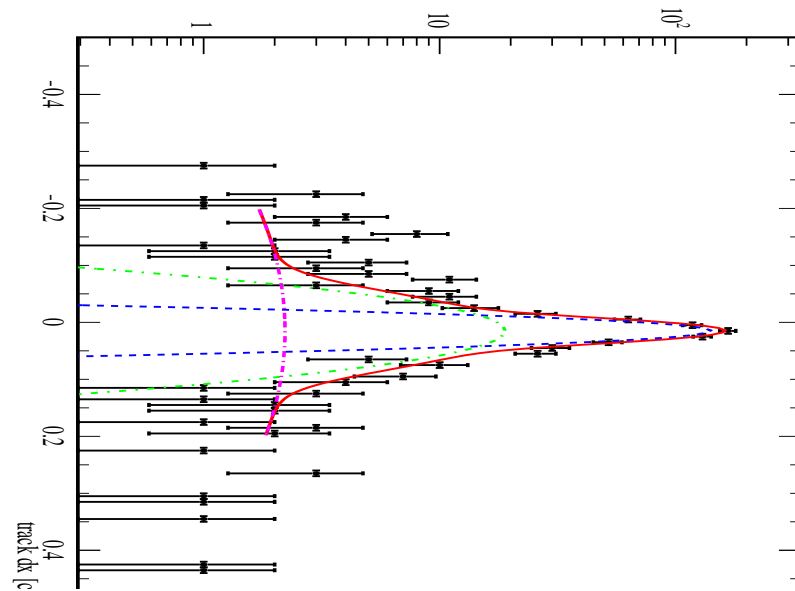
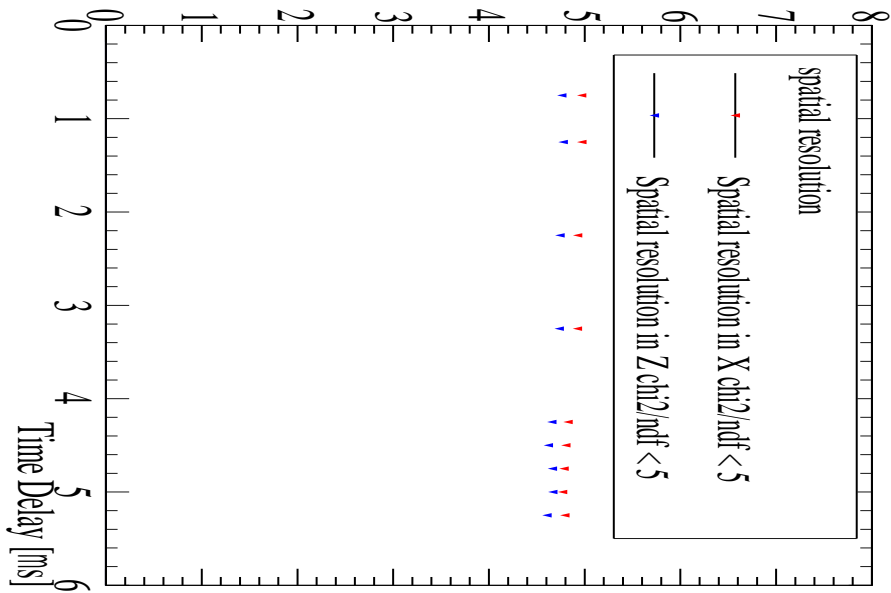


Timepix3 ASIC bump-bonded to a wafer, <https://medipix.web.cern.ch/medipix3>



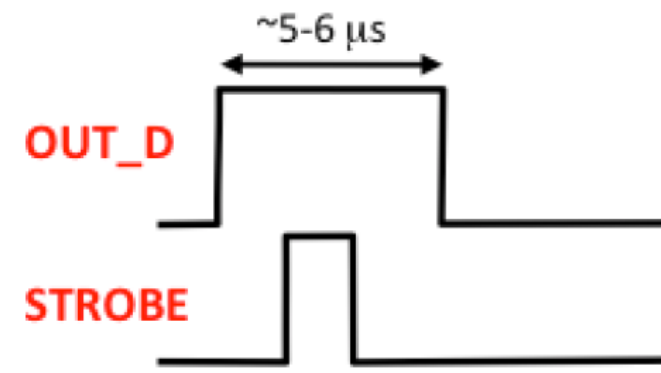
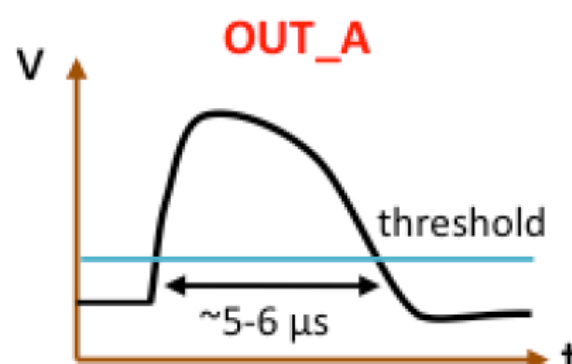
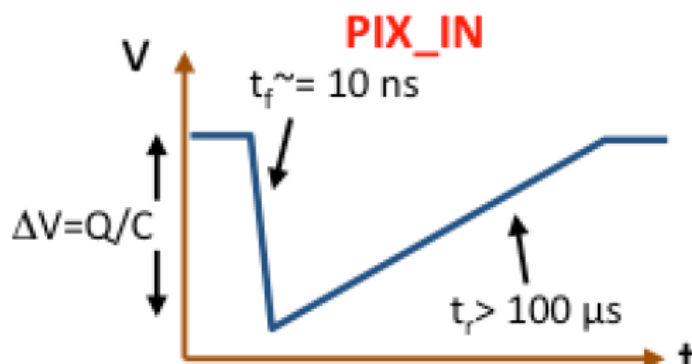
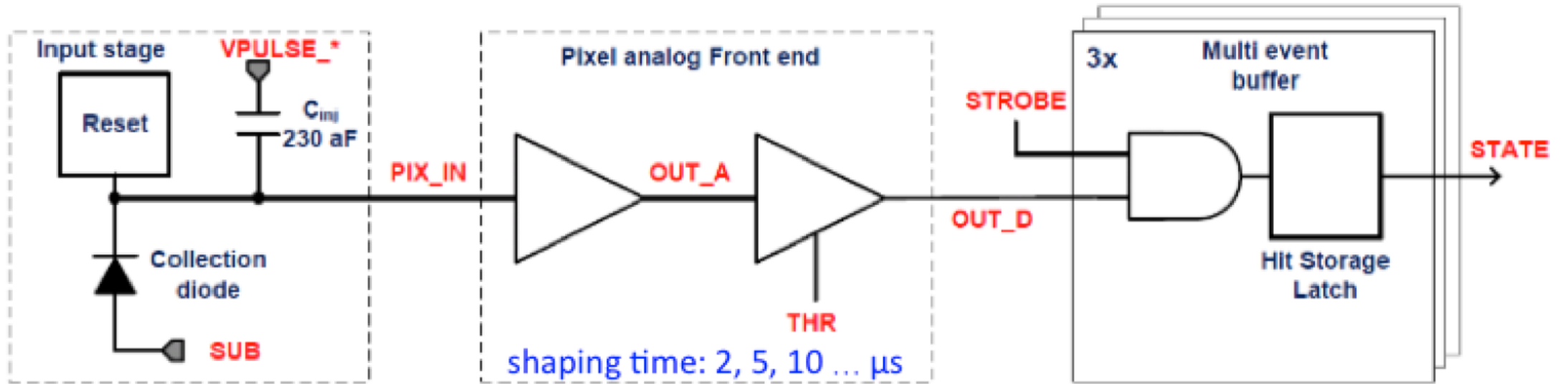
Medipix ASIC bump-bonded to a wafer, <http://x-ray.camera/technology/flip-chip-bonding/>

Physics capabilities

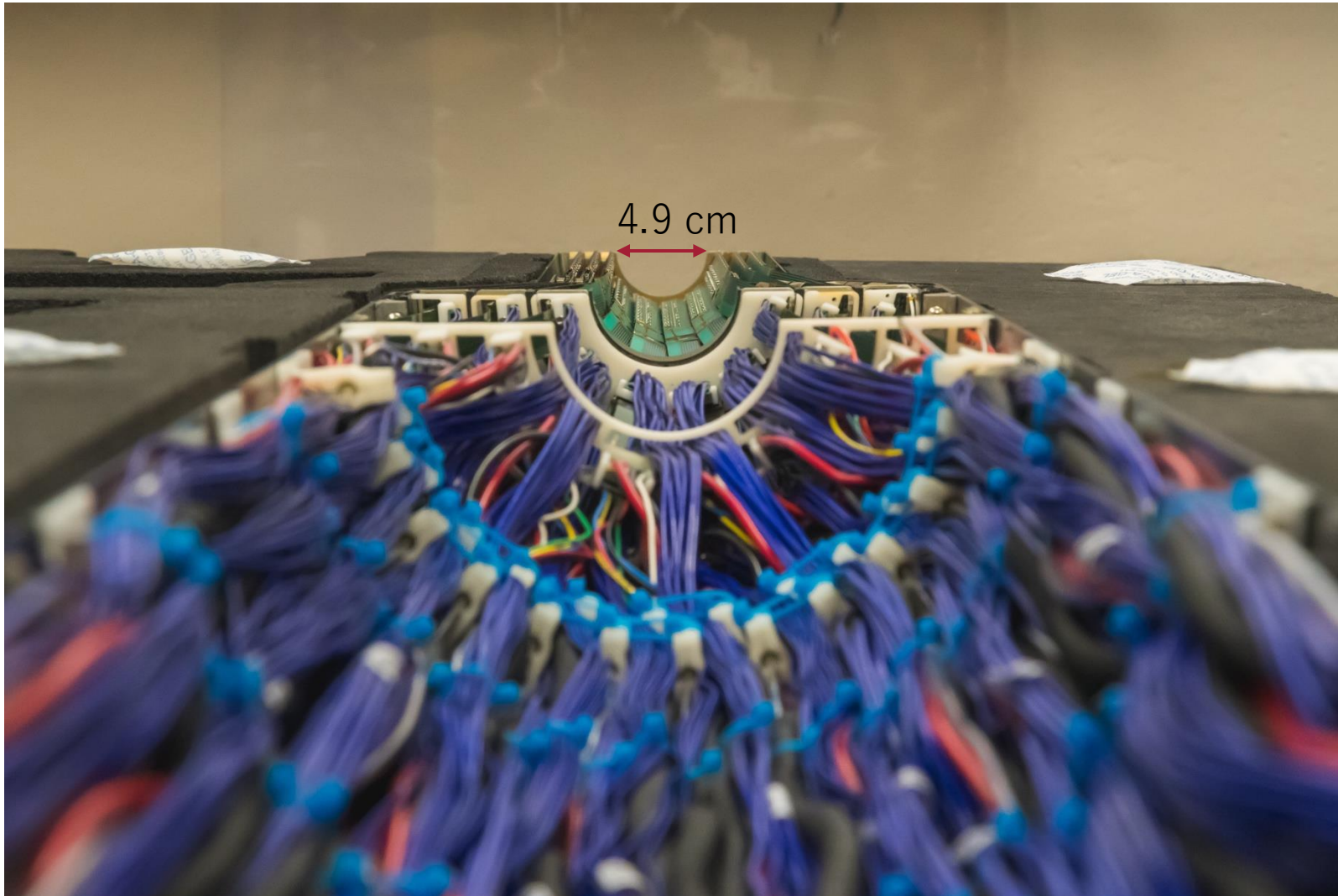


Left – MVTX spatial resolution as a function of trigger delay from test beam
Middle – MVTX track resolution from test beam
Right – sPHENIX DCA_{xy} resolution from simulation

MAPS Signal Processing Design



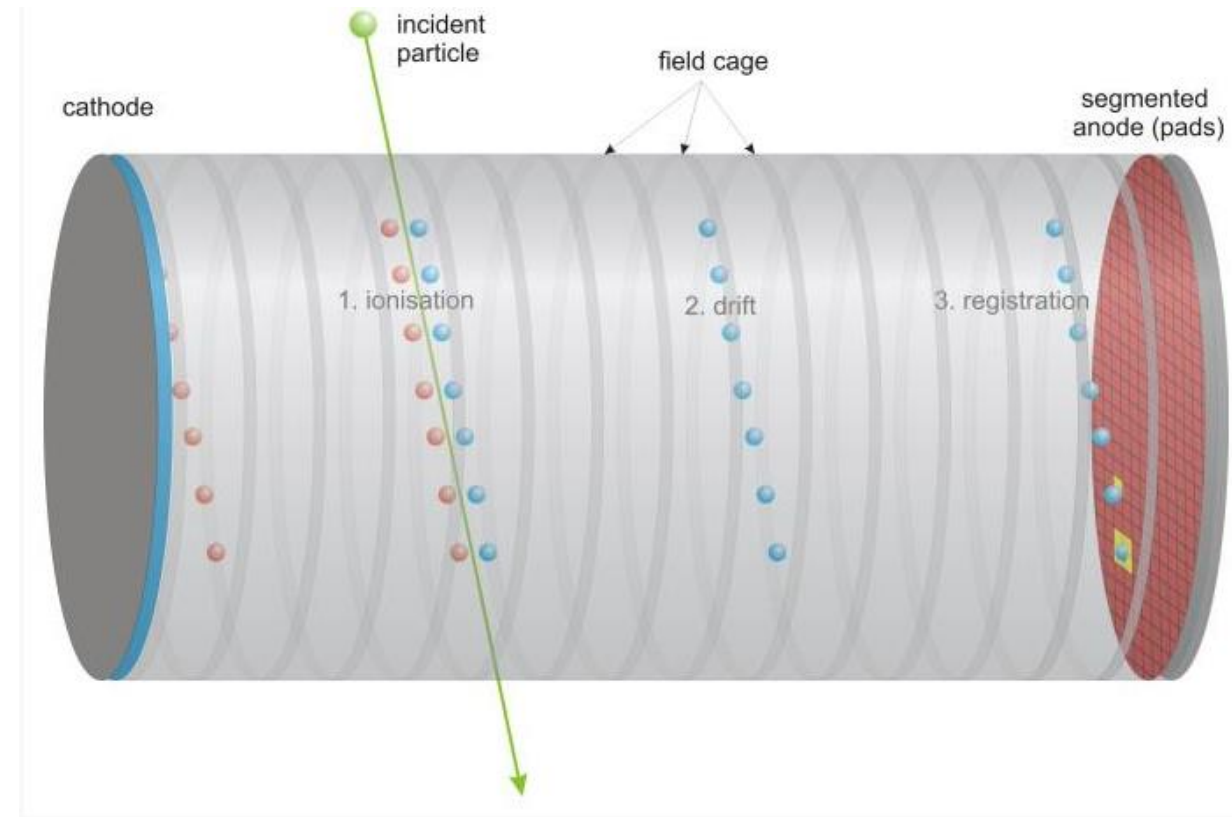
MVTX construction



TPC

What's a Time Projection Chamber ?

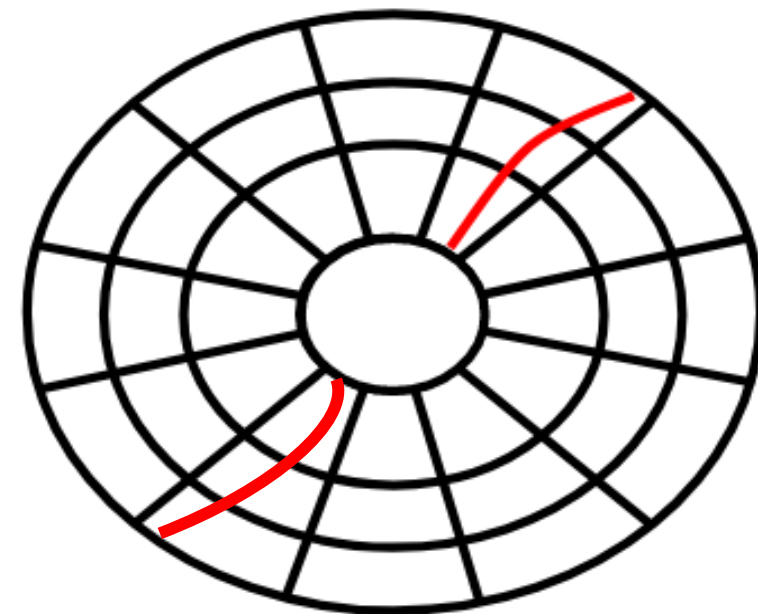
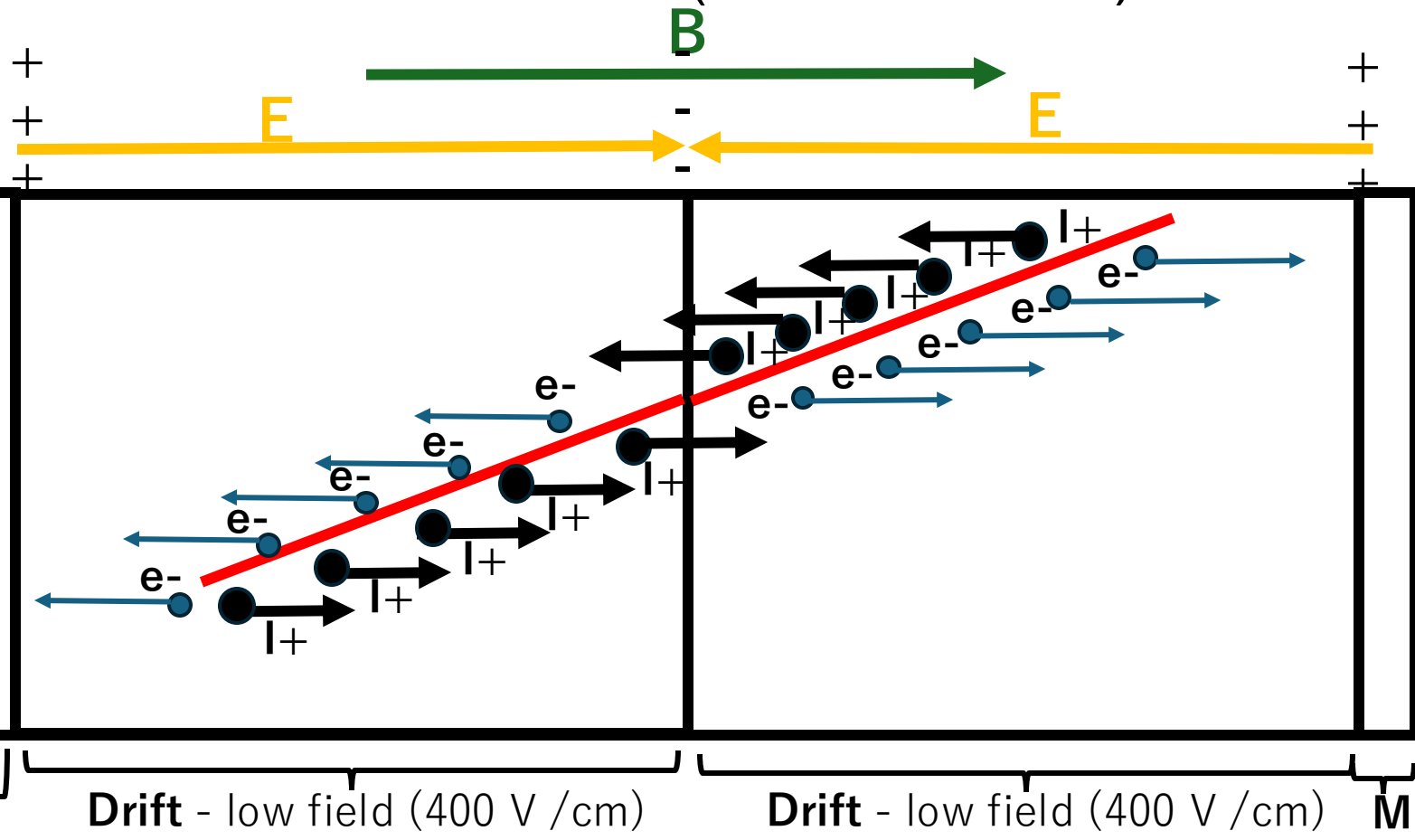
- Time Projection Chamber (TPC)
- Gaseous Drift Detectors
 - Big cylinder filled with (mostly) noble gas (Ne, Ar, etc...) and electric field
 - Particles come in, ionize gas, make electrons (and ions)
 - Electrons drift to anode plane – are read out



Source: <https://www.lctpc.org/e8/e57671>

What's a Time Projection Chamber

- Double sided TPC (like sPHENIX)



Drift - low field (400 V / cm)

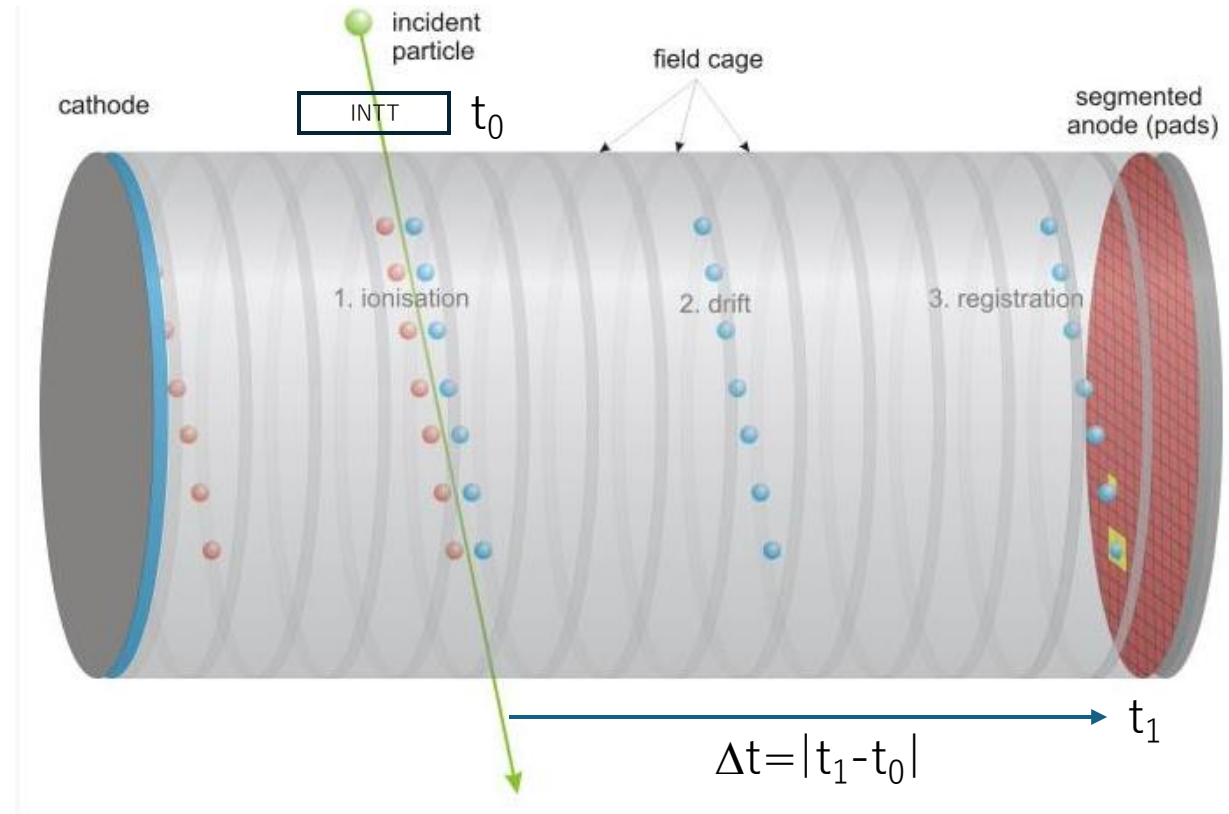
Drift - low field (400 V / cm)

Multiplication* ~ high (~50 kV / cm)

Multiplication* ~ high (~50 kV / cm)

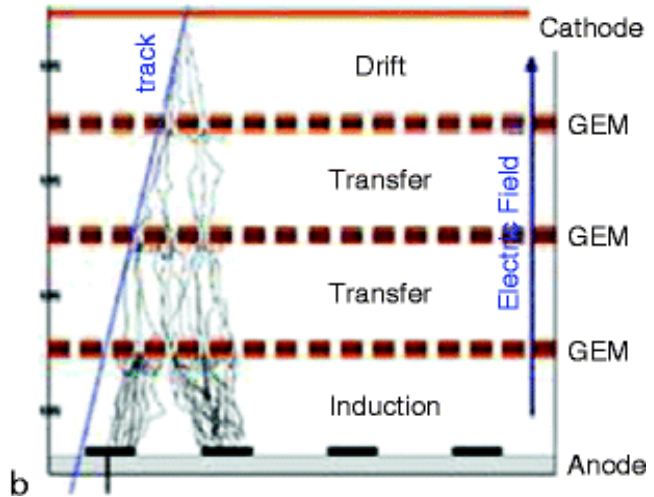
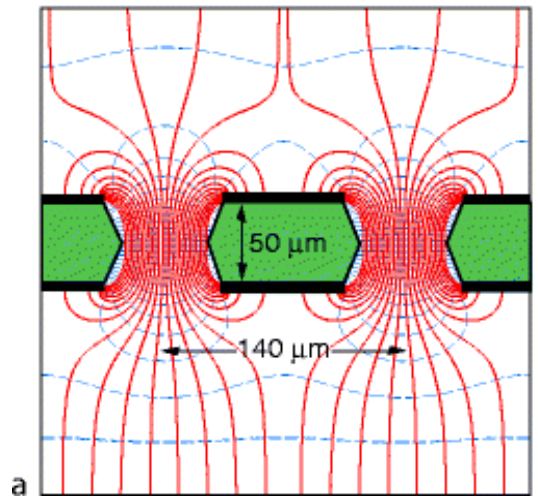
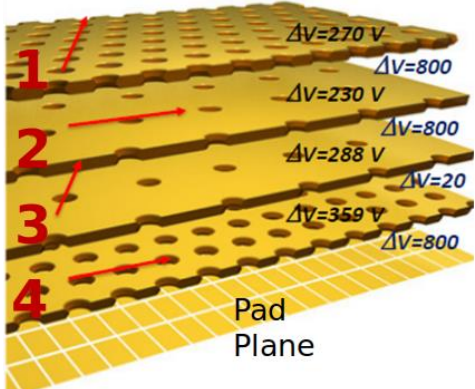
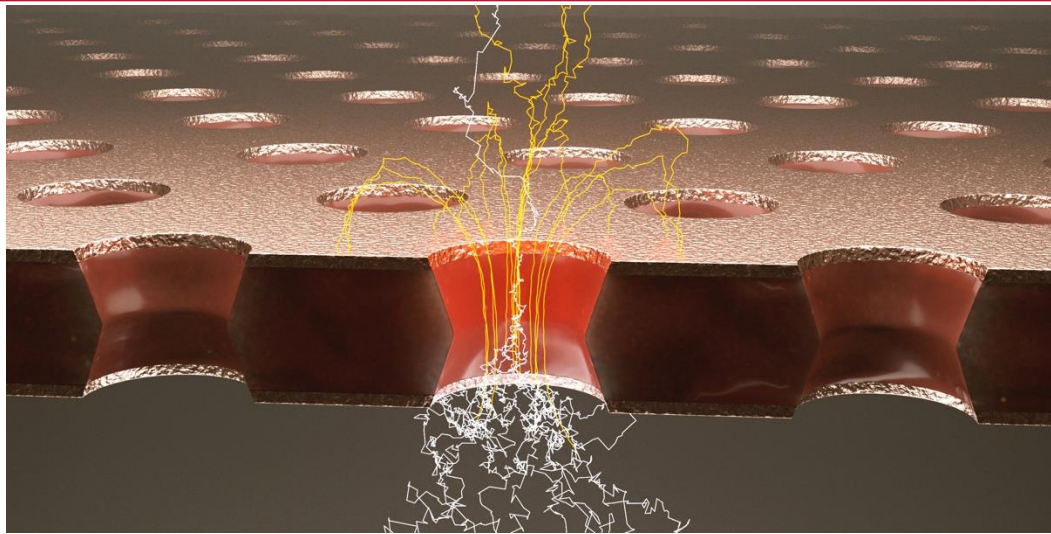
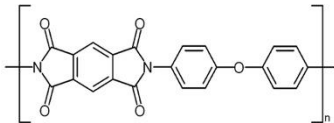
How TPC Works?

- The $r\phi$ position (coordinates perpendicular to the cylinder axis) of the trajectory can be reconstructed directly from the coordinates of its projection on the pad plane.
- The z position (coordinate along the cylinder axis) is reconstructed from the drift time (time between particle passing the TPC volume and measured signal on the pads).
- Therefore an external timing information, e.g. from a silicon detector is needed.



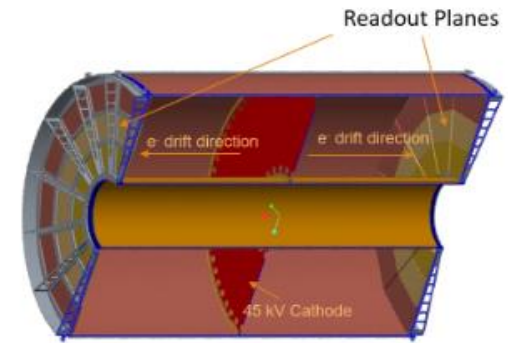
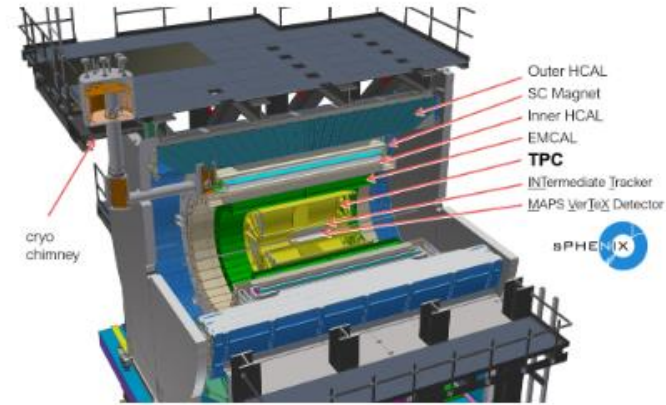
Multiplication Region – How do you get those high fields

- Gaseous Electron Multiplier (GEM) Foils
 - Creates specific field shape in holes
 - Inside holes – Townsend Avalanche
- Copper/Katpon/Copper w/ holes
 - 50 μm depth
 - 70 μm hole diameter
- Form stack with mutiple (4) foils
 - Each GEM in the stack has varying pitch between holes



sPHENIX TPC Overview

- Gaseous Drift Detector
 - Ar/CF₄ 60:40 % drift gas
 - O(13 μs) drift time
 - GEM (Gaseous Electron Multiplier) amplification
 - 4 Kapton + Copper GEMs / module
 - Un-gated like ALICE TPC
 - Allows for streaming readout
 - Zig-zag segmented copper sensor pads
 - Improves position resolution
- 72 GEM modules/2 sides
 - 36 modules / full φ
 - 3 modules / full r
 - 20 < r < 78 cm, |η| < 1.1, full φ
- Measures Momentum
 - Target momentum resolution:
 - Δp/p = 0.02 * p
 - O(150 μm) spatial resolution



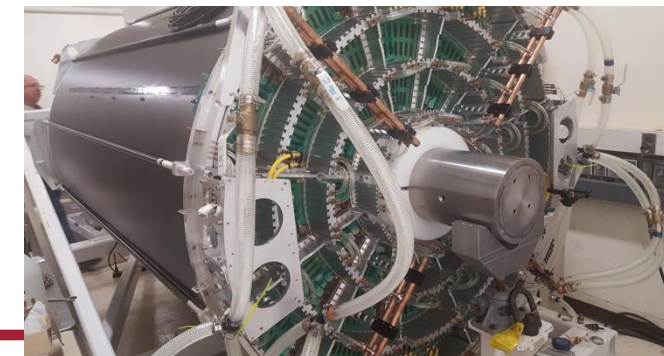
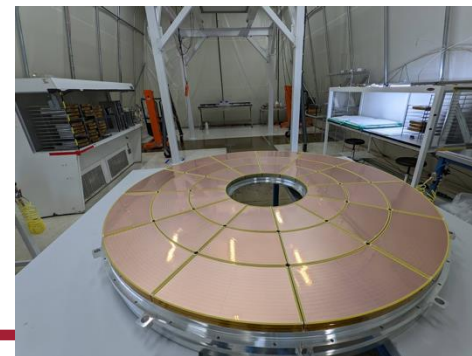
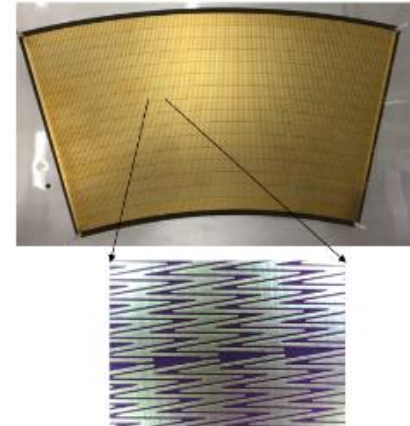
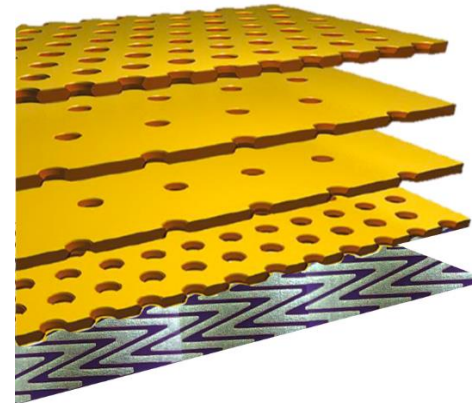
$$E_{\text{drift}} = 400 \text{ V/cm}$$

Standard pitch not rotated

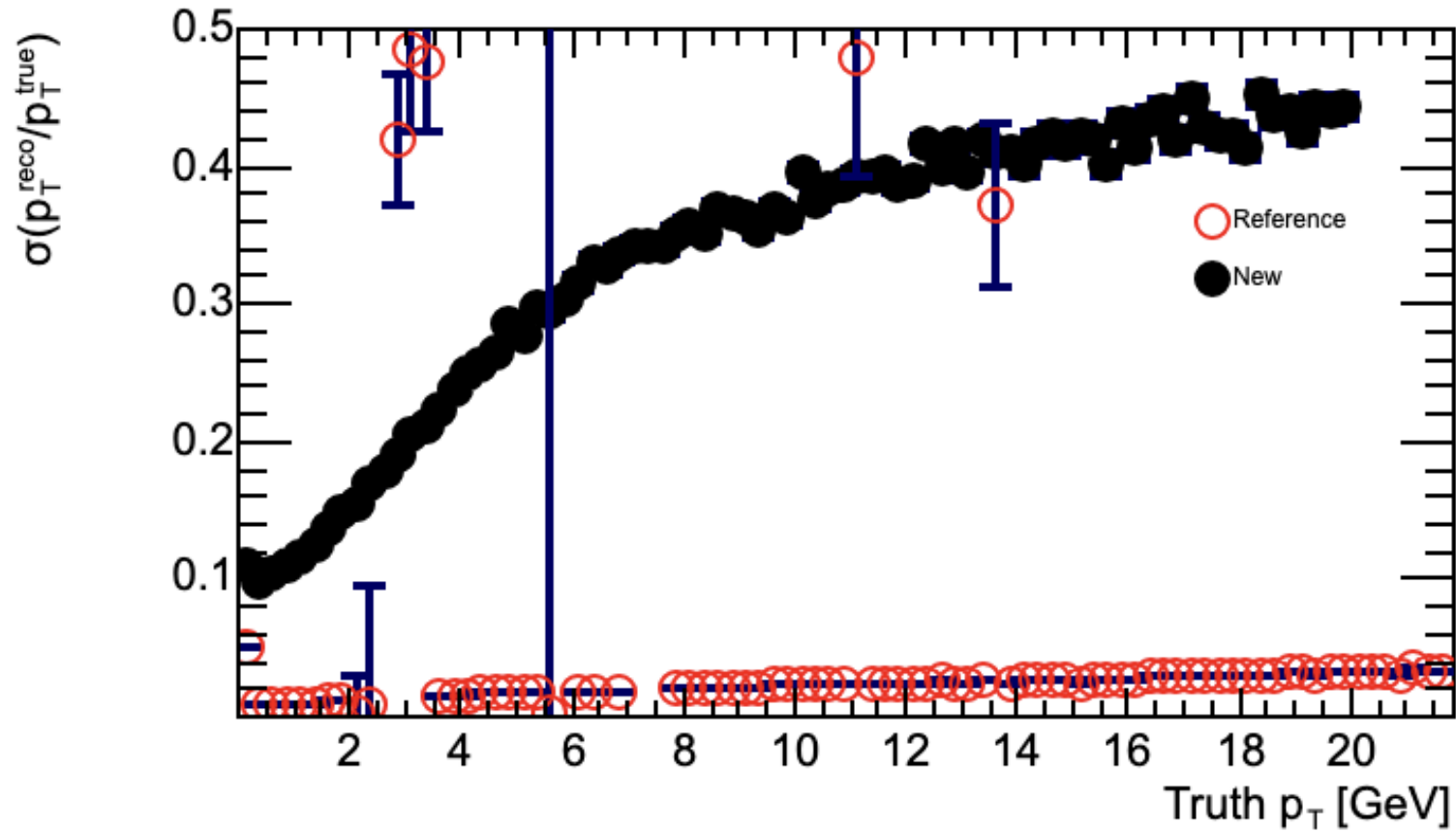
Large pitch rotated

Large pitch not rotated

Standard pitch rotated



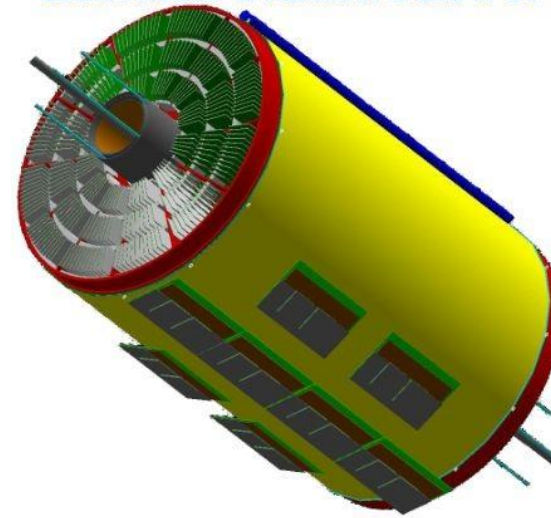
Momentum Resolution w and w/o TPC



TPOT - Time Projection chamber Outer Tracker

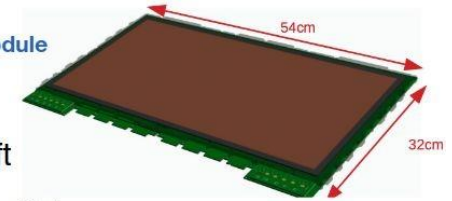
- Gaseous Drift Detector
 - Ar/HC(CH₃)₃ 95:5 % drift gas
 - 3 mm drift length
 - Micromegas amplification
 - Resistive layer w/ strips for readout
- 8 modules/bottom of TPC
 - Fully covers 1 TPC sector/side
 - Partially covers 2 other TPC sectors/side
- Provides reference for TPC
 - O(100 μm) spatial resolution
 - Provides check for TPC calibration

Geant4 view of sPHENIX TPC and TPOT

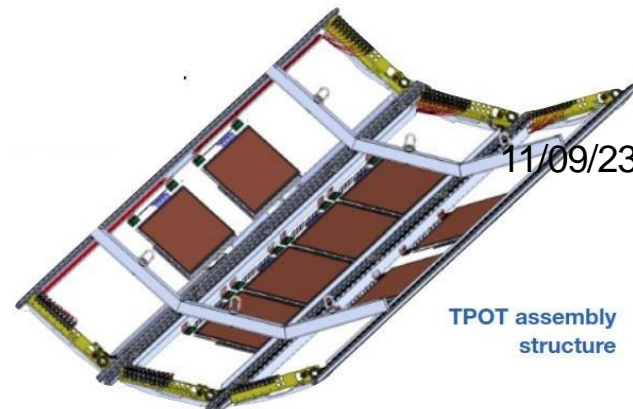


Each module = 2 bulk, resistive 1D-Micromegas detectors (back-to-back)

TPOT module



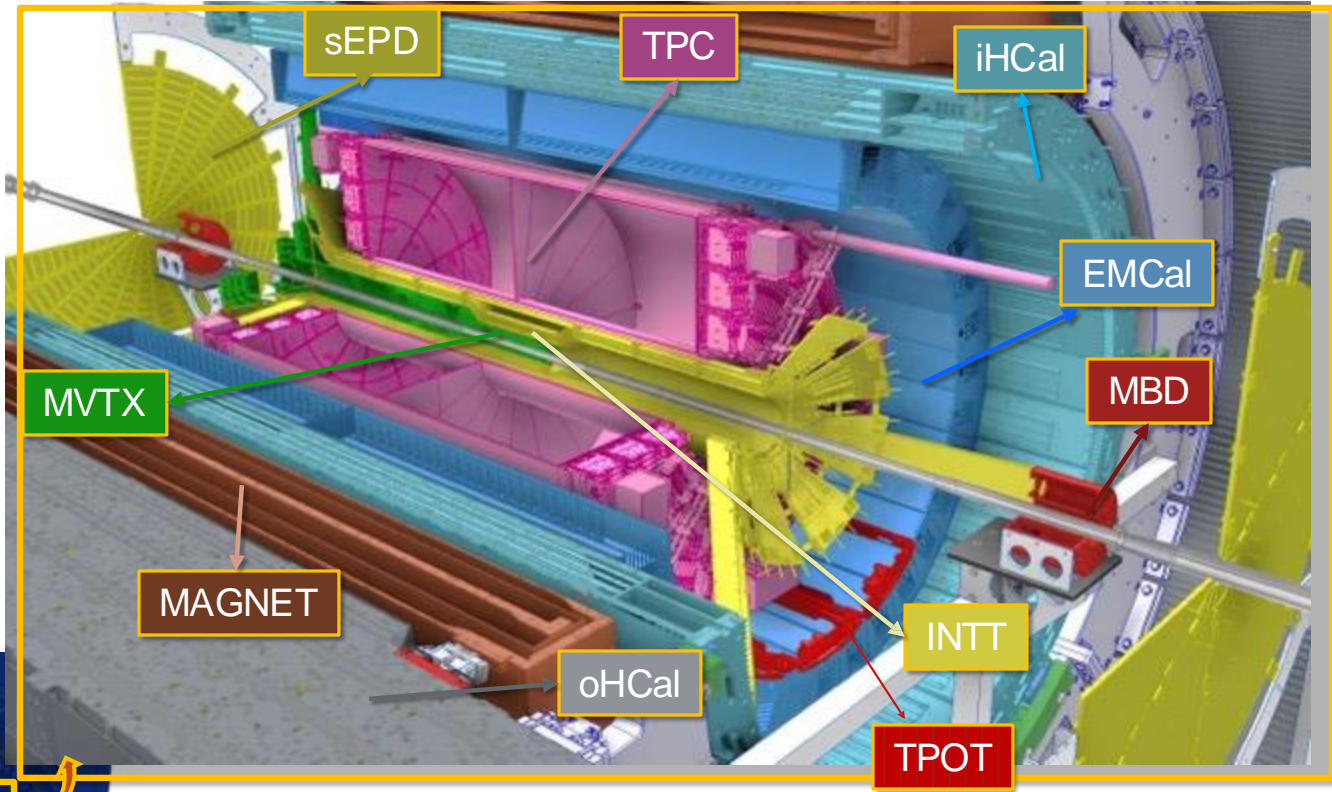
- ▶ Carbon drift
- ▶ 1mm/2mm pitch
- ▶ Ar/Isobutane (95/5)
- ▶ **Resistive** layer with strips



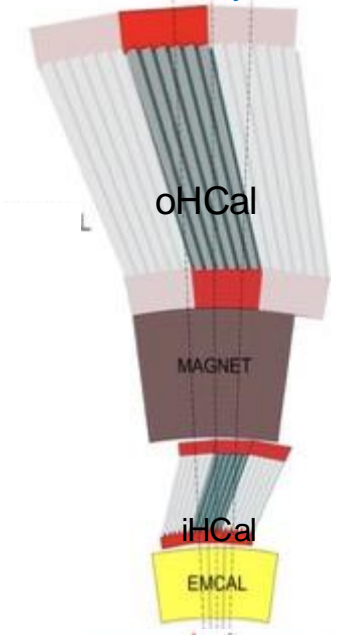
TPOT assembly structure



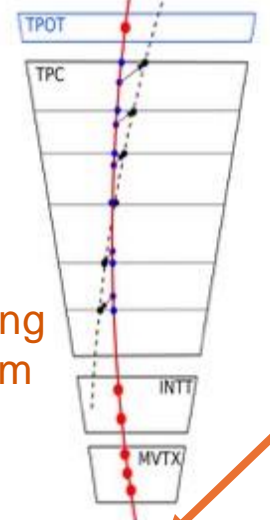
sPHENIX Detector



Calorimeter system

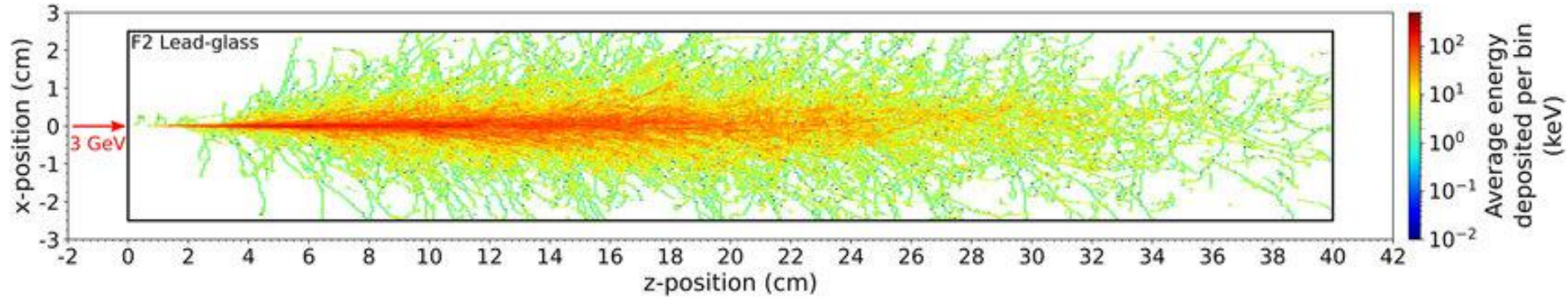


Tracking system

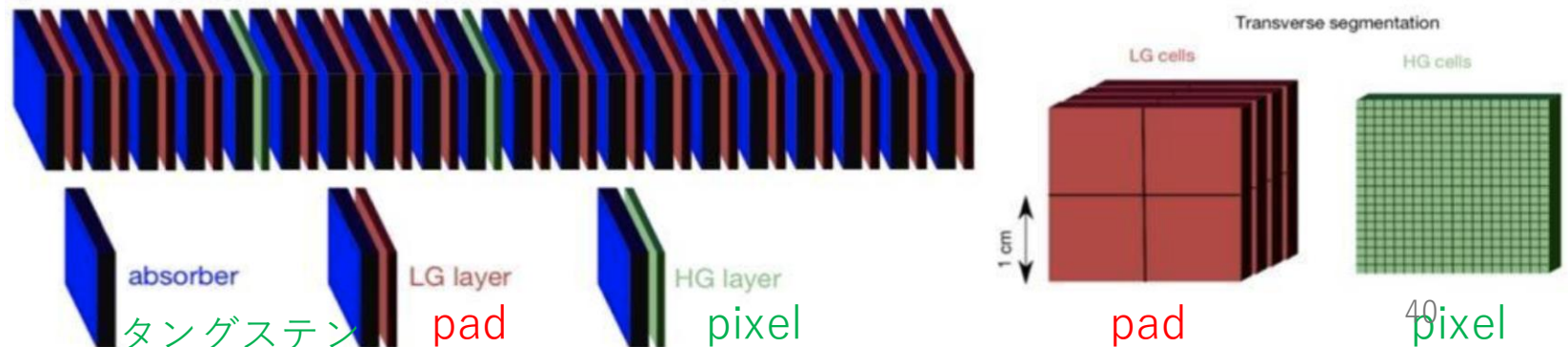
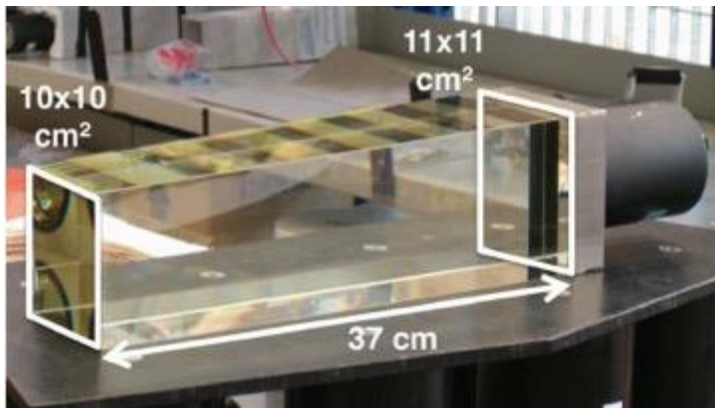


Calorimeter System

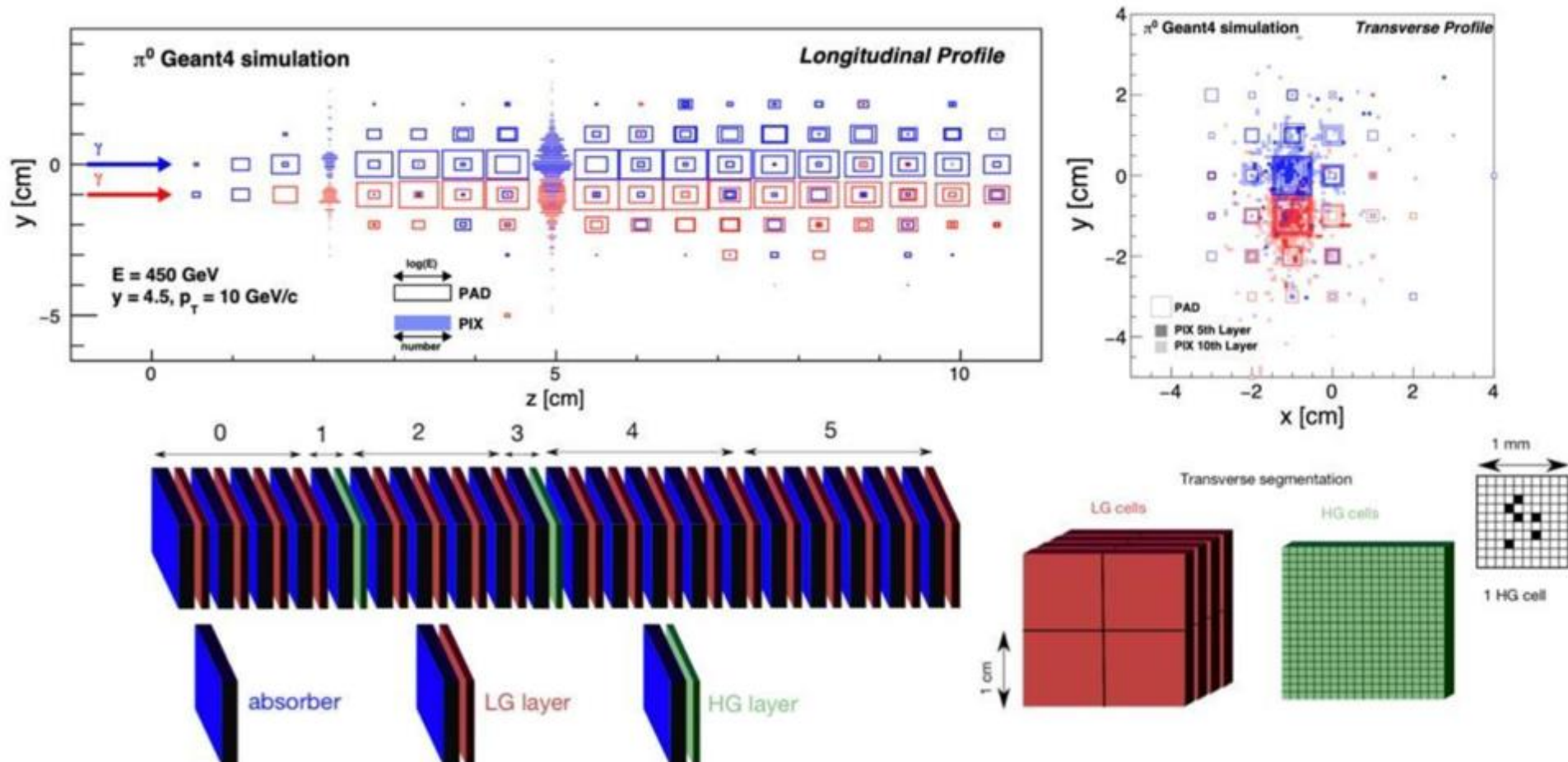
Calorimeters



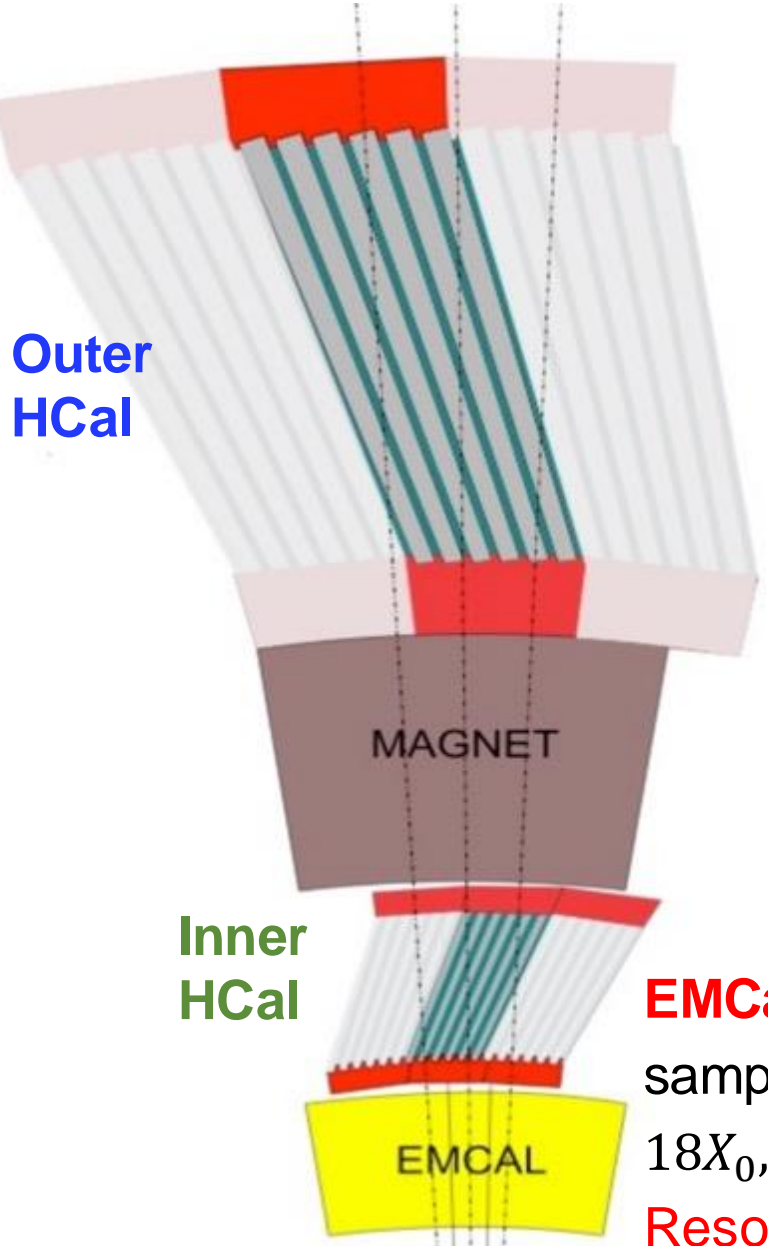
- Total absorption Type
 - High energy resolution
 - Low position resolution
 - Pb-Glass, etc.
- Sampling Type
 - High position resolution as a trade off of lower energy resolution
 - Pb, W, Fe... as absorber
 - Sensors
 - Scintillation fibers, silicon sensors, etc
 - Pixel sensors for shower max



Sampling Type Calorimeters



sPHENIX Calorimeters



Outer
HCal

Inner
HCal

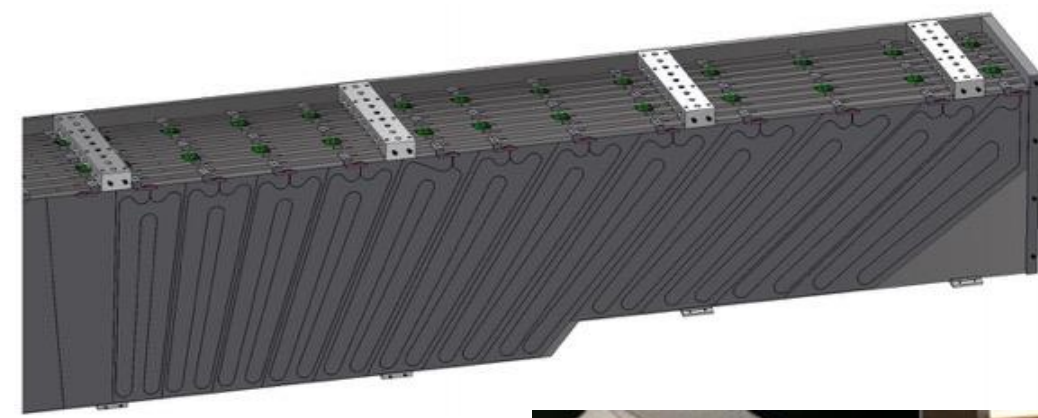
MAGNET

EMCAL

Outer HCal: Steel absorber plates and scintillating tiles with embedded WLS fibers

Inner HCal: Al absorber plates and scintillating tiles with embedded WLS fibers

Resolution $\sim 88\%/\sqrt{E} \oplus 12\%$ (single particle) for overall HCal.



EMCal: Tungsten-scintillating fiber sampling calorimeter (SPACAL type).

$18X_0, 1\lambda, \Delta\eta \times \Delta\phi = 0.025 \times 0.025$

Resolution $\sim 16\%/\sqrt{E} \oplus 5\%$.



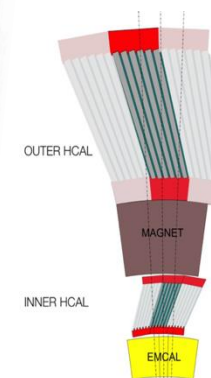
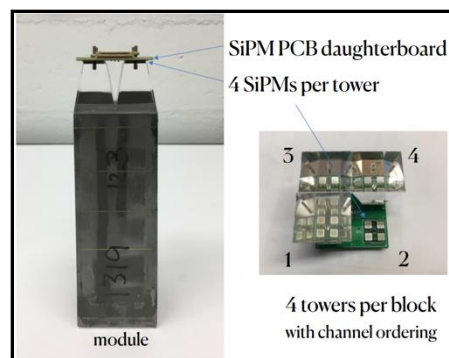
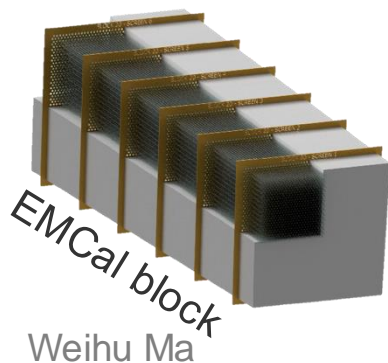
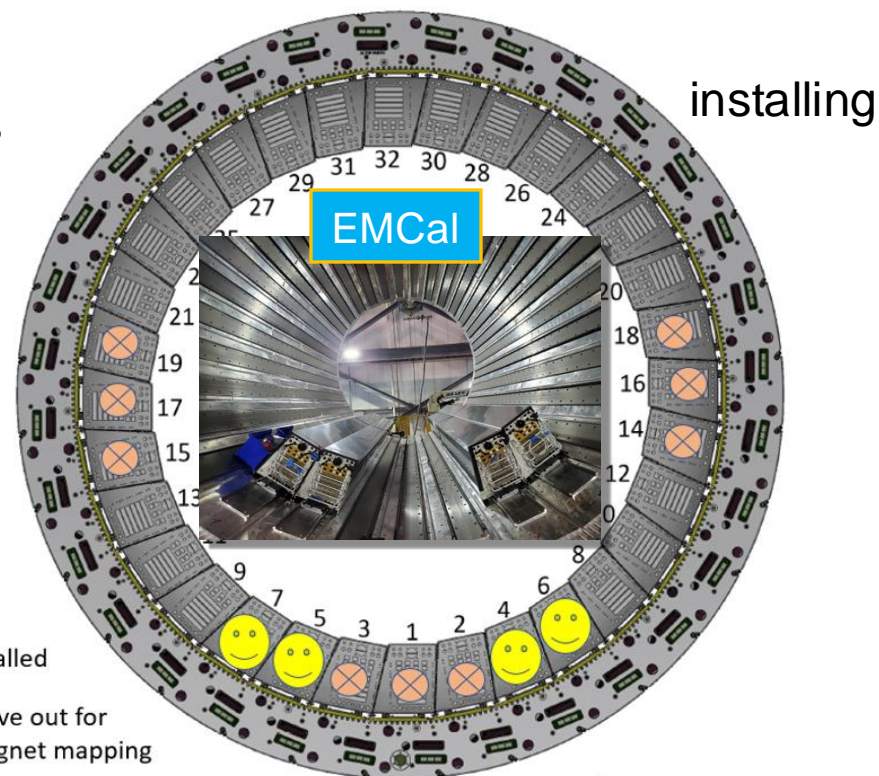
Electromagnetic Calorimeter (EMCal)

Calorimeter System(EMCal+iHCal+ oHCal)

- ✓ Compact, hermetic, near-projective sampling calorimeters
- ✓ Coverage $|\eta| < 1.1$, 2π in ϕ
- ✓ SiPM readout for both EMCal and HCal
- ✓ Less-biased jet measurement
- ✓ All Calorimeter electronics complete!

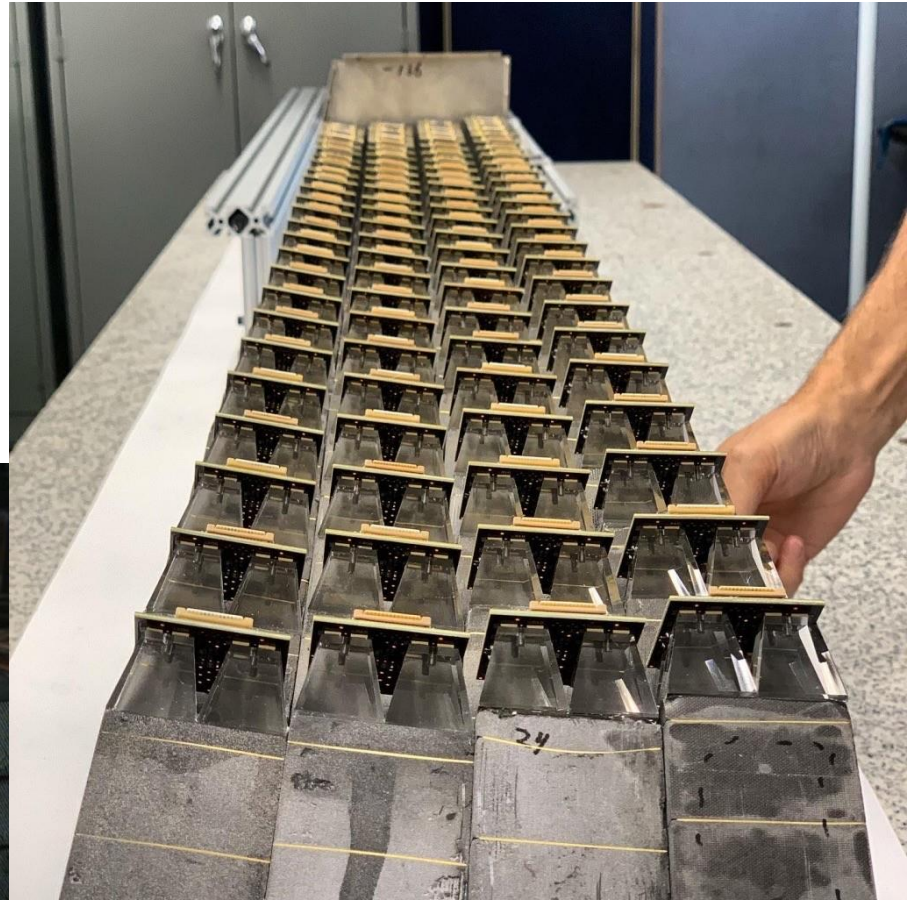
Electromagnetic Calorimeter (EMCal)

- ✓ Tungsten/scintillating fiber SPACAL
- ✓ $\sim 7\text{mm}$ radiation length
- ✓ $\Delta\eta \times \Delta\phi = 0.025 \times 0.025$
- ✓ Good energy resolution $\sigma_E/E \leq 16\%/\sqrt{E}$
- ✓ Sector Installation underway 10/64



sPHENIX EMCal

59



sPHENIX EM calorimeter

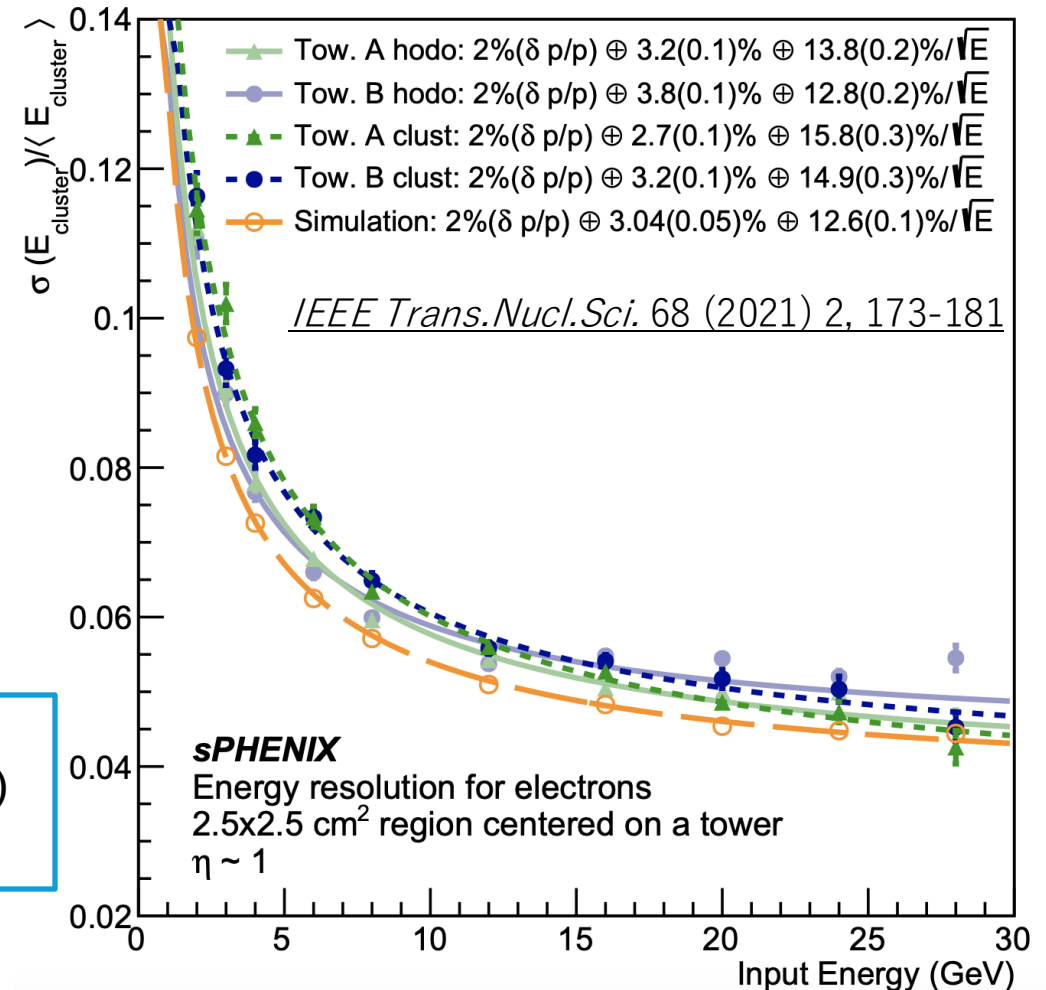
Full calorimeter covers 2π in azimuth
and $|\eta| < 1.1$

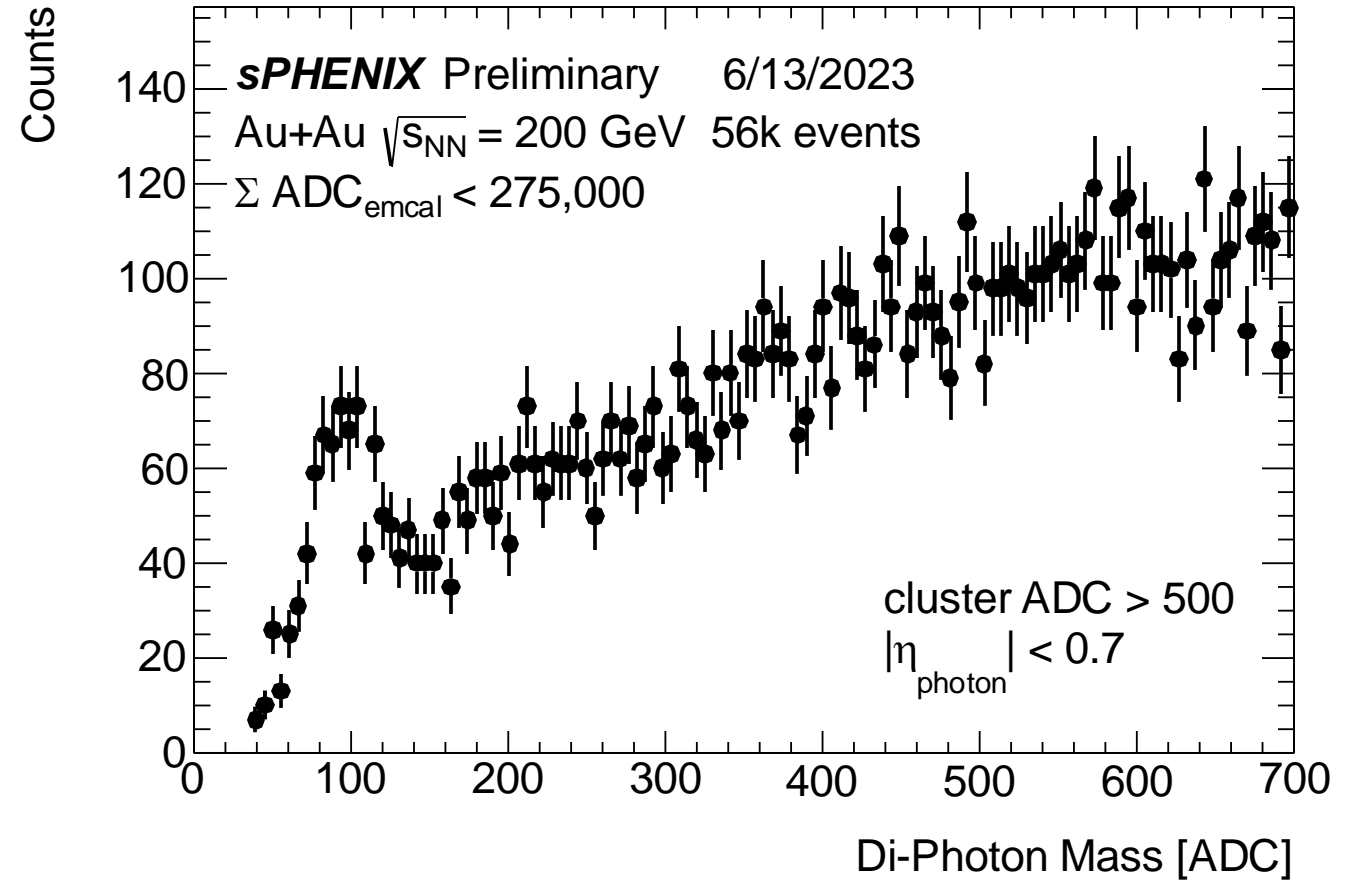
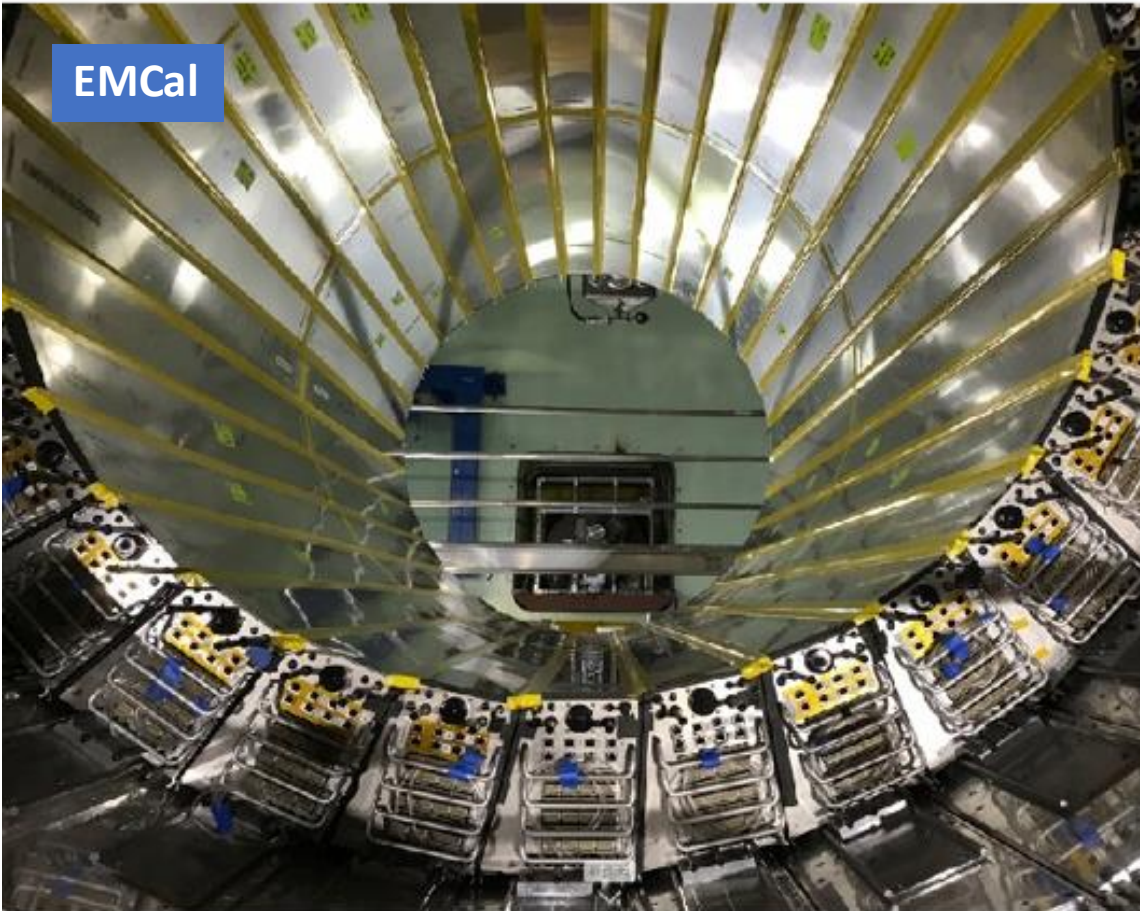
EMCal:

- Sampling calorimeter of scintillating fibers embedded in tungsten blocks
- $\Delta\eta \times \Delta\phi = 0.025 \times 0.025$ towers



Block production
finished at UIUC (80%)
& Fudan/PKU/CIAE
(20%)



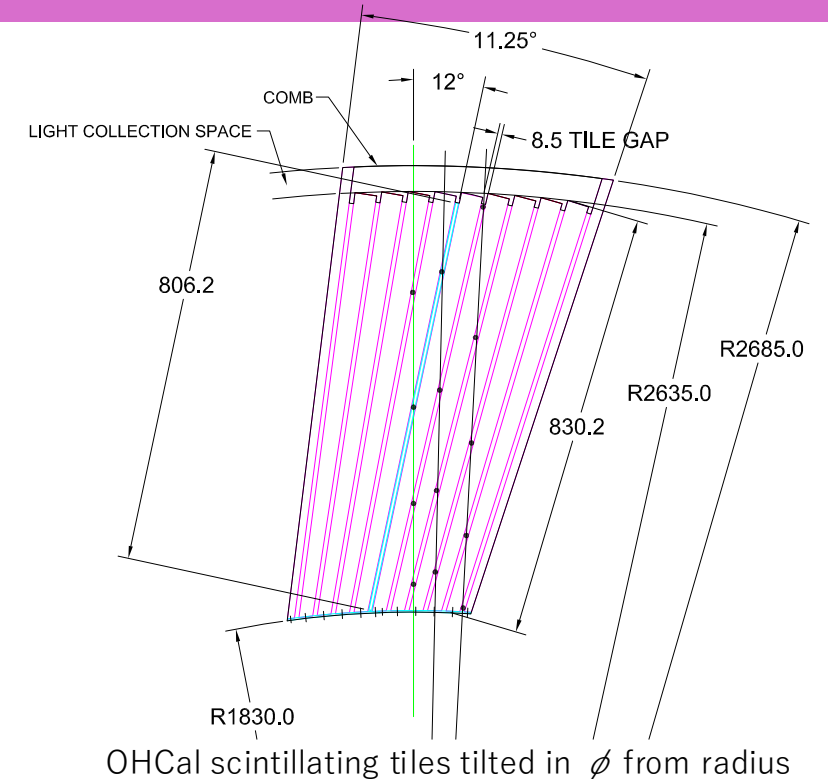
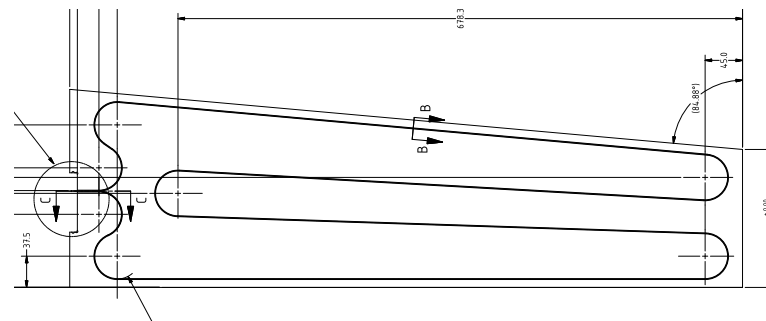
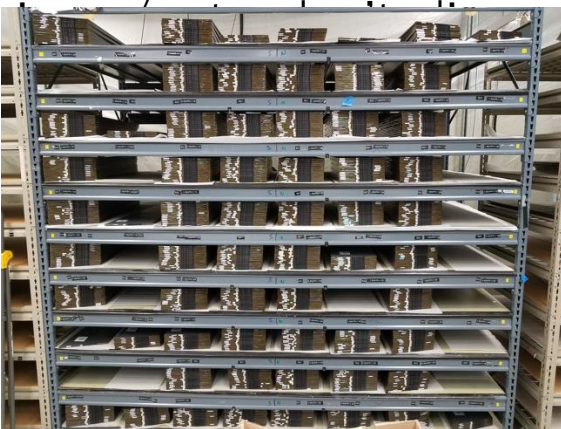
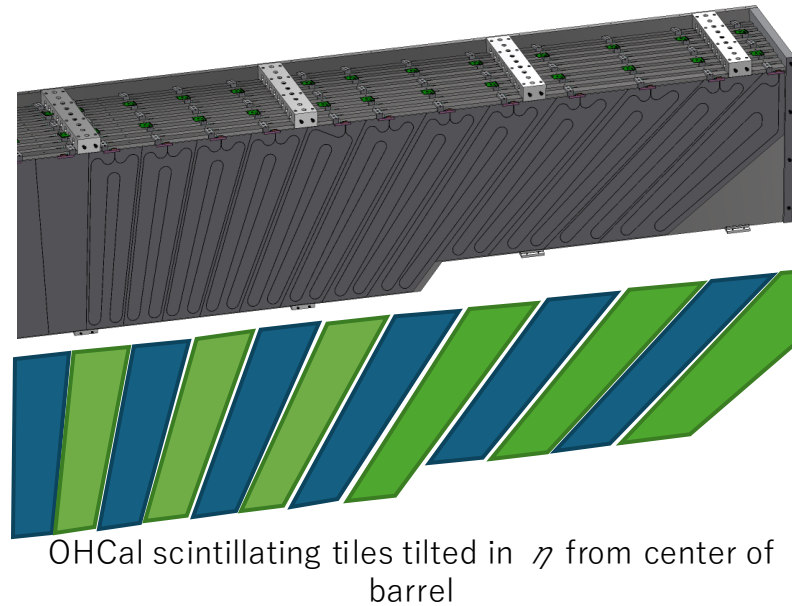


Di-photon mass distribution shows expected π^0 peak

What the HCal is

Tiles, Segmentation, and Tilt

- Fanning out radially from nominal collision vertex
- tilted away from radius so that a radial particle would go through multiple tiles/sector
- Tilt in phi is different for inner/outer
- Sector boundaries between



What the HCal is

Assembly pictures

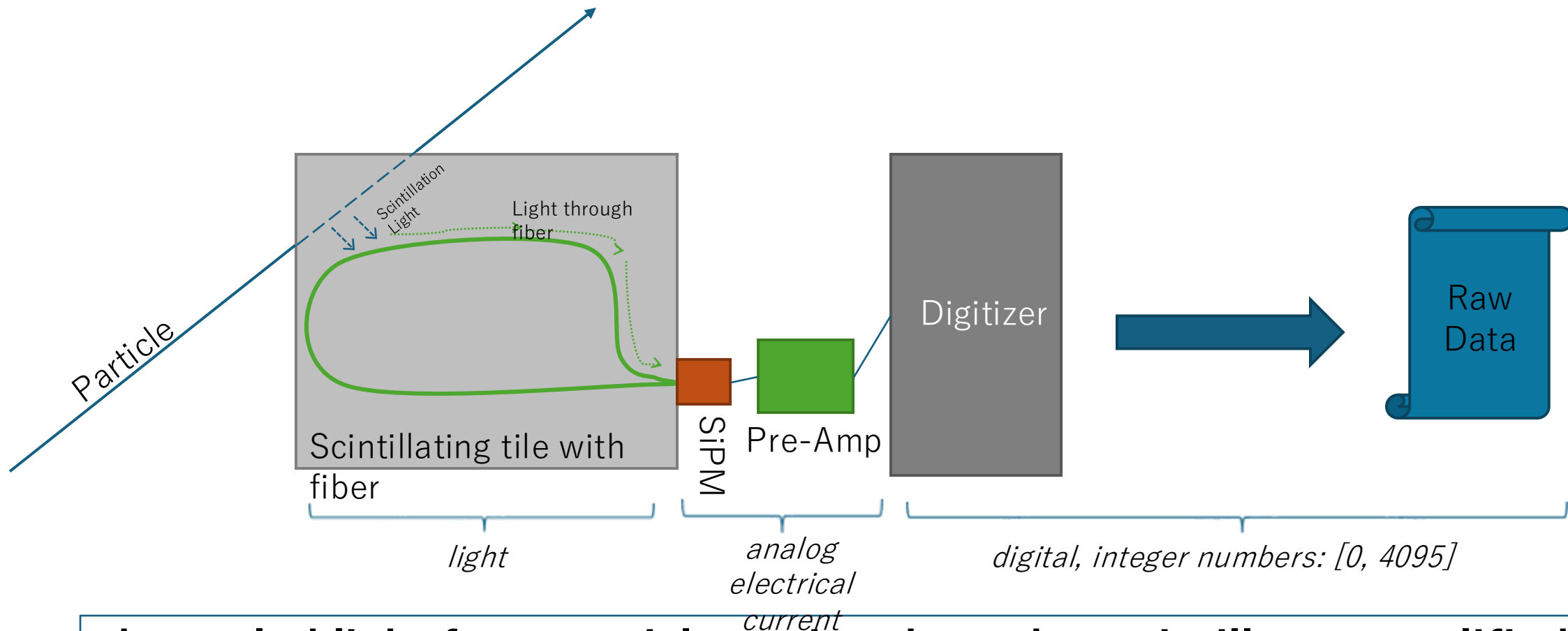


Schematic & Channel

Numbering								South Half								North Half							
2	0	6	4	1	8	1	1																
3	1	7	5	0	9	4	2																
				1																			
South Channel Block (Third)								Middle Channel Block (Third)								North Channel Block (Third)							

See Back-Up Slide 47: These channels match the scheme in the South Channel Block, but are different for the PHENIX HBDs and the sPHENIX electronics

What the HCal measures



channeled light from particles going through a scintillator, amplified and digitized

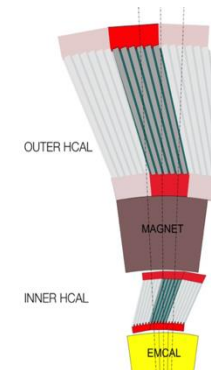
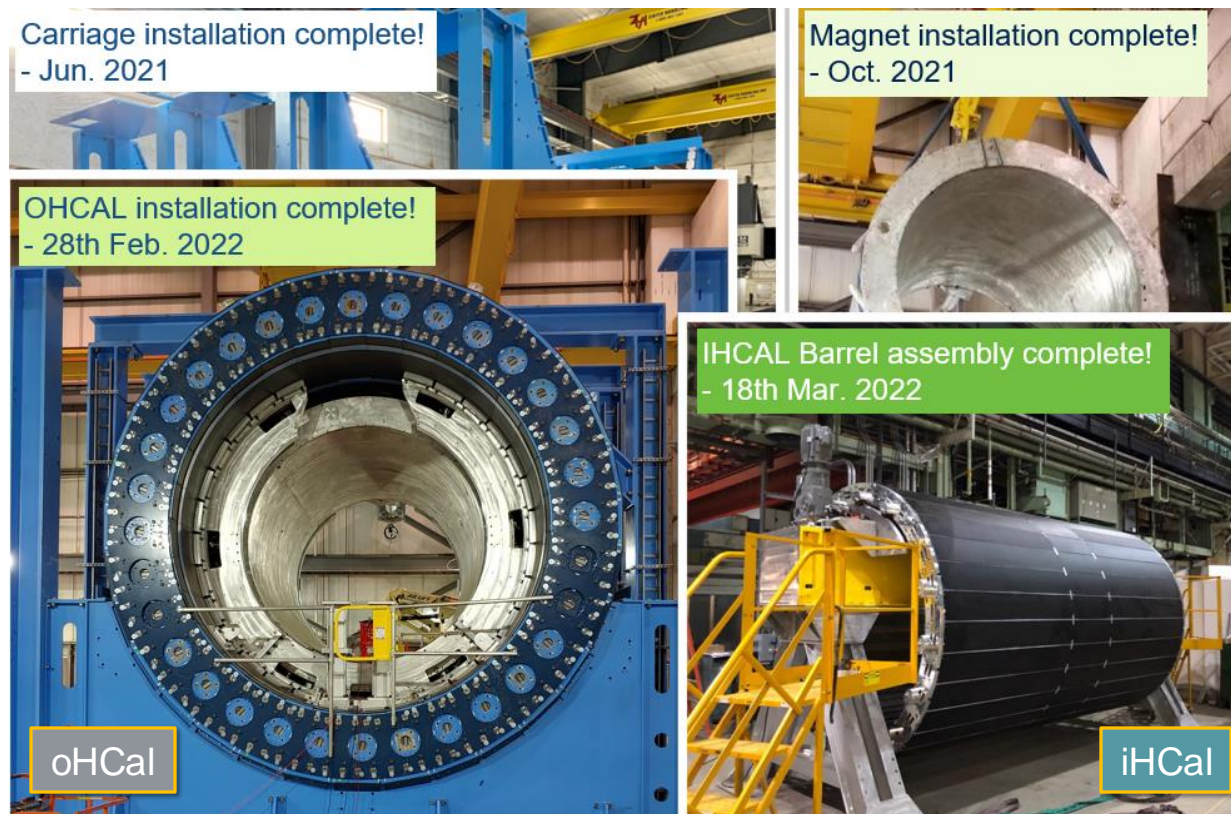
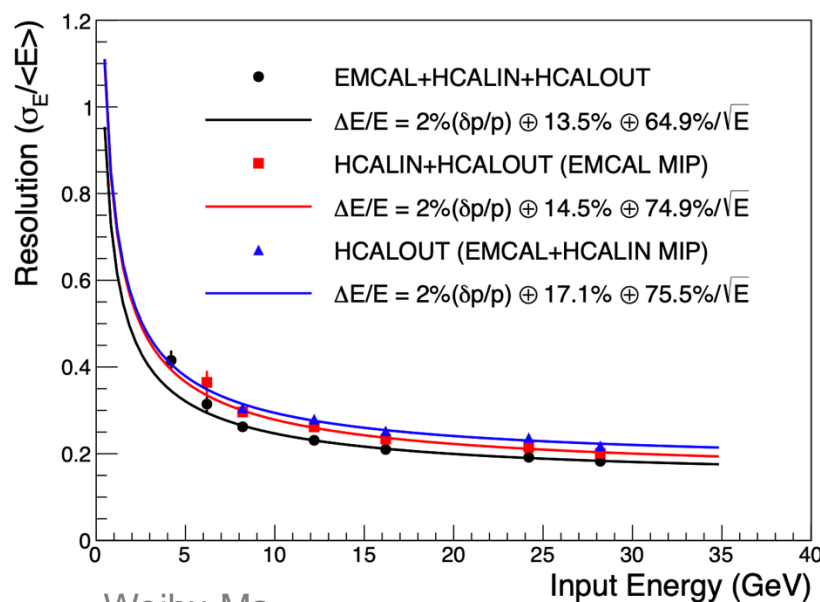
Hadronic Calorimeter (HCal)

Inner Hadronic Calorimeter (iHCAL)

- ✓ Aluminum-scintillating tiles with embedded WLS fibers

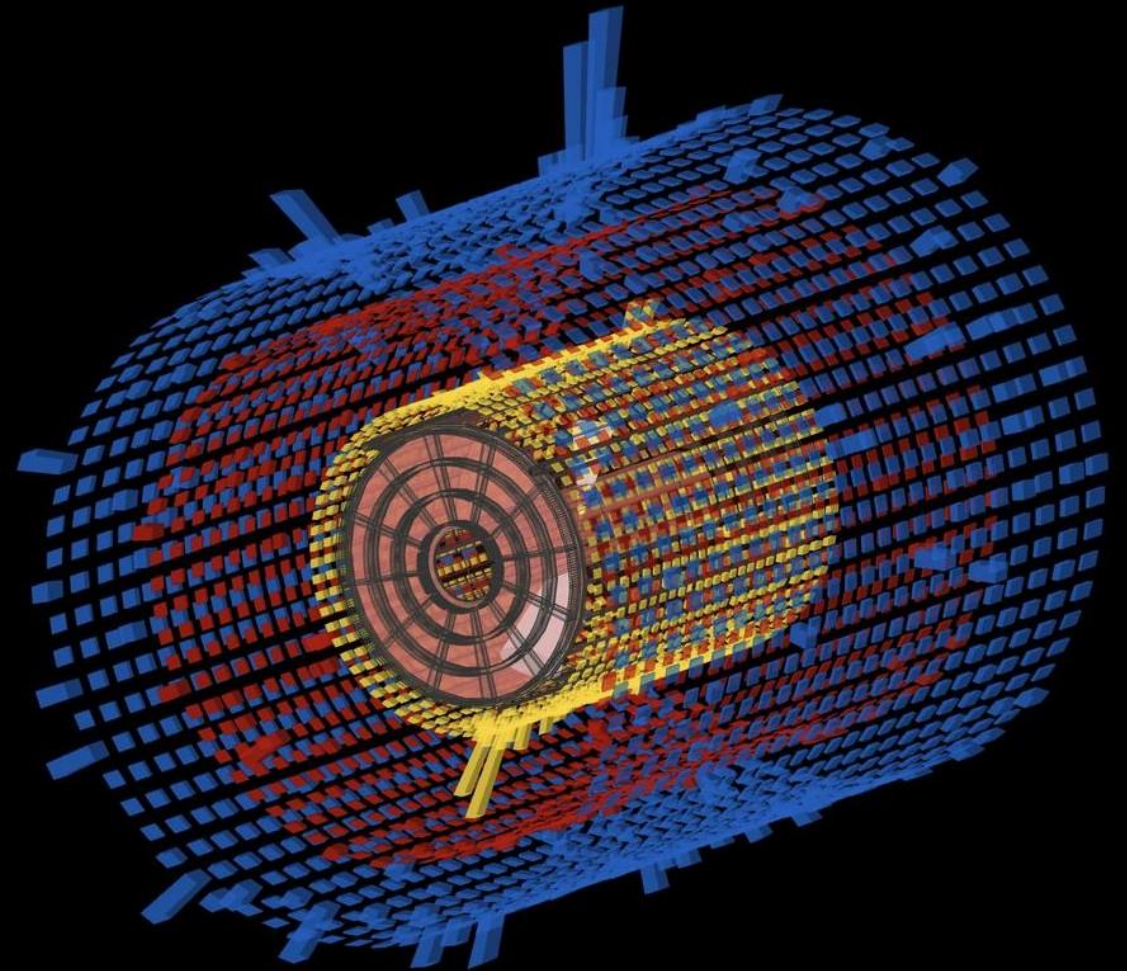
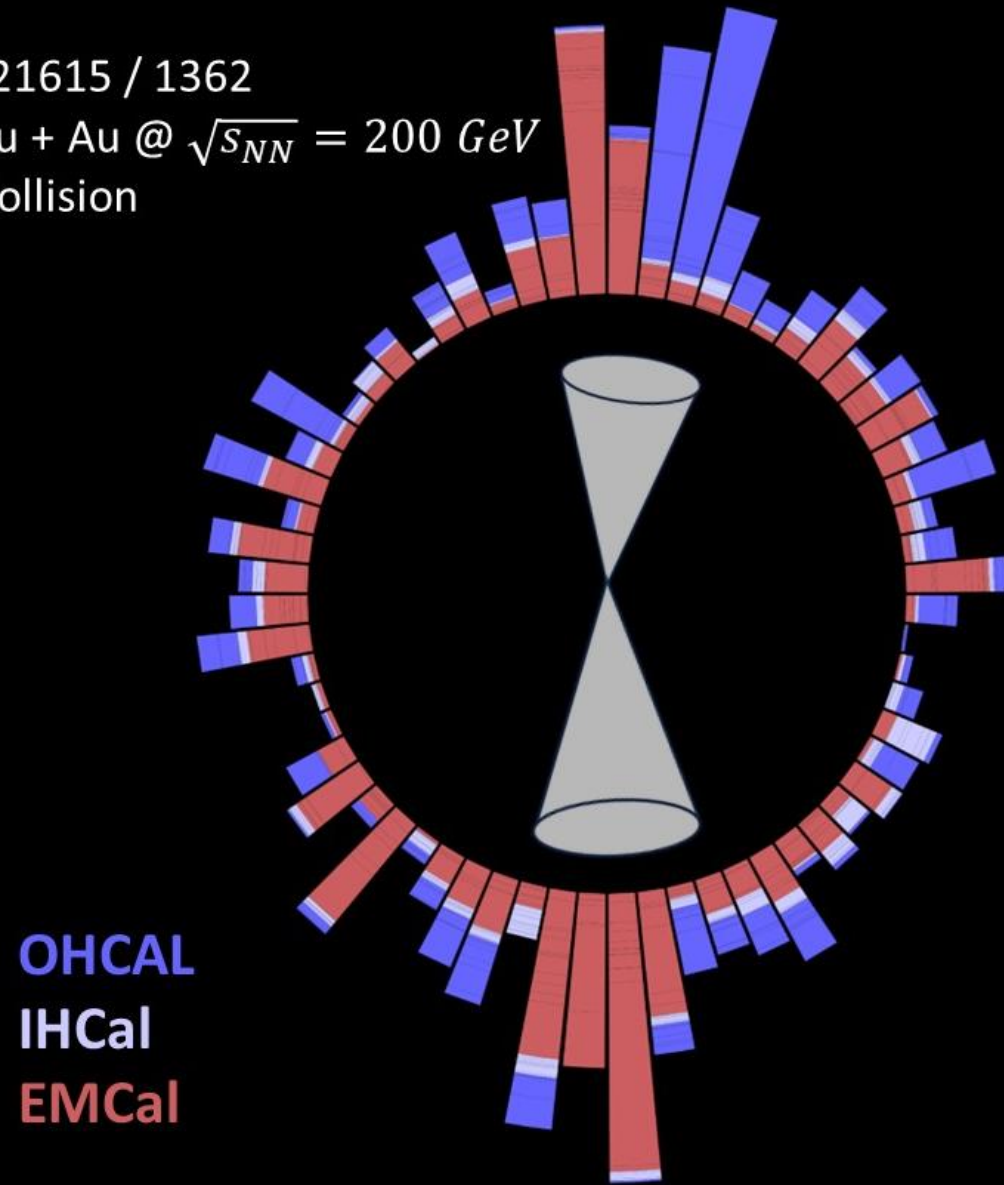
Outer Hadronic Calorimeter (oHCAL)

- ✓ Tilted steel plates/scintillator tiles with embedded WLS fibers
- ✓ $\Delta\eta \times \Delta\phi = 0.1 \times 0.1$ towers
- ✓ Installation complete!



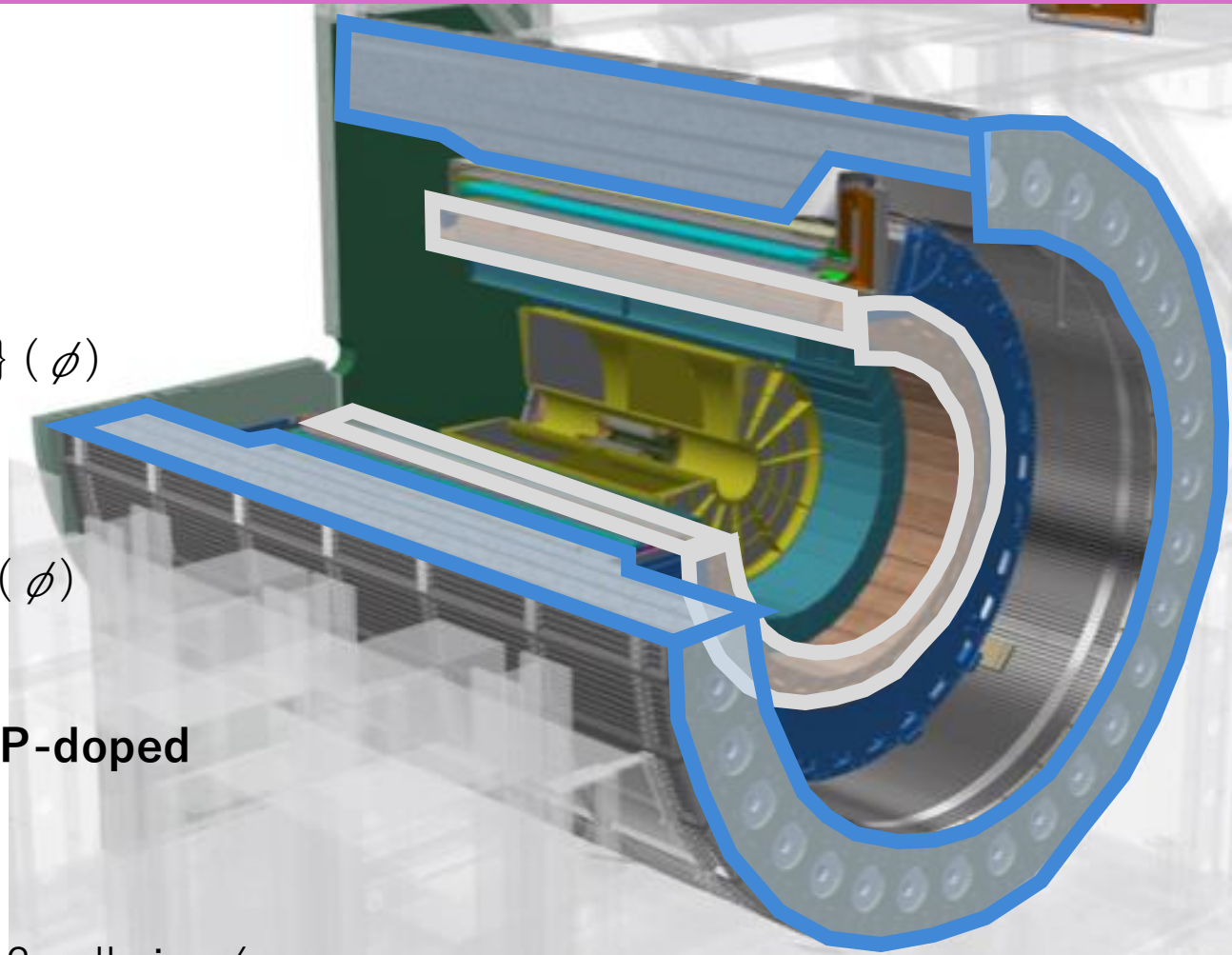
Dijet Event in Run 2023 Au+Au Data

sPHENIX
Run/Event: 21615 / 1362
Collisions: Au + Au @ $\sqrt{s_{NN}} = 200 \text{ GeV}$
Peripheral Collision



What the HCal is

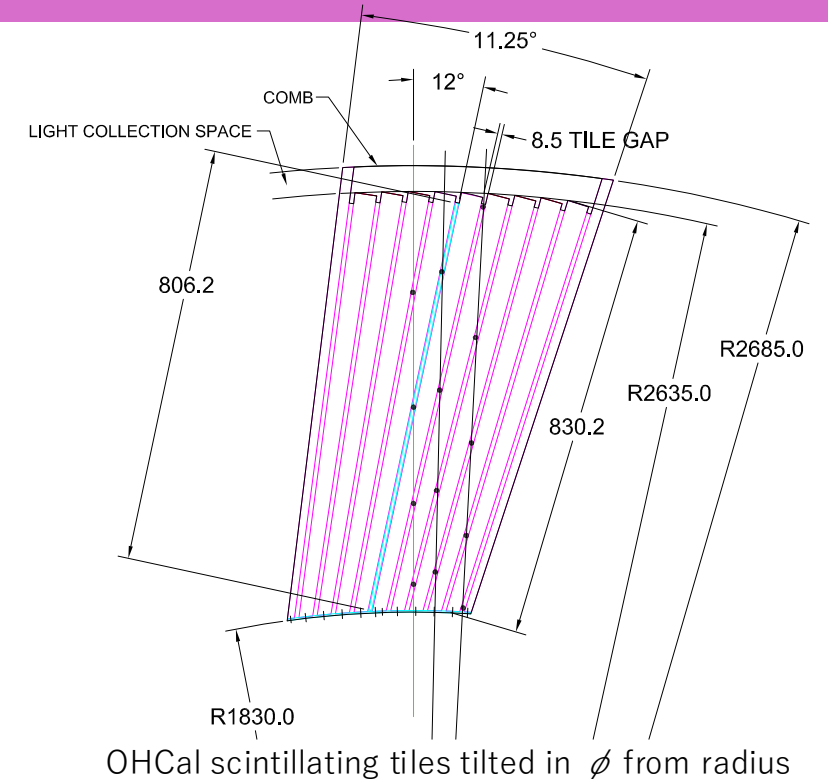
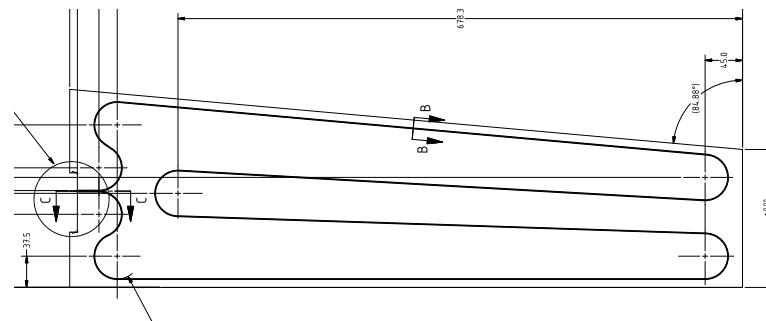
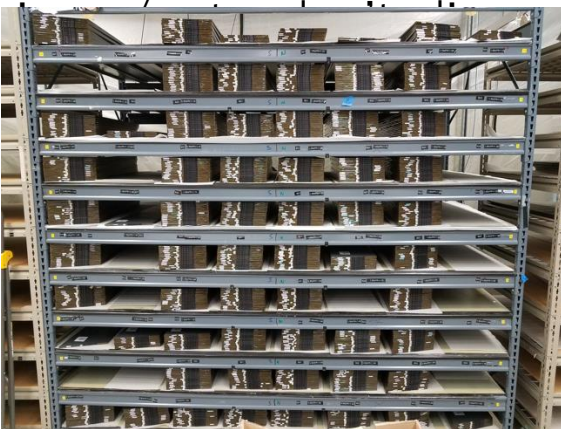
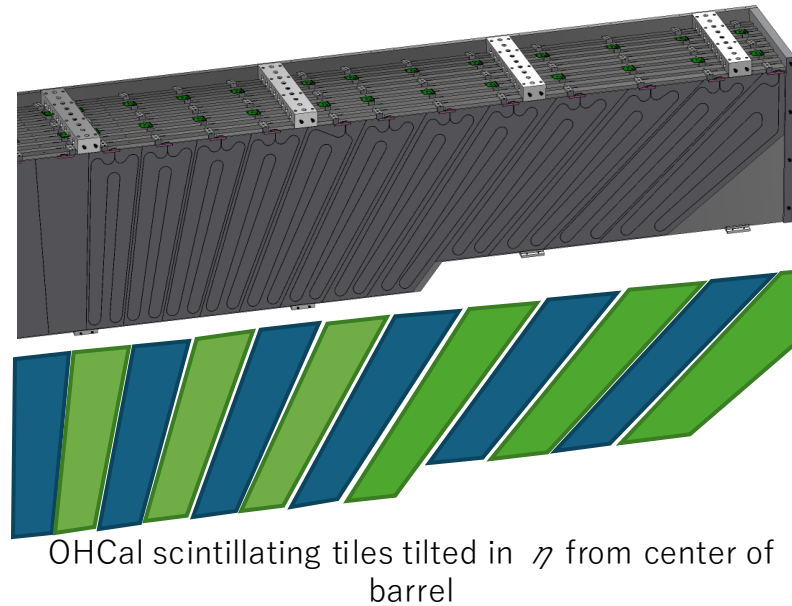
- **Acceptance**
 - $-1.1 < \eta < 1.1$
 - $0 \leq \phi < 2\pi$
- **Details**
 - OHCaI
 - **low-carbon, magnet steel absorber**
 - $7.22\text{m} (z) \times 0.865\text{m} (r) \times \{0.357\text{ m}, 0.527\text{m}\} (\phi)$
 - $12,105.5\text{ kg} \times 32\text{ modules (sectors)}$
 - IHCaI
 - **aluminum absorber**
 - $4.35\text{m} (z) \times 0.235\text{m} (r) \times \{0.223\text{ m}, 0.27\text{m}\} (\phi)$
 - $907.2\text{ kg} \times 32\text{ modules (sectors)}$
- **Sampling detector**
 - **7,680 (O) + 6,144 (I) scintillating tiles (POPOP-doped polystyrene)**
 - tapered, tilted metal plates
 - **Arrangement of each sector**
 - 5 (O) or 4 (I) tiles per cell, 24 cells in η by 2 cells in ϕ
 - **Segmentation: $\Delta \eta / \eta_{\text{total}} \sim 0.1, \Delta \phi / 2\pi = 0.1$**



What the HCal is

Tiles, Segmentation, and Tilt

- Fanning out radially from nominal collision vertex
- tilted away from radius so that a radial particle would go through multiple tiles/sector
- Tilt in phi is different for inner/outer
- Sector boundaries between



What the HCal is

Assembly pictures

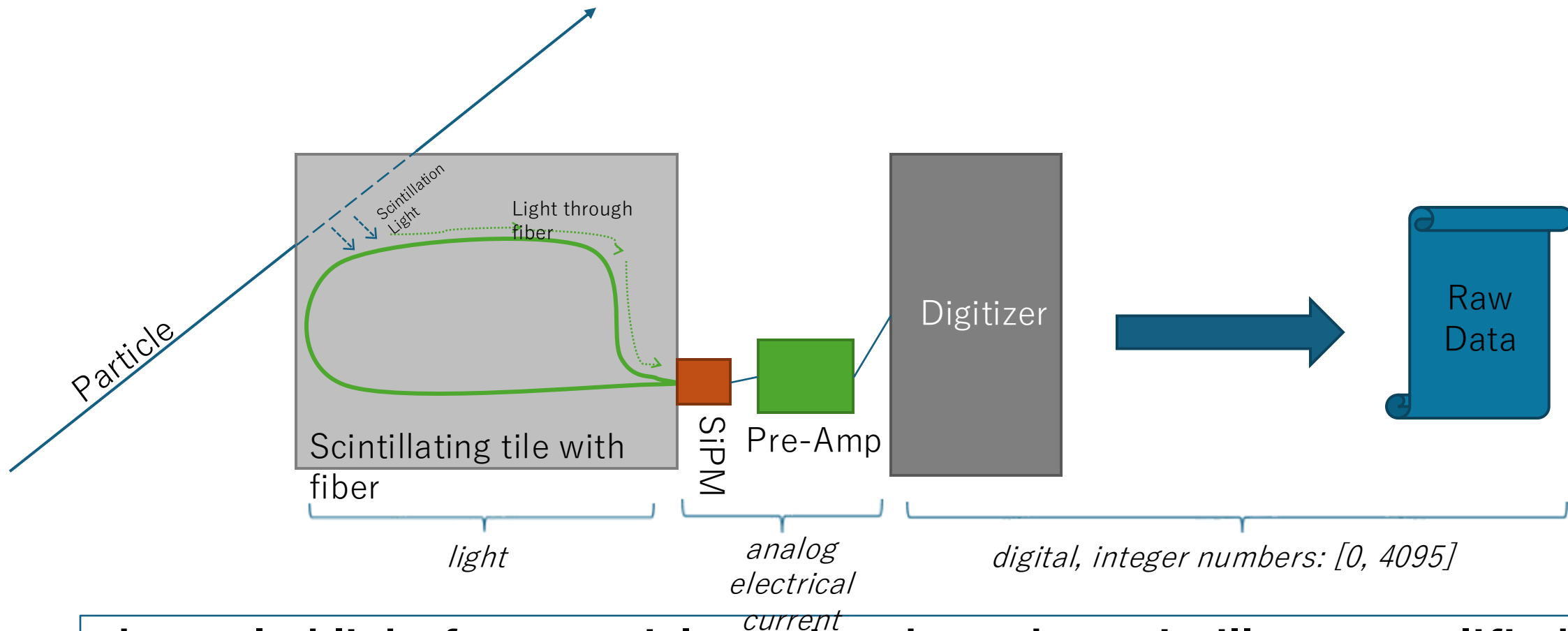


Schematic & Channel

Numbering								South Half												North Half															
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								1												5															
South Channel Block (Third)								Middle Channel Block (Third)												North Channel Block (Third)															

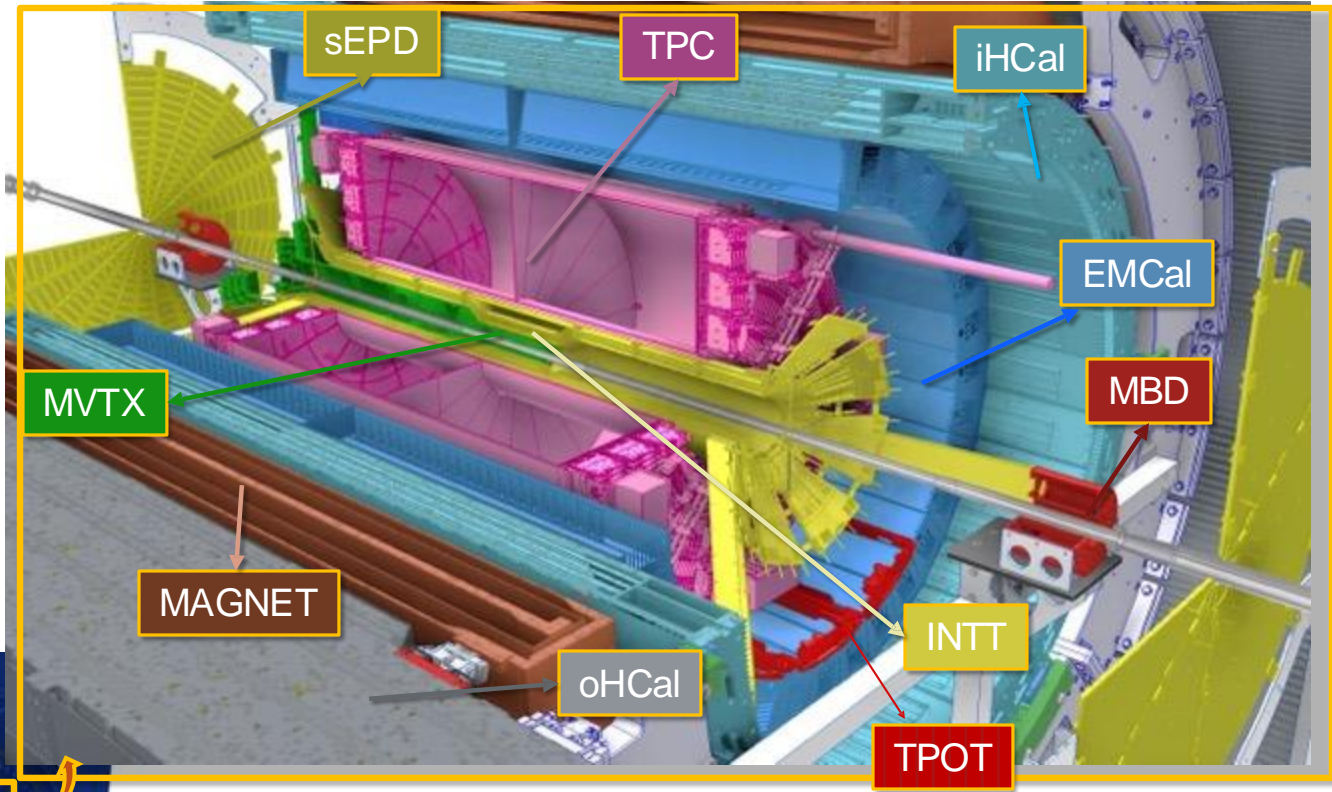
See Back-Up Slide 47: These channels match the scheme in the South Channel Block, but are different for the PHENIX HBDs and the sPHENIX electronics

What the HCal measures

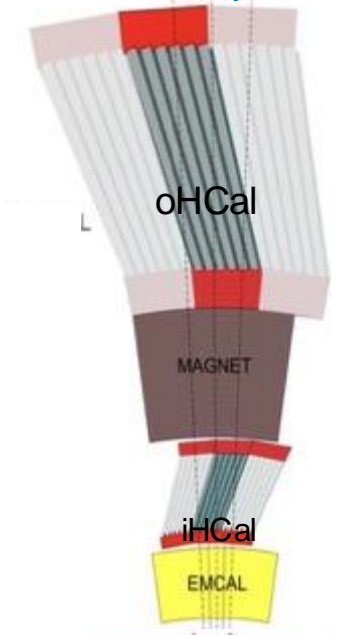


channeled light from particles going through a scintillator, amplified and digi

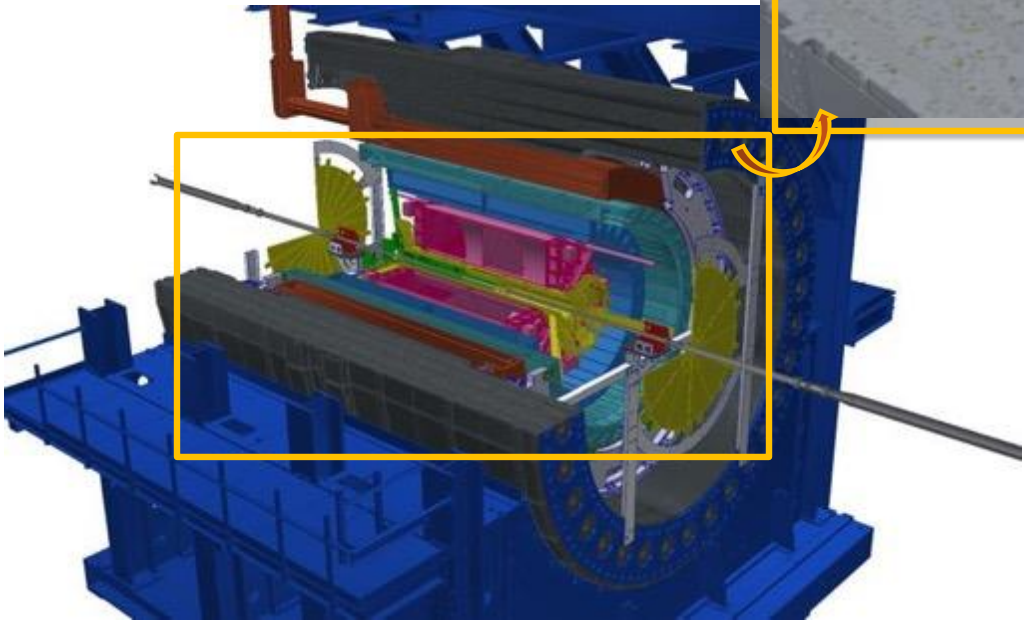
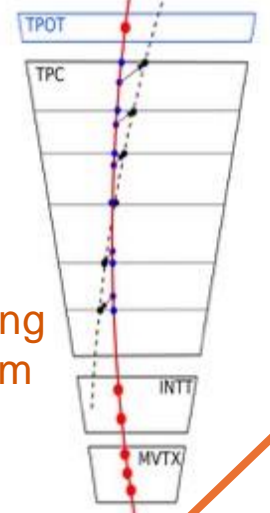
sPHENIX FORWARD Detector



Calorimeter system

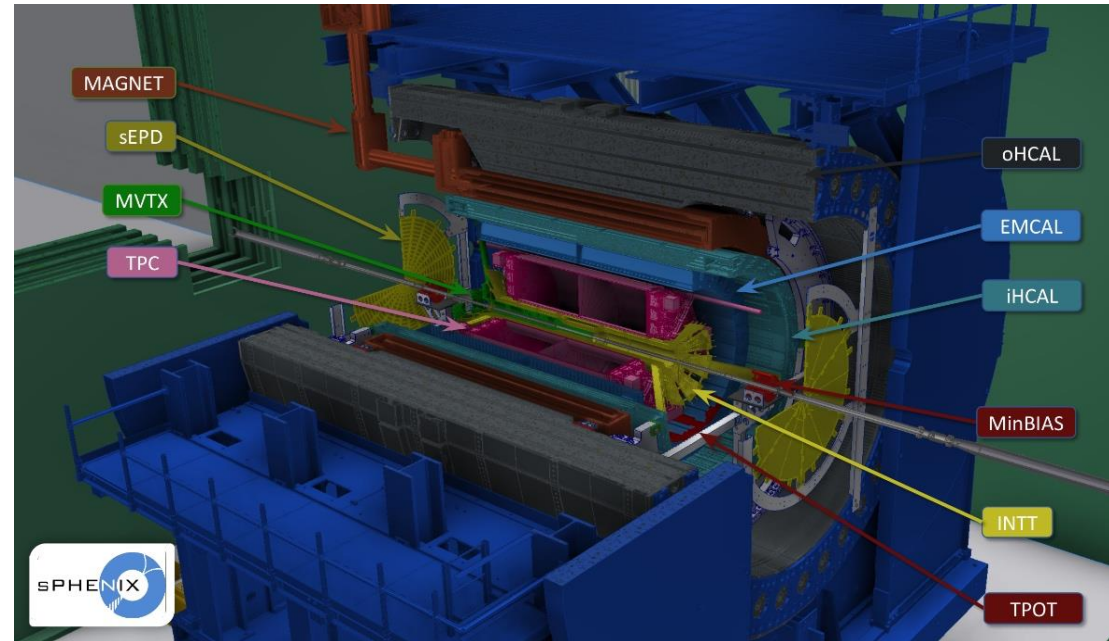
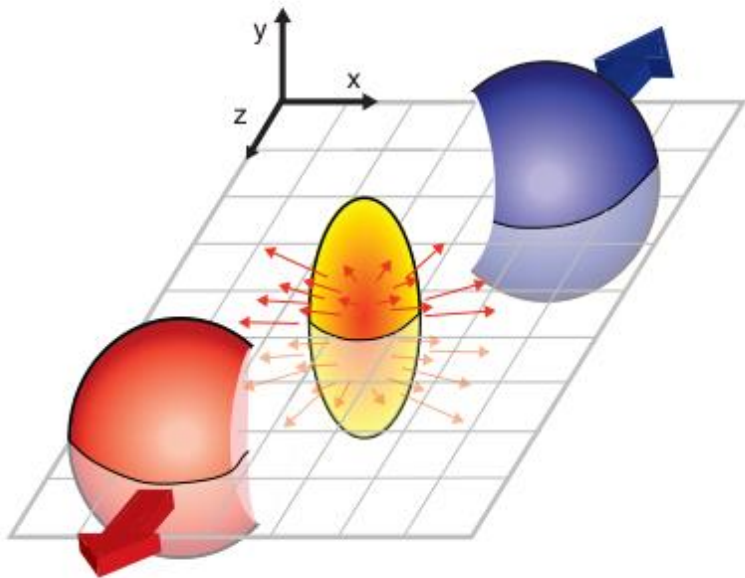


Tracking system

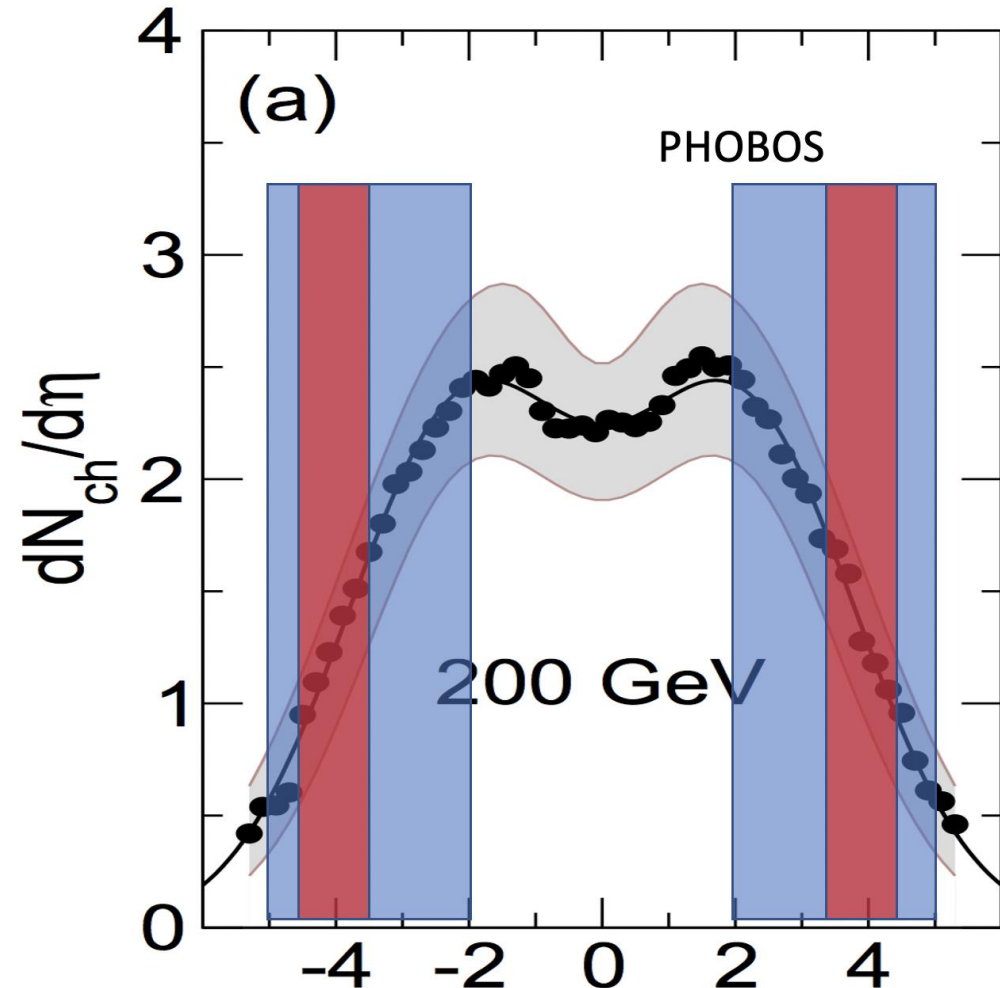


sPHENIX Event Plane Detector (sEPD)

Built to determine the collision geometry → Impact Parameter

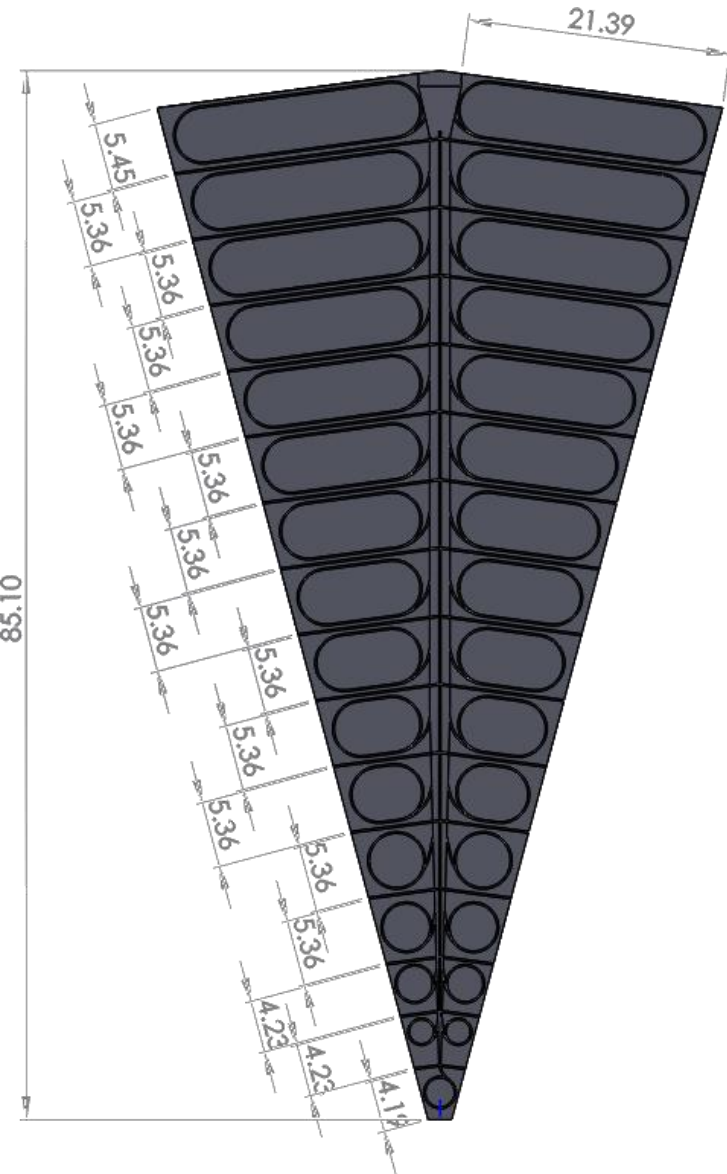


Forward Particle Distributions



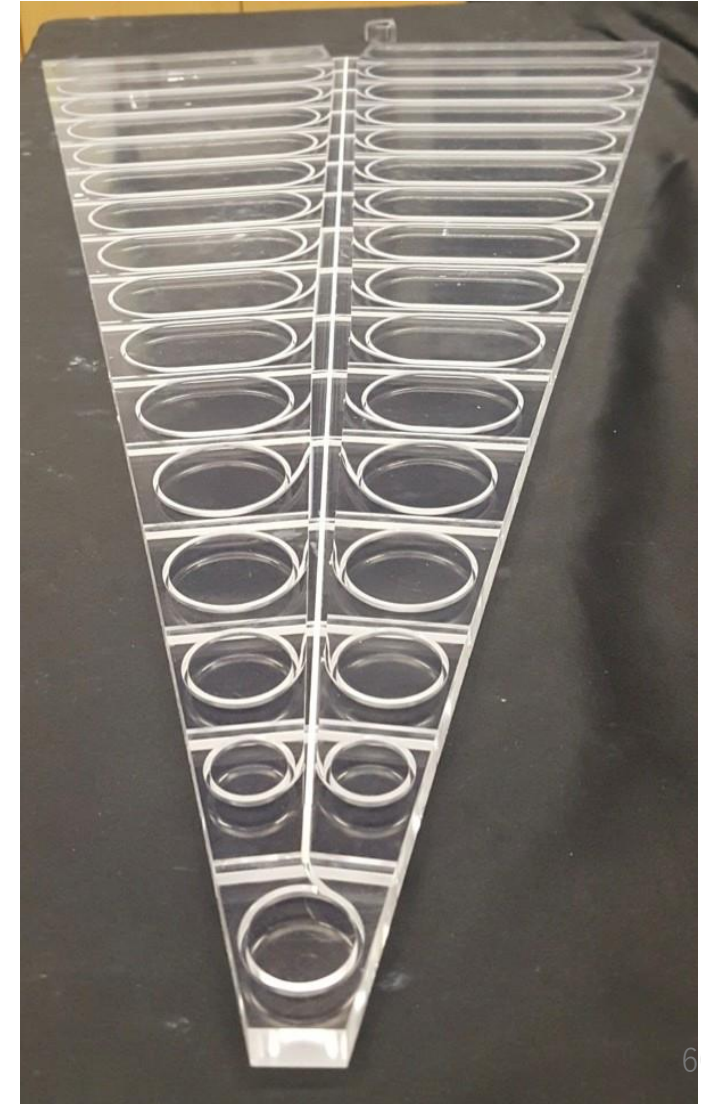
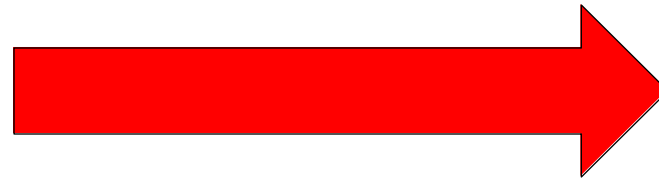
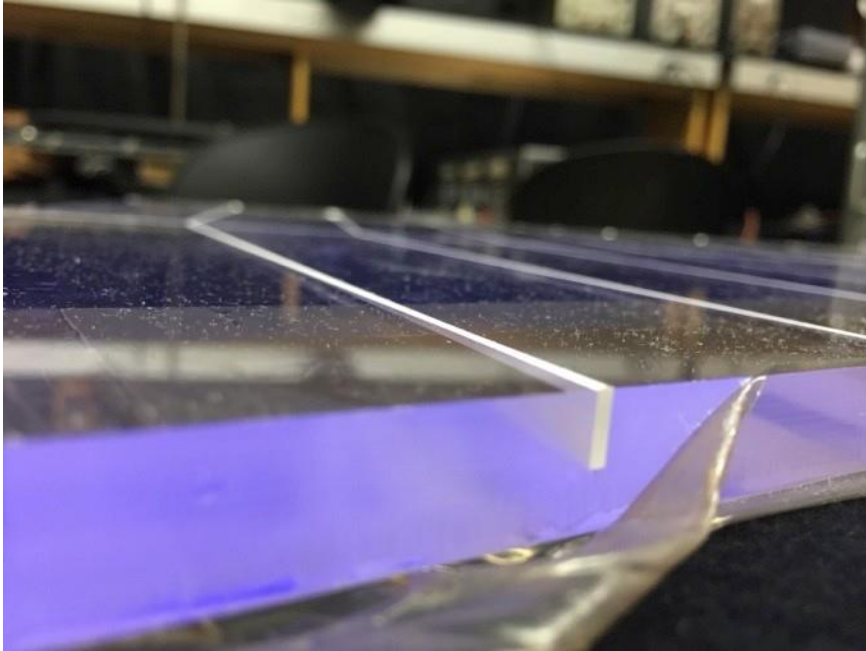
- **sEPD** $2.0 < |\eta| < 4.9$
- **MBD**: $3.51 < |\eta| < 4.61$
- Large acceptance with azimuthal symmetry with h gap from mid-rapidity is very useful for many analyses
 - Especially important for small systems

Sector Design



- 2 Wheels of 12 sectors with 31 optically-isolated tiles
 - **1.2-cm-thick scintillator**
- Total of $12 \times 31 \times 2 = 744$ channels
- $R_{\text{outer}} = 0.9 \text{ m}$, $R_{\text{inner}} = 4.6 \text{ cm}$
- Planned location of $\sim z = 319 \text{ cm}$
 - **$2.0 < |\eta| < 4.9$**
 - STAR: 375 cm ($2.1 < |\eta| < 5.1$)
 - PHENIX BBC: ($3.1 < |\eta| < 3.9$)
 - sPHENIX MBD: 250 cm ($3.51 < |\eta| < 4.61$)
- Wavelength shifting fibers (3x loops) glued into tiles
- Machined out of a single piece of scintillator

Isolation Grooves

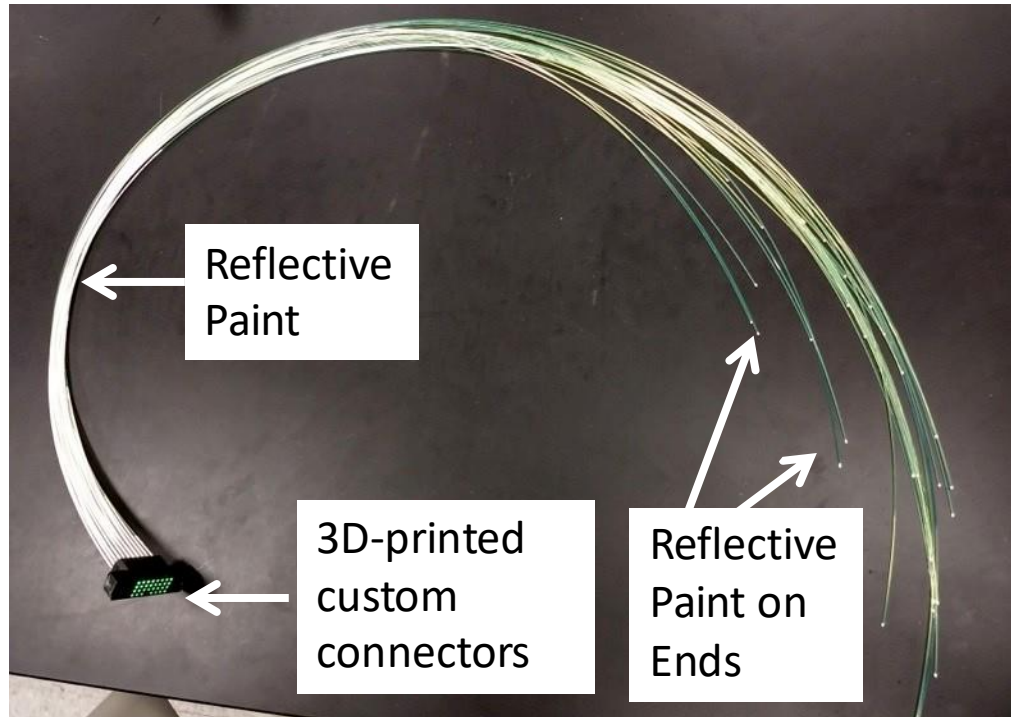


Mill “half-way” and fill grooves with TiO_2 + epoxy mixture (reflective epoxy)

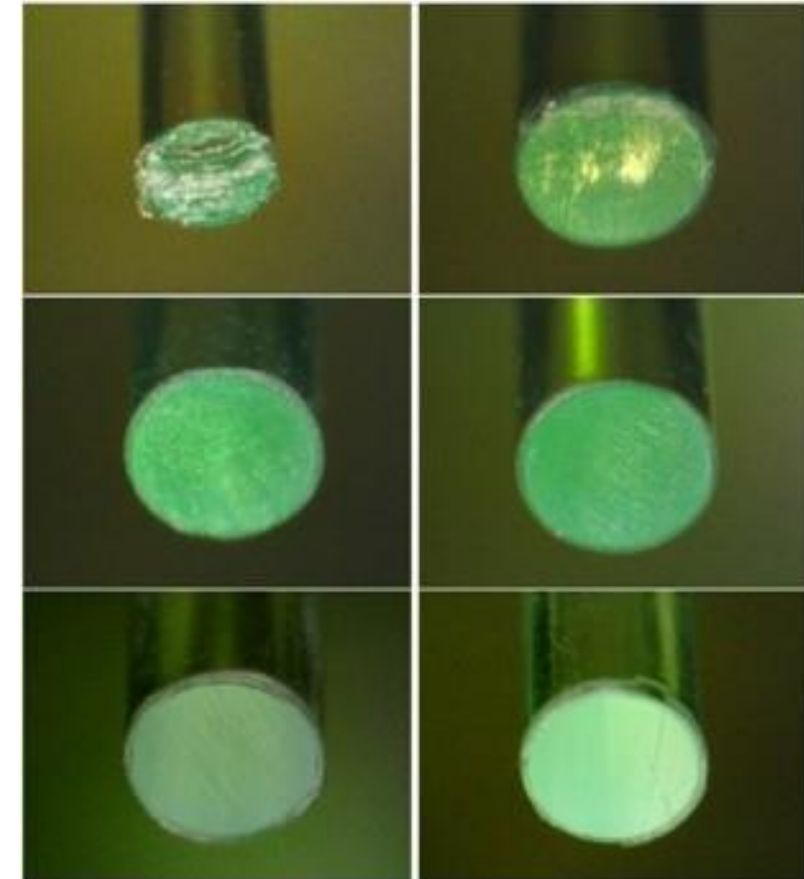
- **Optical isolation!**

Flip over and finish milling the grooves + Fiber channels

WLS Fiber Preparation



Connectors polished prior to gluing, inserts for panel screws

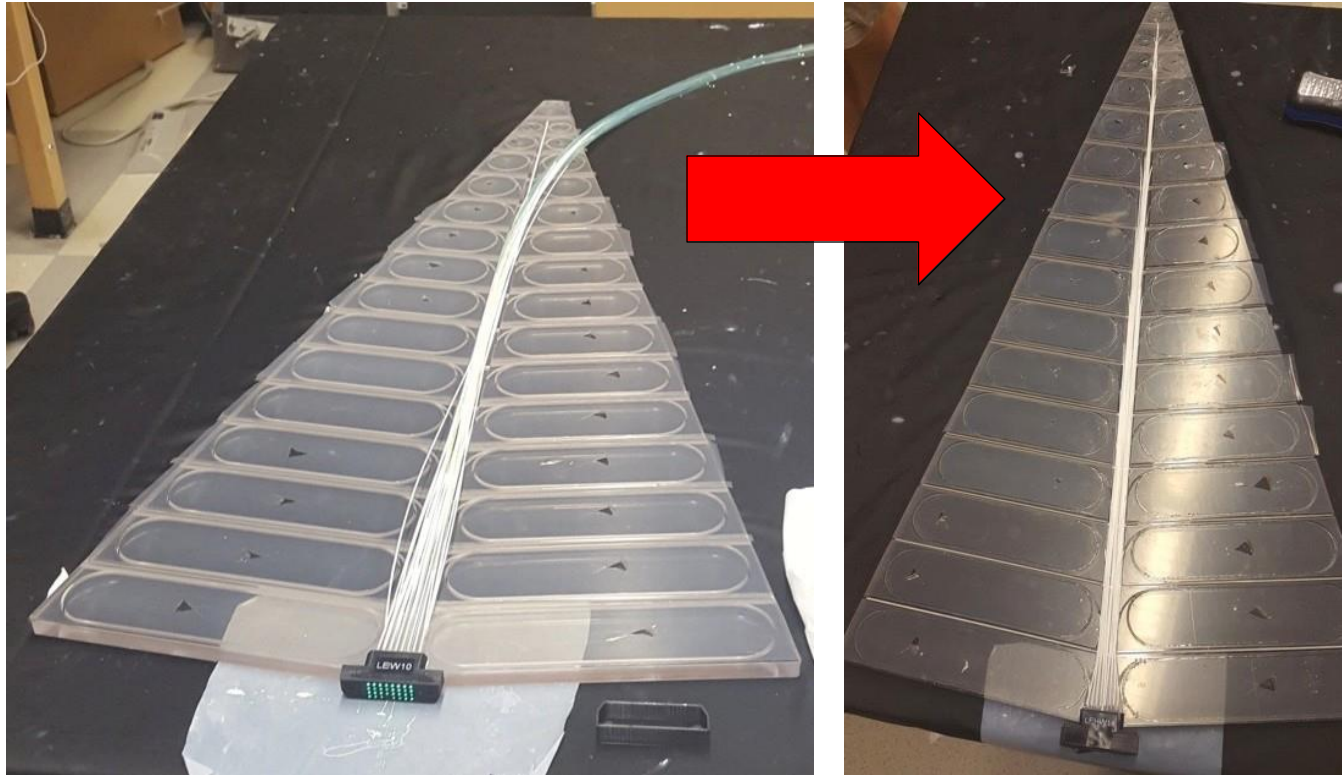


Reflective paint for “Central Channel”

- **Decreases cross-talk**

Fiber ends painted → Increases light yield by ~30-50%

sEPD Sector Construction

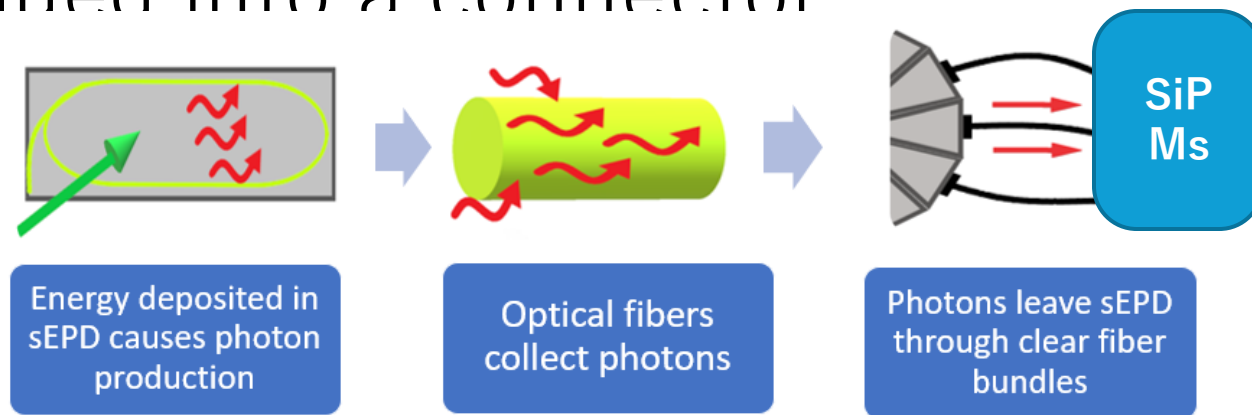


Optical Isolation is important!
Sectors will be checked after construction

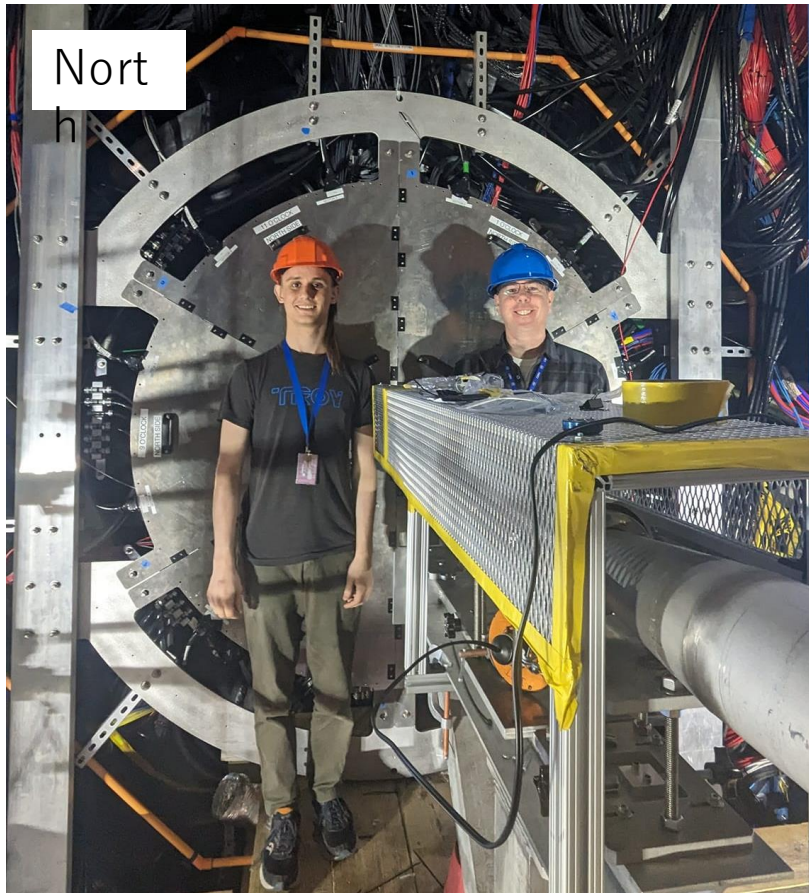
- Connector glued into place (reflective epoxy), then fibers (optical epoxy)
- Central channel and front grooves filled with reflective epoxy
- Tape removed and scintillator polished

Clear Fiber Bundles

- Purpose: carry signal to the electronics
- Clear fibers were cut to a length of 6.8 meters
- The fibers were put into thick tubing measuring 4.4 meters
- Fibers glued into a connector

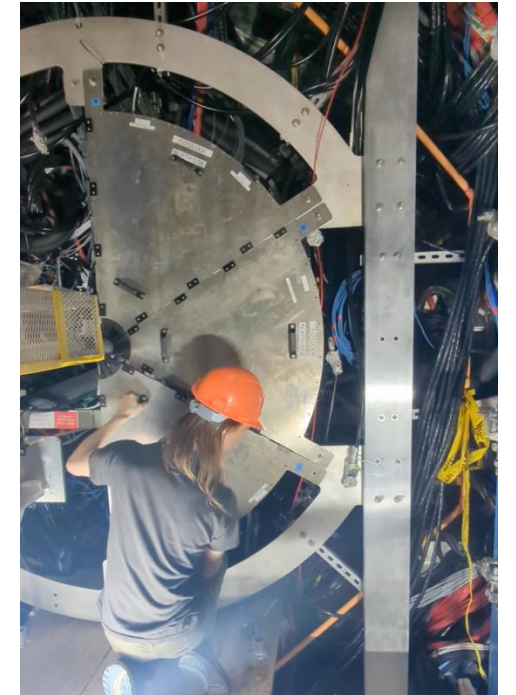
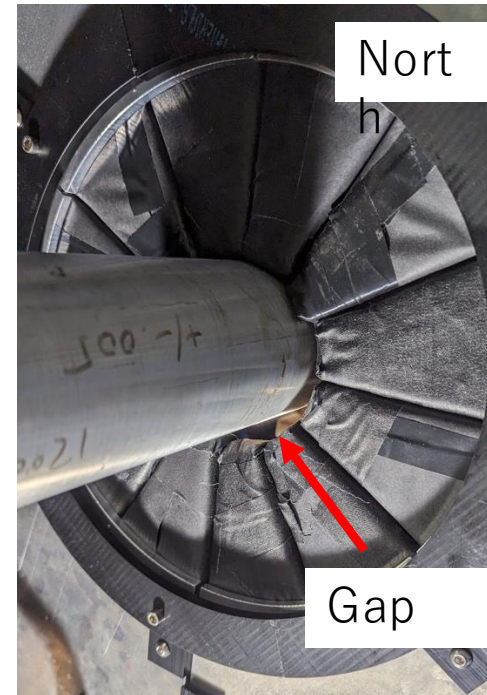


sEPD Install 2024



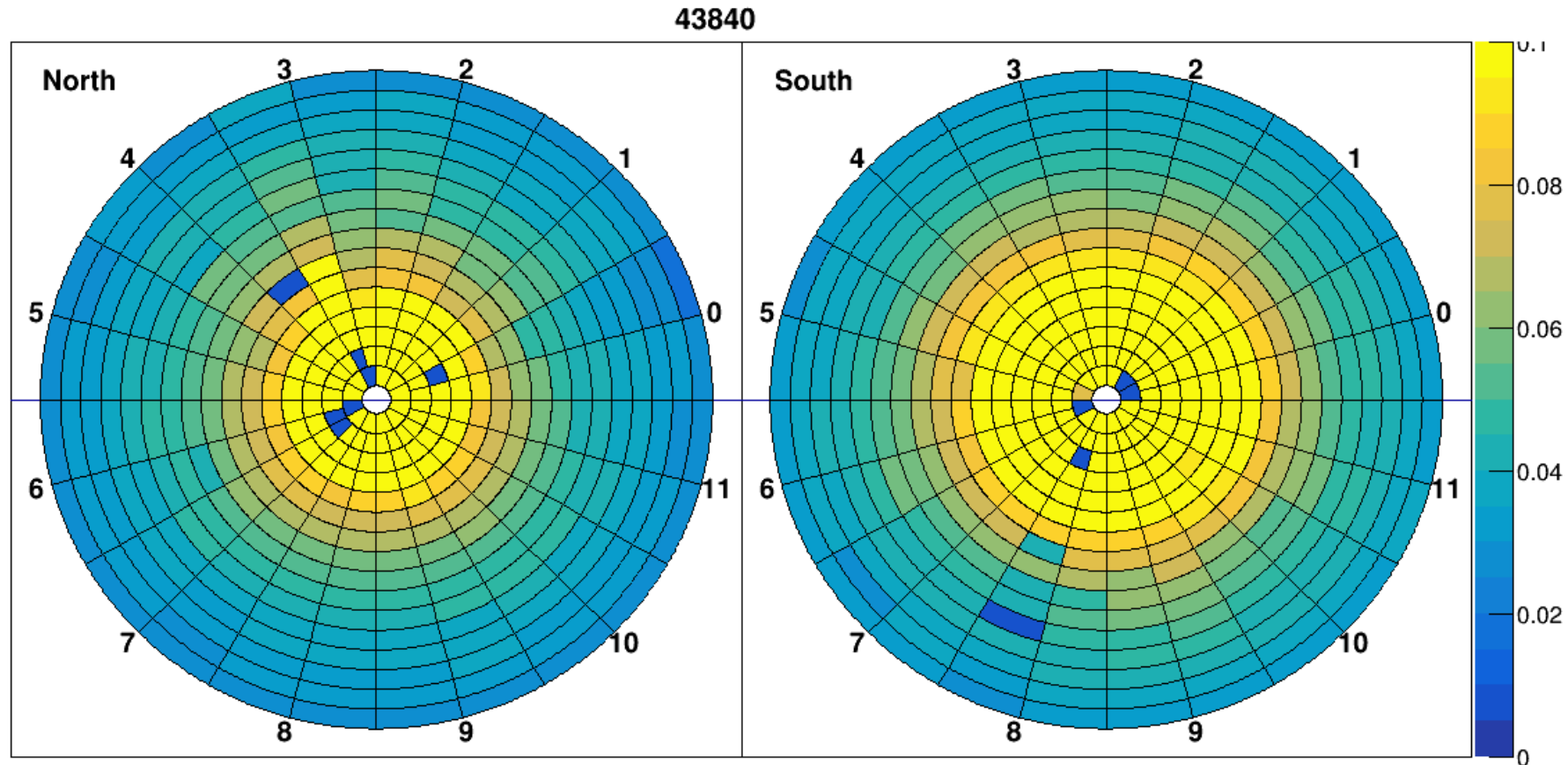
Tristan
Protzman

Ron
Belmont



- South installed during an earthquake
- North installed during an eclipse

First data



Number of “hits”
per tile divided by #
of collisions in the
run

Further calibration
and data processing
in progress

Event plane
resolution matches
simulation!

Minimum Bias Detector (MBD)

Charged Particle Detector

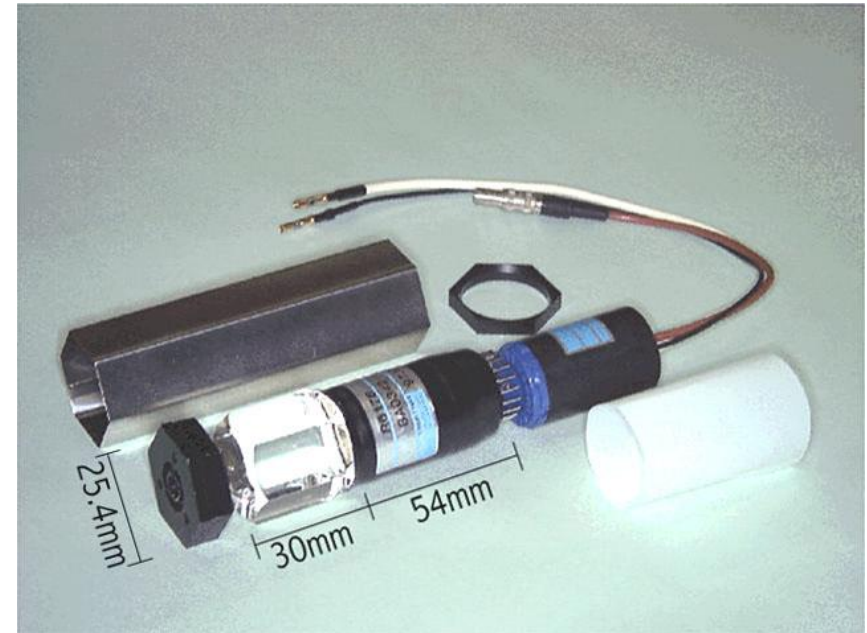
Minimum Bias Detector



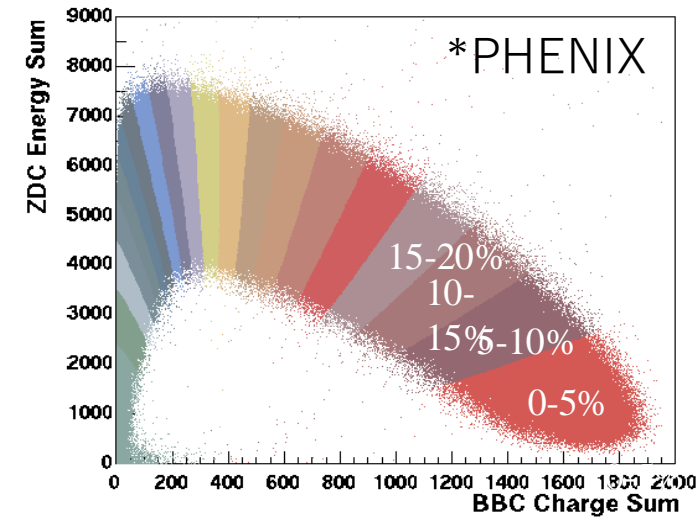
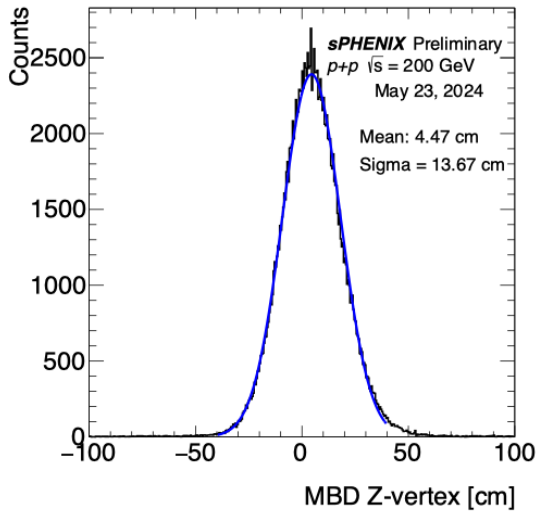
Rapidity Coverage [3.51 < $|\eta$ < 4.61]

- Reuse of the PHENIX Beam-Beam Counter
- 128 channels of 3 cm thick quartz radiator on mesh dynode PMT
- 120 ps timing resolution

- Each element is assembled by Quartz Cherenkov radiator ($\beta_{th} = .7$) and meshed dynode PMT.



Role of MBD



Collision Vertex

initial point of charged particle tracking

Centrality

Determination

Impact Parameter
Determination with ZDC

Minimum Bias

Trigger

Level1 Trigger with
Online Vertex Cut

Time-Zero

Determination

Start Timing for ToF
Measurements

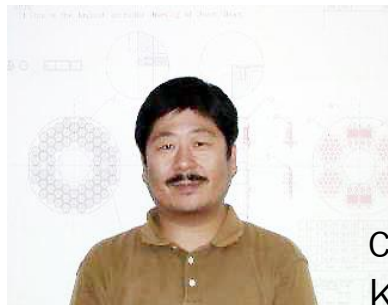
Reaction Plane

Determination

Direction of Impact
Parameter

BBC Guys

DC : Toru Sugitate



contact person
Kensuke Homma



Tomoaki Nakamura

Takashi Hachiya



Kenta Shigaki

Yuji
Tsuchimoto

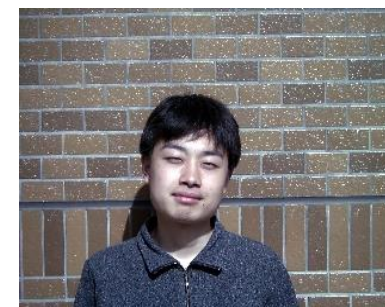
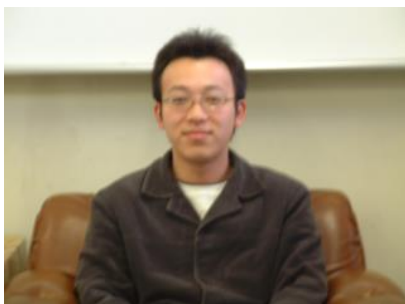


Kota Haruna

Hiroyuki Harada



Akitomo Enokizono
enoki@hepl.hiroshima-u.ac.jp

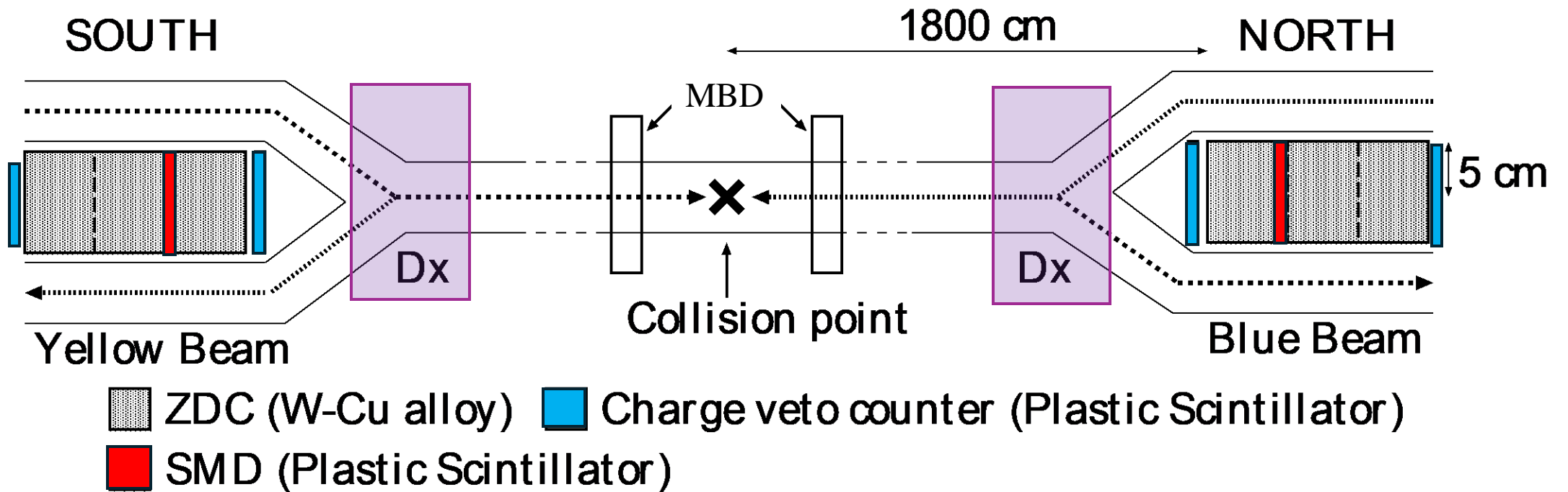


Ryota Kohara

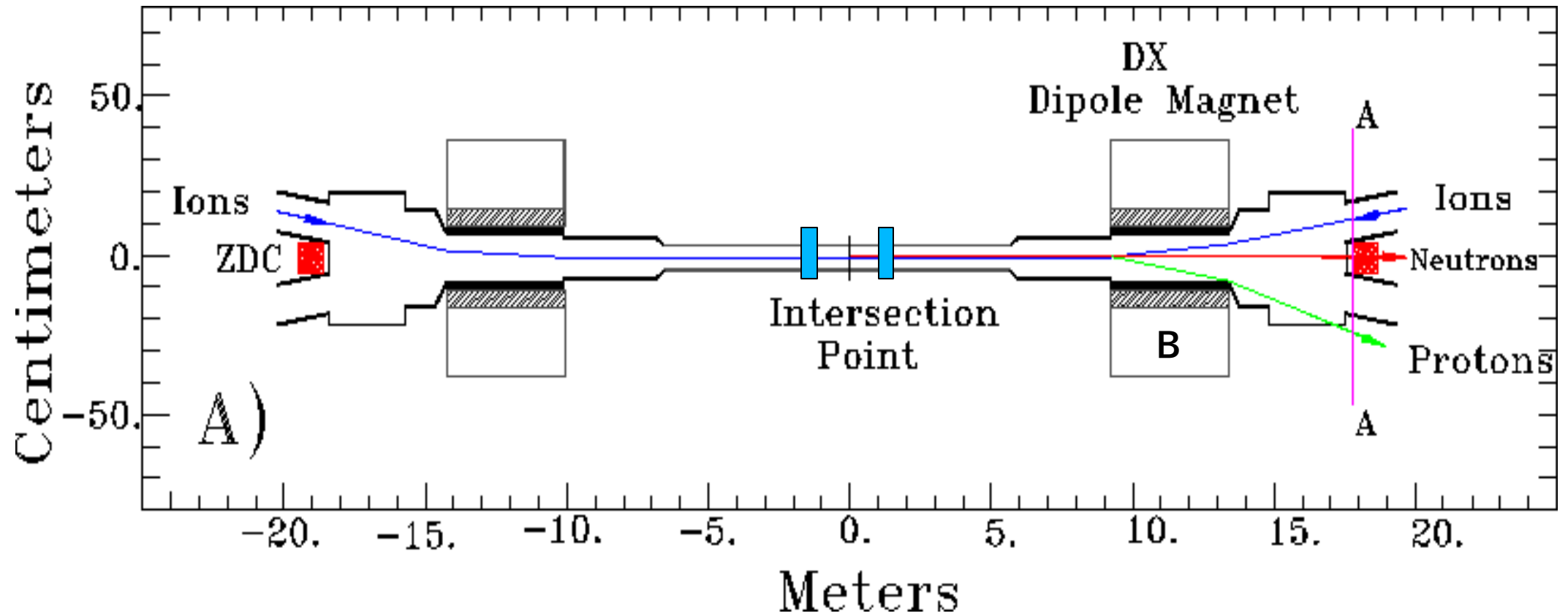
Zero Degree Calorimeter (ZDC)

Neutron Detector

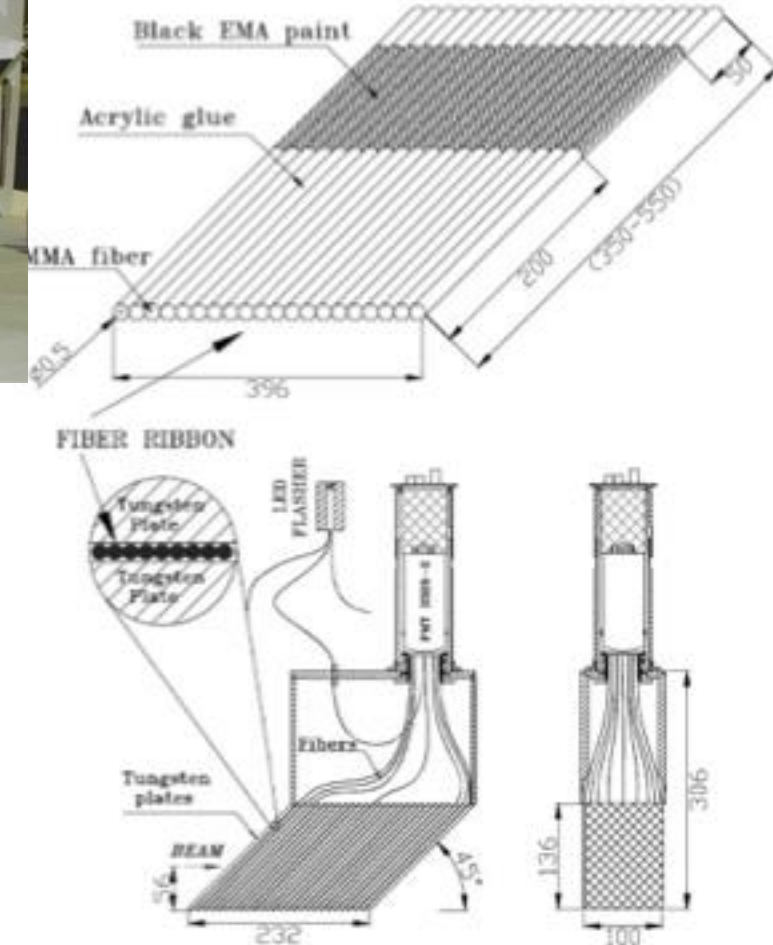
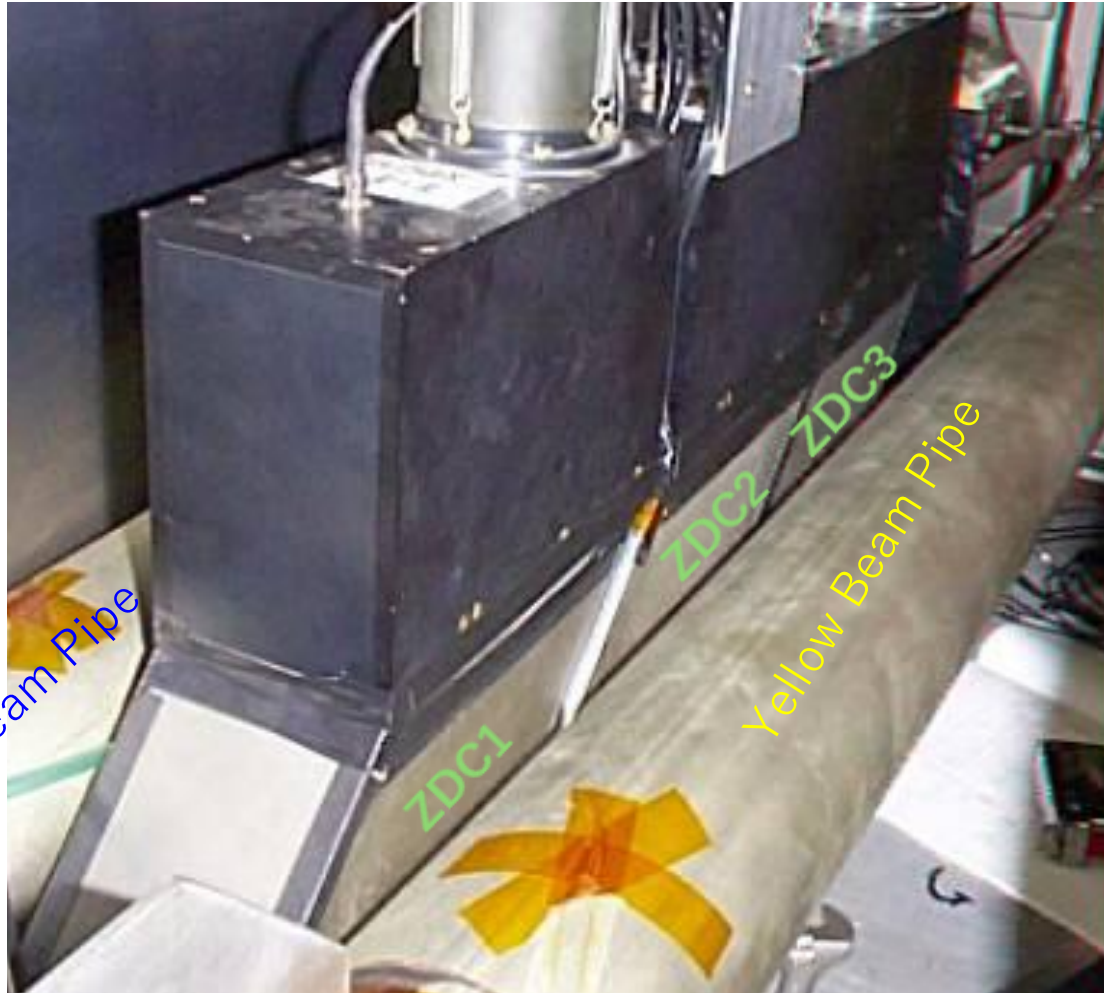
ZDC Location



ZDC as Neutron Detector



ZDC Compartments

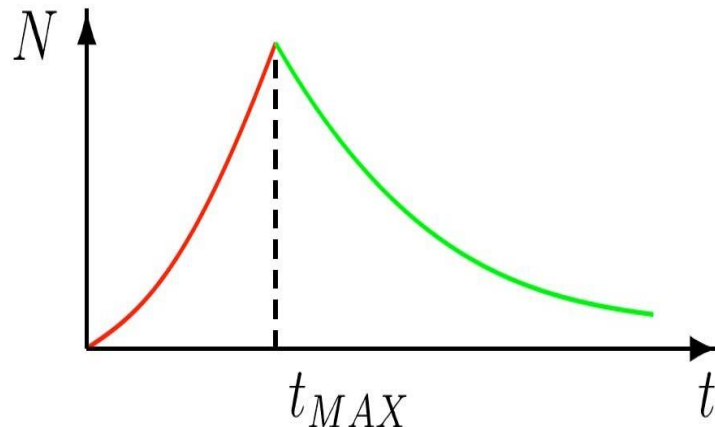
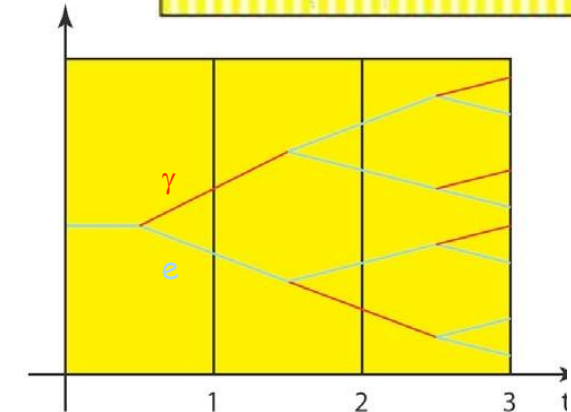
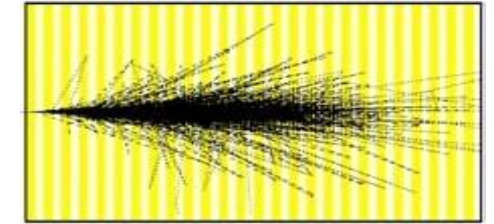


Shower Max Detector (SMD)

■ Electromagnetic shower development

□ Simple qualitative model for shower development (Heitler)

- Consider only: bremsstrahlung and pair production
- Each electron with $E > E_c$ travels $1X_0$ and then gives up half of its energy to a bremsstrahlung photon
- Each photon with $E > E_c$ travel $1X_0$ and then undergoes pair production with each created particle receiving half of the energy of the photon
- Electrons with $E < E_c$ cease to radiate and lose remaining energy through ionization
- Neglect ionization losses for $E > E_c$



Total number of particles after $t X_0$:

$$N(t) = 2^t = e^{t \ln 2}$$

Average energy of shower particle at depth t :

$$E(t) = E_0/2^t = E_0/e^{t \ln 2} \quad t_{max} = \ln(E_0/E_c)/\ln 2 \propto \ln(E_0)$$

$$E(t) = E_c$$

$$N_{max} = e^{t_{max} \ln 2} = E_0/E_c$$

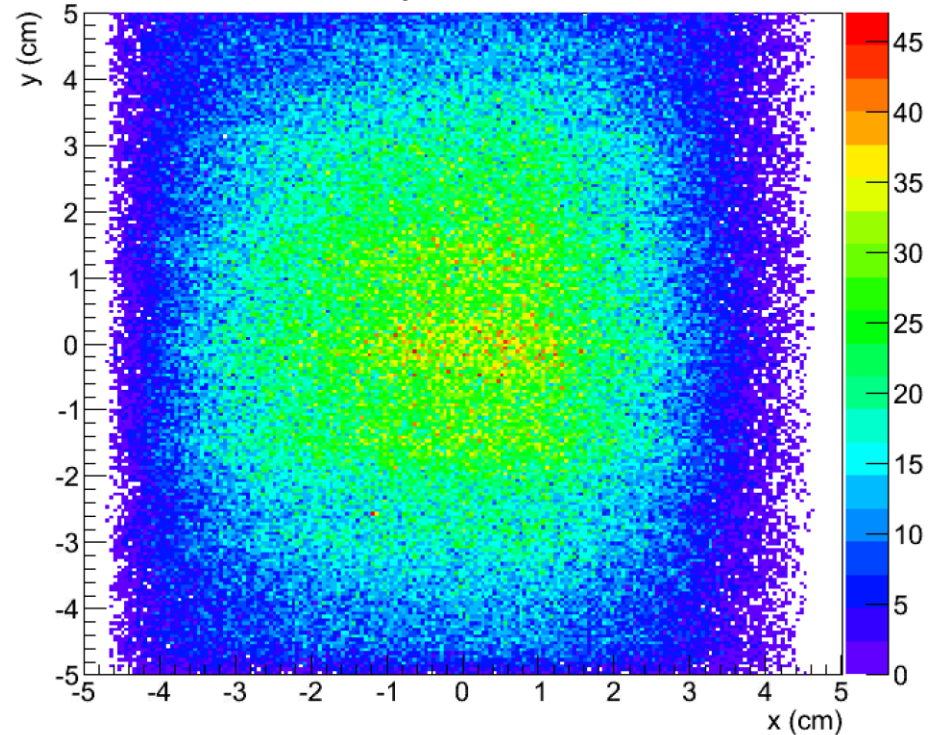
After $t=t_{max}$: ionization, compton effect and photoelectric effect!

Shower Max Detector (SMD)

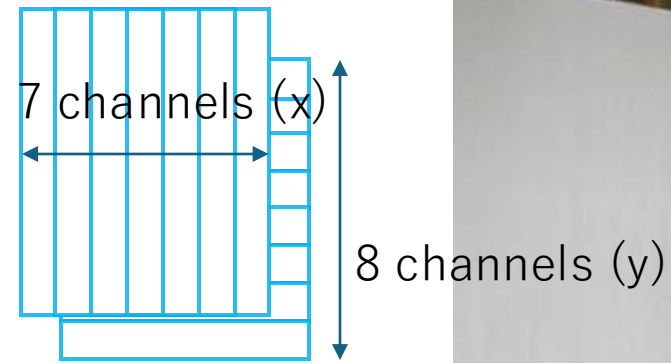
- X-Y plastic strip scintillator hodoscopes
($\Delta x, \Delta y \sim 1$ cm)

- $$x, y = \frac{\sum_i^{SMD} E(i) \times pos(i)}{\sum_i^{SMD} E(i)}$$

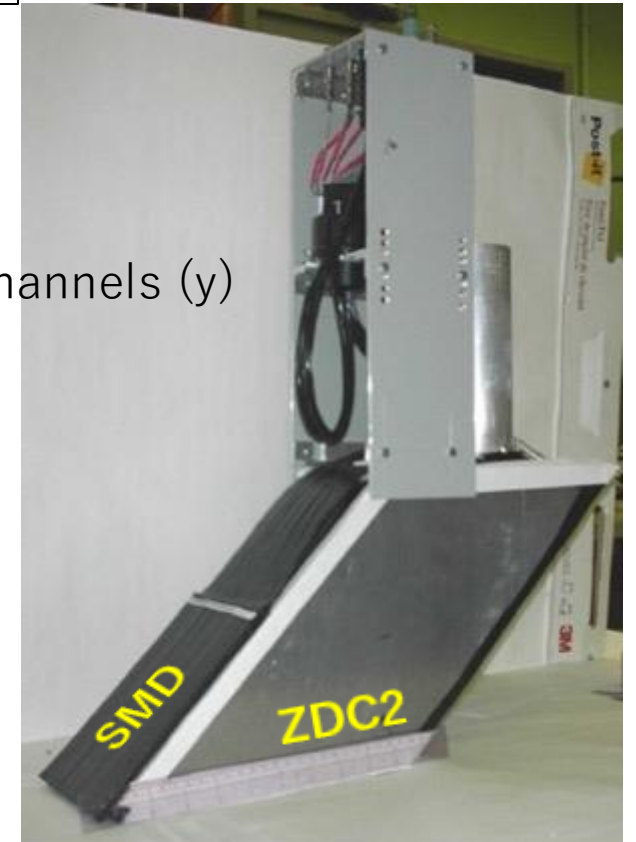
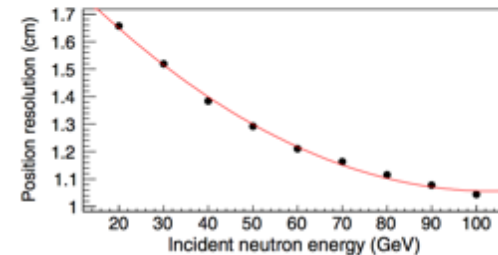
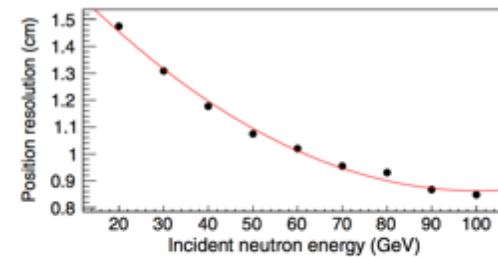
Reconstructed x,y Position of Neutrons



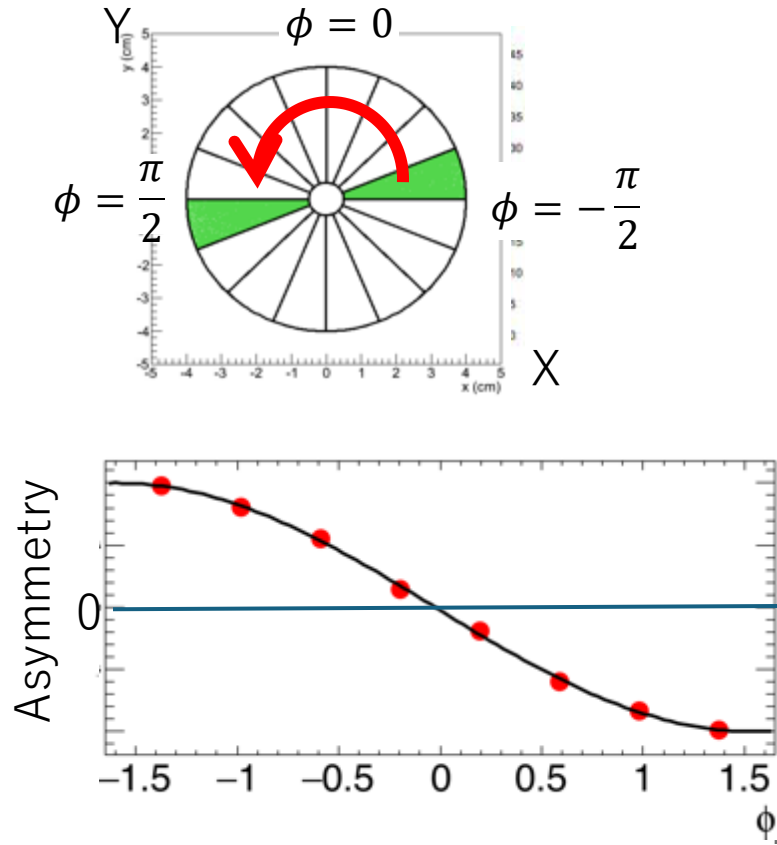
11 cm x 17 cm
Tilted by 45°



SMD Scintillator Paddles



Local Polarimeter



- Raw asymmetry of neutron yields

$$e_N(\phi) \equiv \frac{\sqrt{N_\phi^\uparrow N_{\pi-\phi}^\downarrow} - \sqrt{N_\phi^\downarrow N_{\pi-\phi}^\uparrow}}{\sqrt{N_\phi^\uparrow N_{\pi-\phi}^\downarrow} + \sqrt{N_\phi^\downarrow N_{\pi-\phi}^\uparrow}}$$

- Normalization by polarization P
- Correction C_ϕ

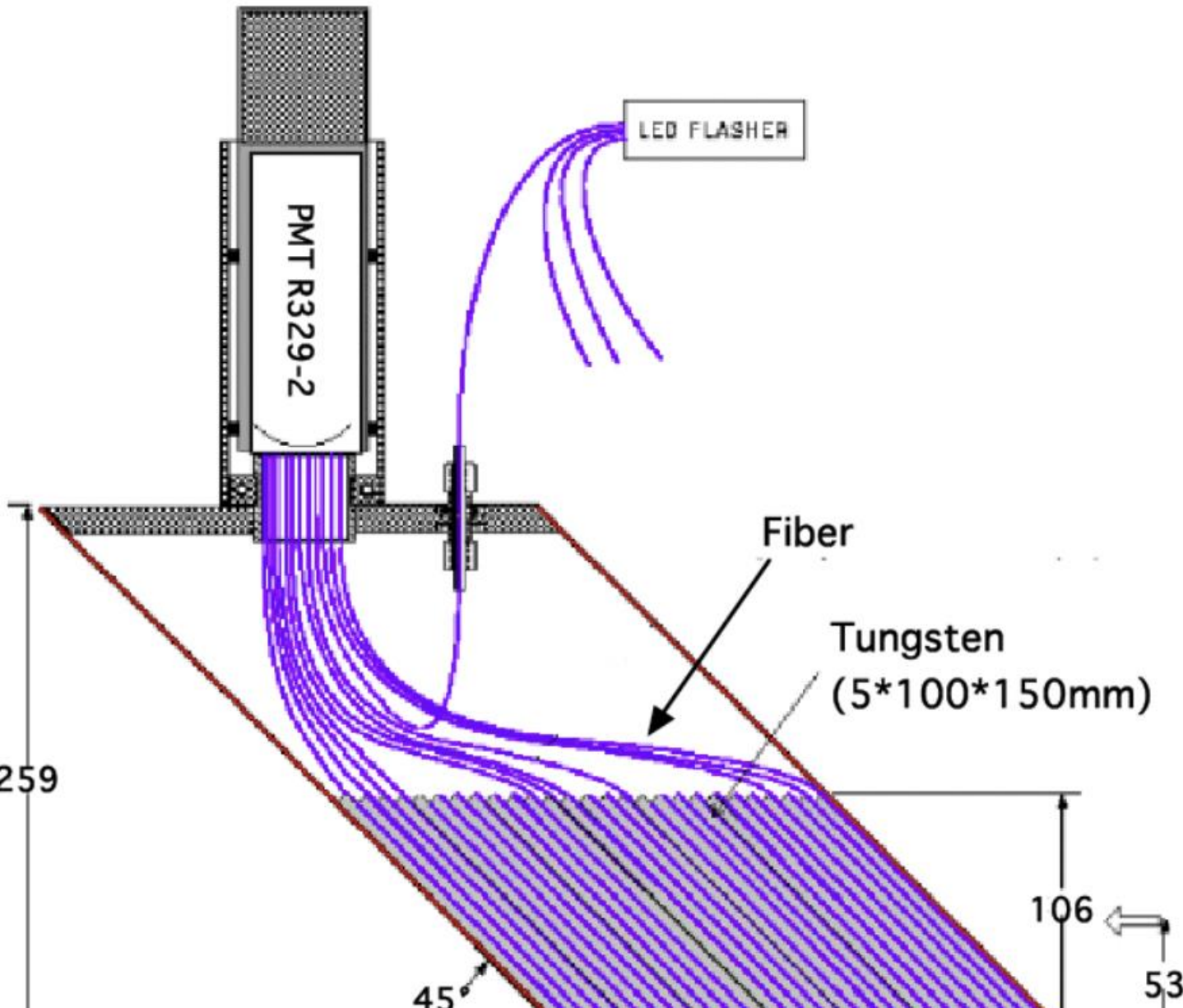
$$A_N = \frac{\sqrt{\sigma_L^\uparrow \sigma_R^\downarrow} - \sqrt{\sigma_L^\downarrow \sigma_R^\uparrow}}{\sqrt{\sigma_L^\uparrow \sigma_R^\downarrow} + \sqrt{\sigma_L^\downarrow \sigma_R^\uparrow}}$$

$$A_N = \frac{e_N(\phi)}{\sin(\phi - \phi_0)} \frac{1}{C_\phi} \frac{1}{P}$$

Local
Polarimeter

RHIC
polarimeters
from IP12

ZDC (Zero Degree Calorimeter)



MD (Shower Maximum Detect)

